

Test Status of VMM3

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Acknowledgment

Nachman Lupu, Alex Vdovin (Technion, Israel) - Brigitte Vachon, Benoit Lefebvre (MgGill, Canada)

Lorne Levinson, George Mikenberg, Ilia Ravinovich, Vladimir Smakhtin (Weizmann, Israel)

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Questions

b. VMM readout start-up sequence

So far a **start-up** sequence (CKBC & TKI low before one CKTP before being enabled again) is necessary to get data from the VMM3. The VMM designers must confirm whether such a start-up sequence is necessary in the expected running mode on the NSW, fully document it and verify by simulation that it works under all conditions. It would be very good to have a test done with the ROC FPGA emulator.

c. SFM issue

It seems that this issue can be reliably solved by adding a bias resistor at the VMM input. However, it would be good to understand how the **resistor** is to be selected for instance by showing the charge and rate limits for a given resistor value. Gianluigi shall define how this can be quantified (e.g. looking at the deadtime introduced as a function of charge and rate) and make the related simulations.

d. SREC issue

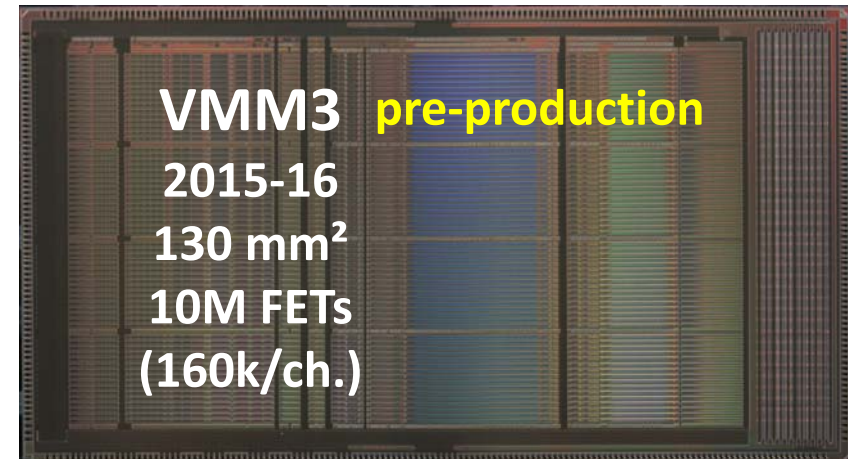
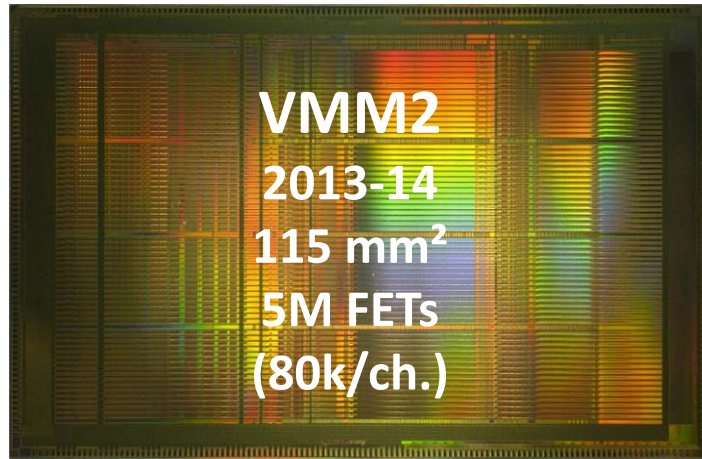
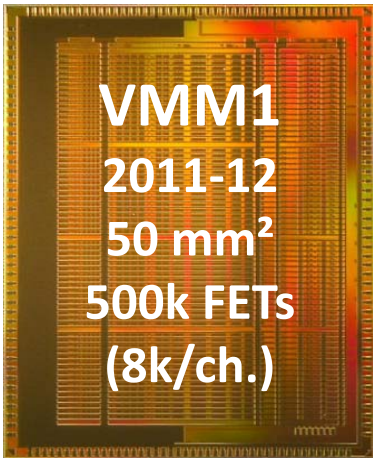
The possibility of running safely the sTGC with the **SREC** disabled is still to be proven. A plot of dead-time versus charge when the SREC is not enabled must be presented. In case the SREC is enabled, a **pi-network** is recommended at the input of the VMM and preliminary measurements with an sTGC indicate it is efficient but may not be necessary for the strips and the pads (a single resistor might work). As for the SFM, simulations should be done showing which are the charge and rate limits for a given network. Additional tests with the small sTGC must be presented. If possible, tests with the large chamber should also be presented (this might be difficult as the chamber is expected mid-April).

g. Other issues

It has been shown that one can leave with the degraded performances of the **ADCs (yield*)**, the acquisition reset issue and the locking in ToT mode ... **baseline (yield*)** issue.

***new**

VMM Development Progress



- mixed-signal
- 2-phase readout
- peak and timing
- neighboring
- sub-hysteresis
- few timing outputs

- mixed signal
- continuous fully-digital readout
- current-output peak detector
- increased range of gains
- three clock-less ADCs per channel
- FIFOs, serialized data with DDR
- serialized ART with DDR
- additional timing modes
- 64 timing outputs
- ITAR
- additional functions and fixes

- **mixed signal + digital**
- **continuous simultaneous readout**
- **SEU-tolerant logic**
- **deeply revised front-end for TGC**
(2nF, 50pC, fast recovery, ...)
- **L0 handling digital core**
- **SLVS and new config. interface**
- **new reset control and fast reset**
- **timing at threshold**
- **timing ramp optimization**
- **pulsar range extension**
- **ART synchronization**
- **32-channel skip**
- **additional functions and fixes**

VMM3 is “de facto” a first prototype

VMM3 Issues

Issue	Circuit	Notes
Need start-up sequence	channel logic	workaround
Handle sTGC charge & rate	analog front-end	workaround
Locking in ToT	channel logic	workaround
ENA acquisition reset	control logic	workaround
Trimming range extension	channel trimmer amplifier	3/4 of targeted
High baseline	shaper	workaround - yield 25ns*
ADC accumulation	ADCs	improvements - yield MSB*

*new

Summary of Startup Sequence Issue

- **Issue** - Specific one-time sequence of control signals is required at power-on
- **Origin** - Register in the acquisition logic of the channel doesn't get reset at power-on
- **Workaround** - Enable-disable auto-reset function (bit STCR)
- **Fix** - Add reset logic to register

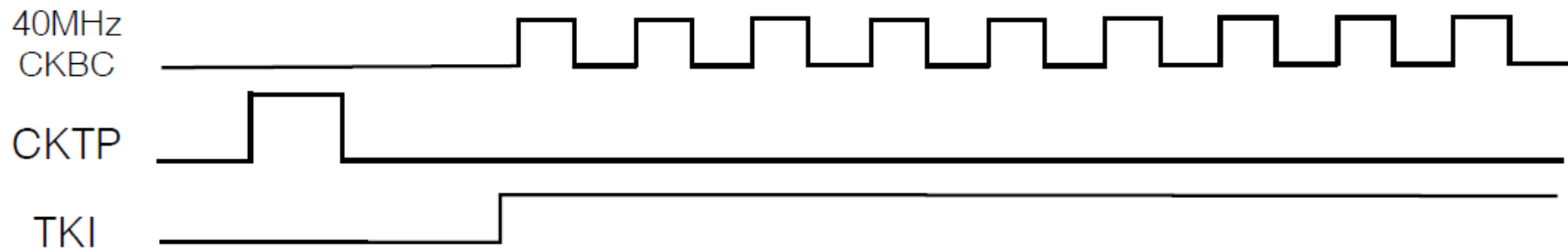
Startup Sequence Issue



VMM Readout

2

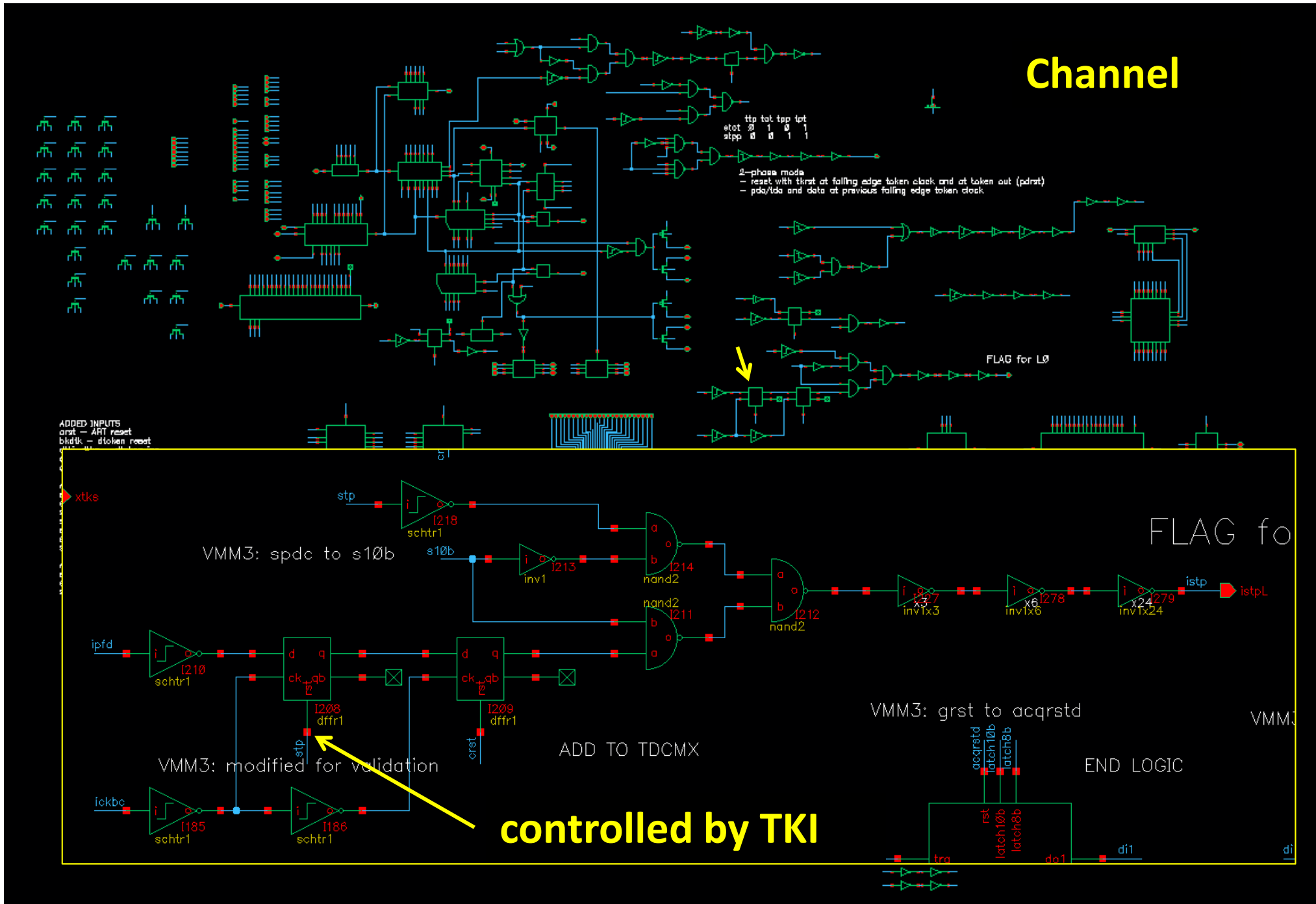
- As of today I am not aware of anybody who have readout the VMM3 without a startup sequence we found initially.
- CKBC, TKI should be low, one CKTP and afterwards we enable them again



- If the above is not followed no data are seen in the data0/1 lines
- Possible functionality comes from the reset of two monostables relevant to the global reset from the CKTP.
- If we keep the VMM3 this functionality should be foreseen in the readout/configuration logic.
- L0 readout functionality should be checked if shows the same behaviour.

This is an ongoing investigation and should be understood if it is compatible with the NSW readout.

Startup Sequence Issue

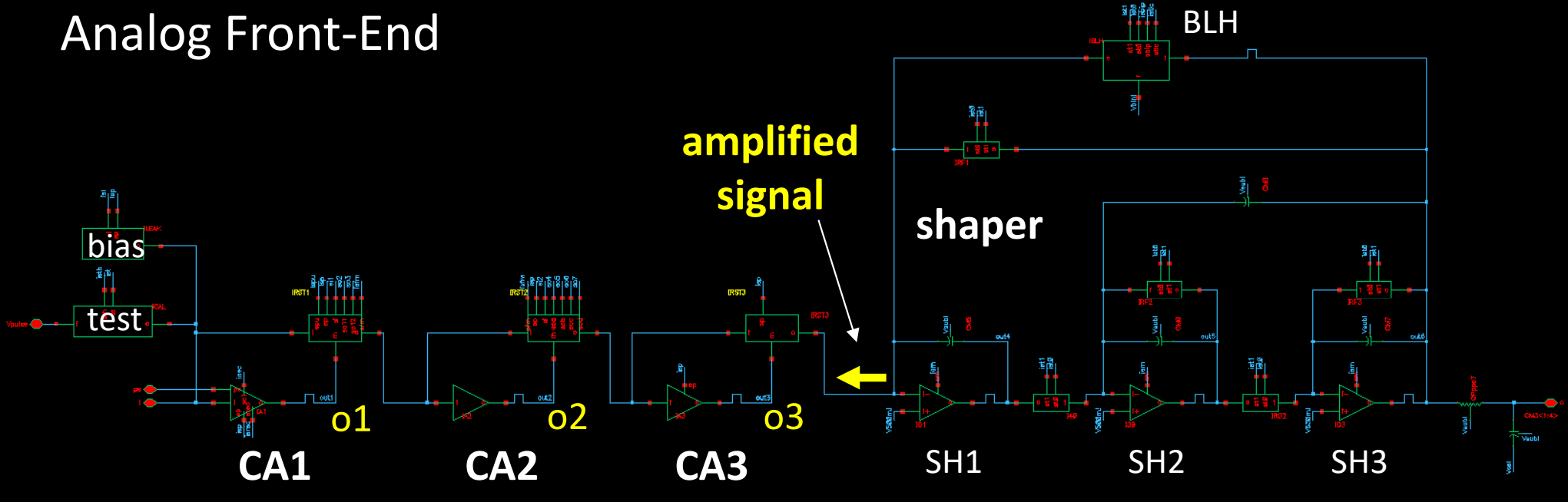


Summary of SFM Issue - Part 1

- **Issue** - In SFM mode, internal operating points can become undefined
- **Origin** - In charge amplification chain, mismatch between SFM currents affects bias current of next stage
- **Workaround** - External bias resistor
- **Fix** - Increase value of bias current in SFM mode

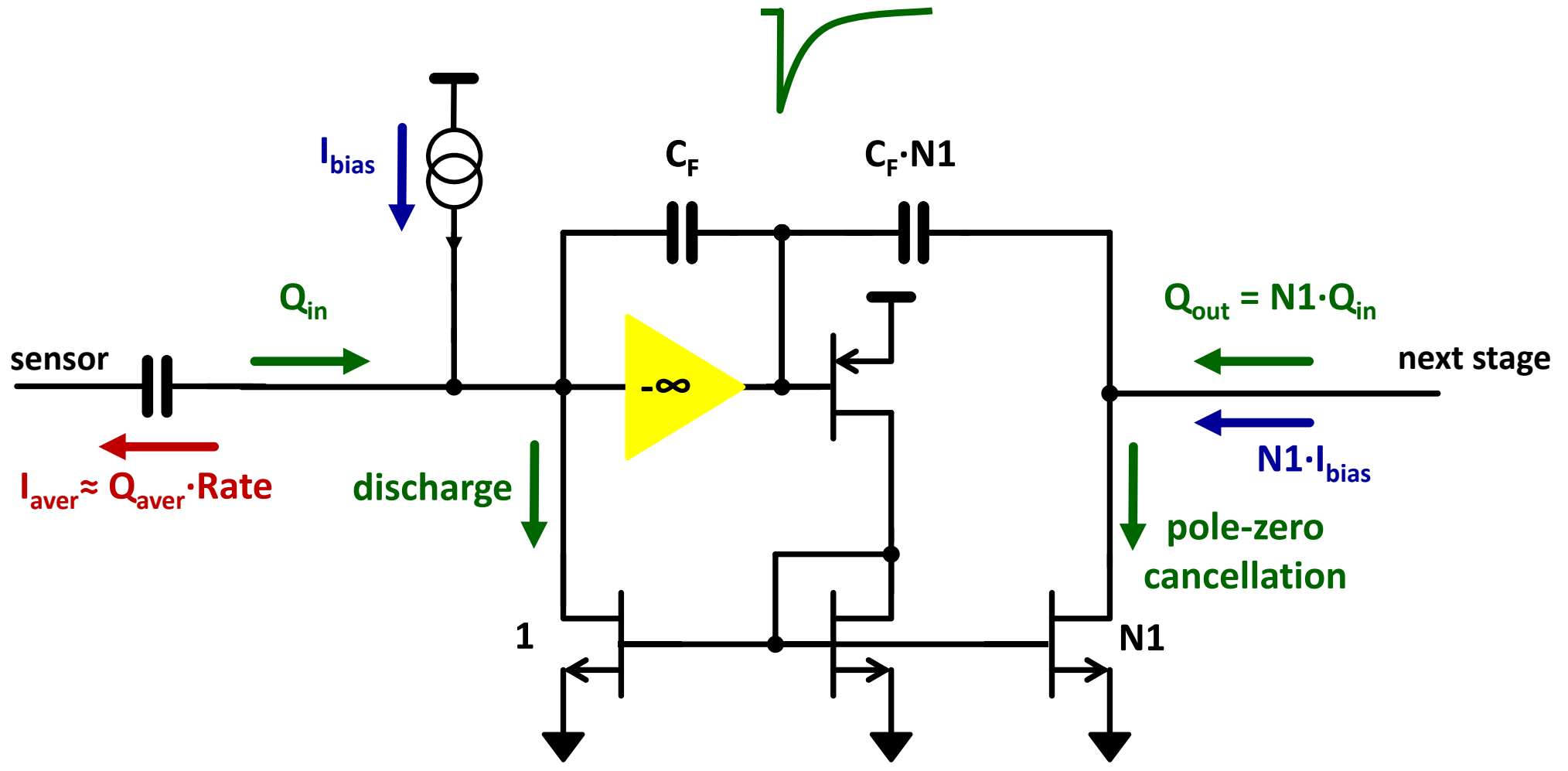
Charge Amplification in VMM3

Analog Front-End



- **CA1** and **CA2** are charge amplification stages with programmable gain
- **CA3** is a charge inversion stage (enabled for positive charge, bypassed for negative charge) to keep same signal polarity at input of shaper

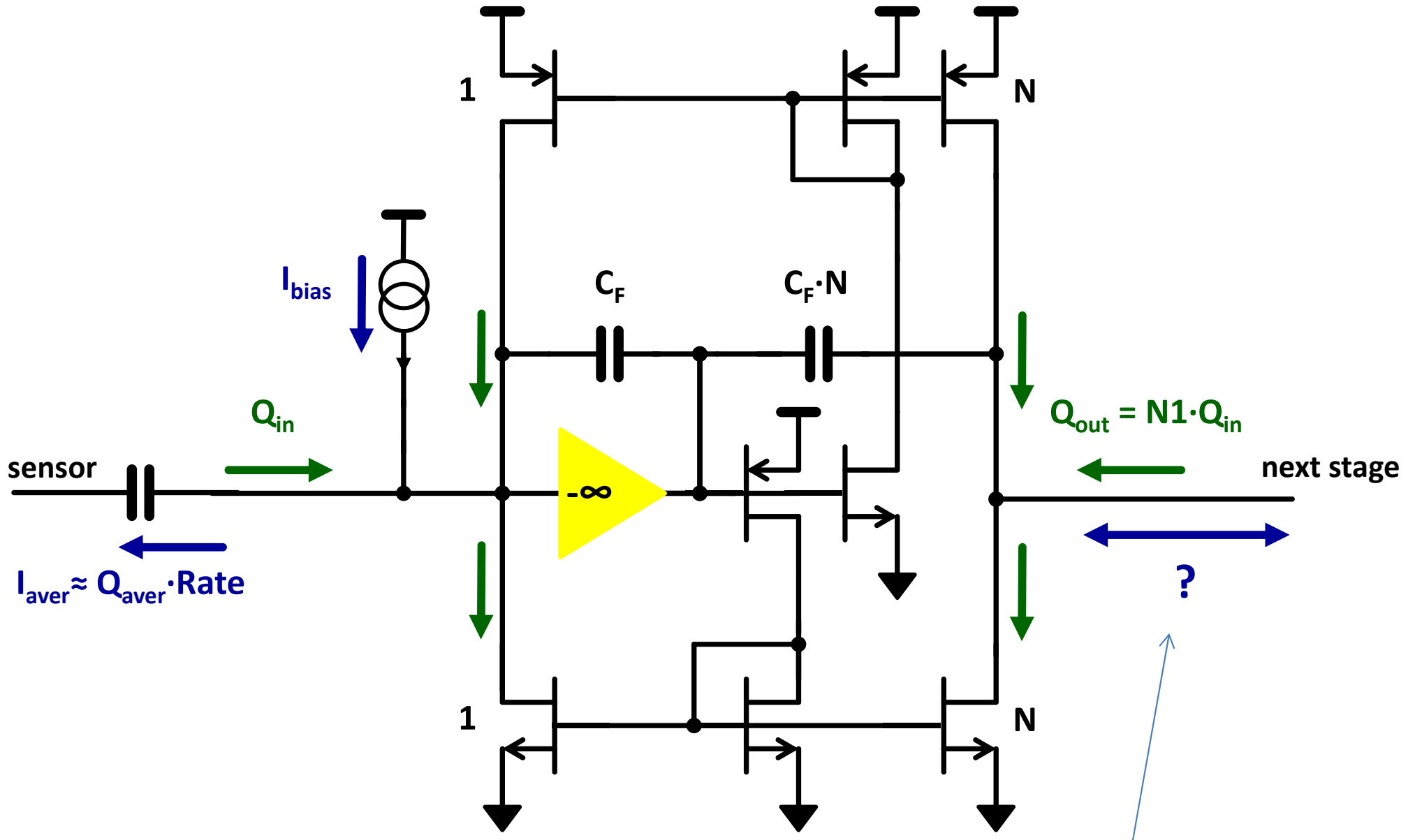
AC Coupling



$I_{aver} > I_{bias} \rightarrow$ amplifier shuts down \rightarrow dead time

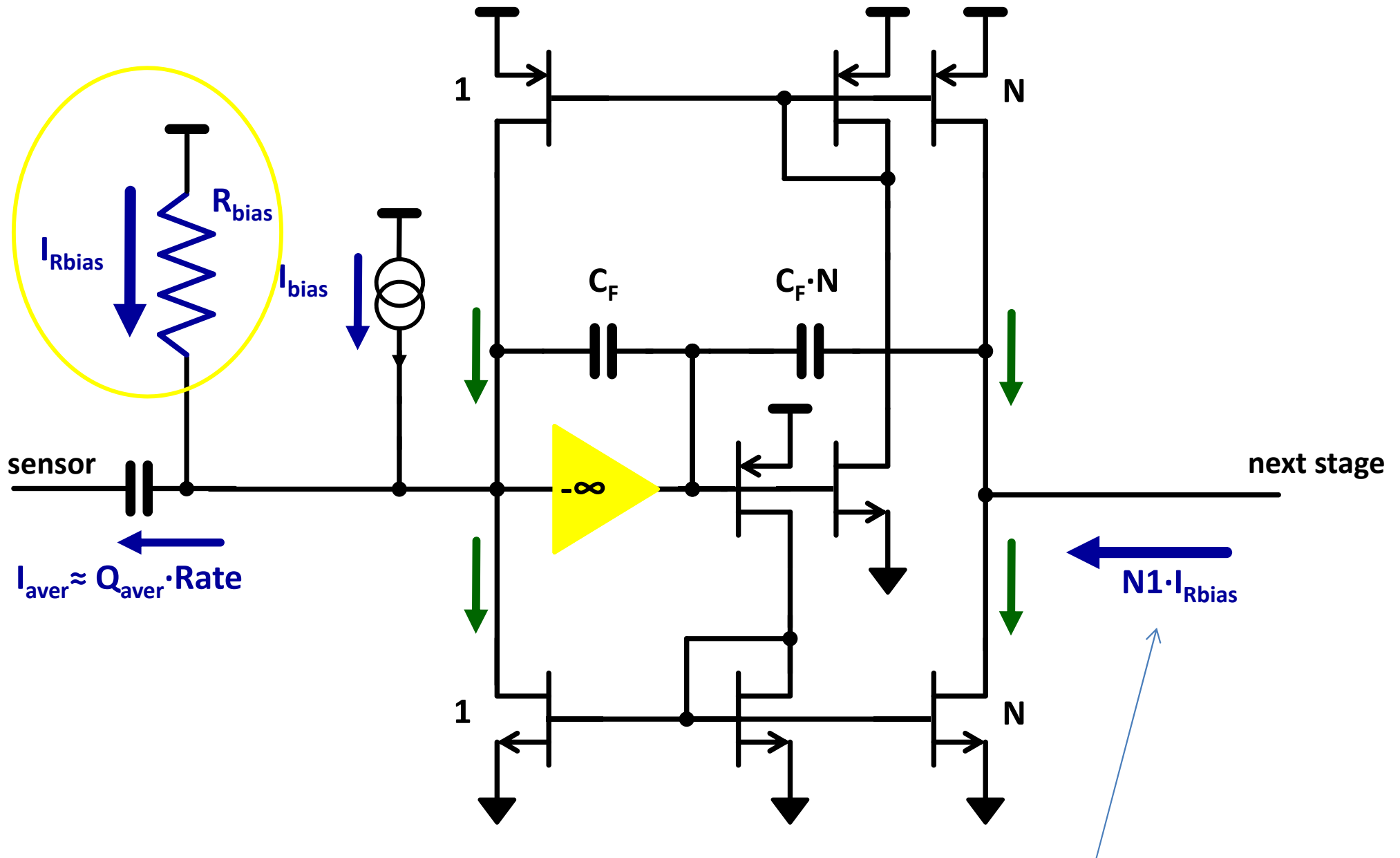
Full-Mirror Circuit* (SFM)

* previously called Dynamic Discharge



**mismatch \rightarrow uncontrolled bias current to next stage
 \rightarrow \sim 40% of the channels shut down**

Workaround for SFM Issue

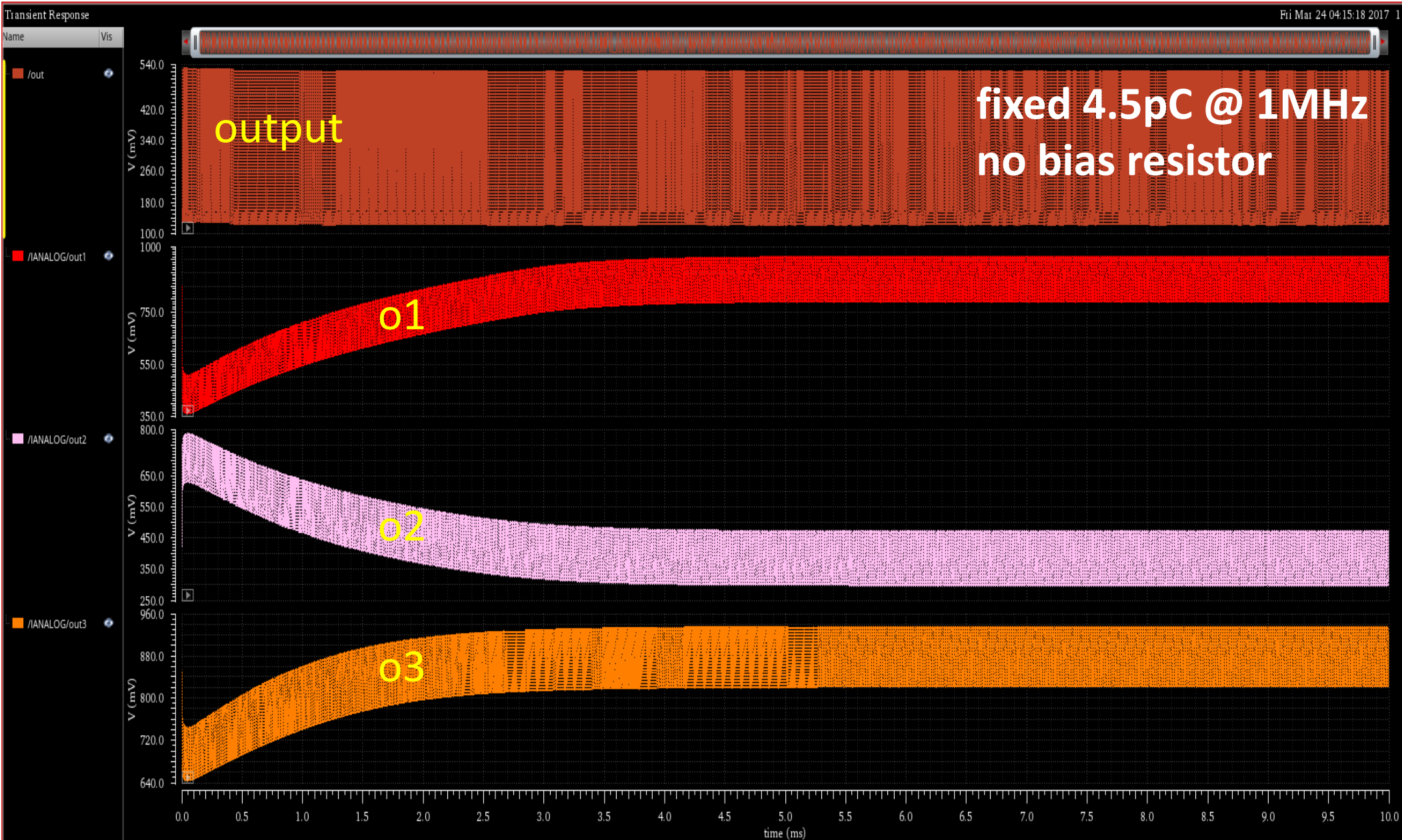


external bias current (few nA) → correct polarity is re-established

Summary of SFM Issue - Part 2

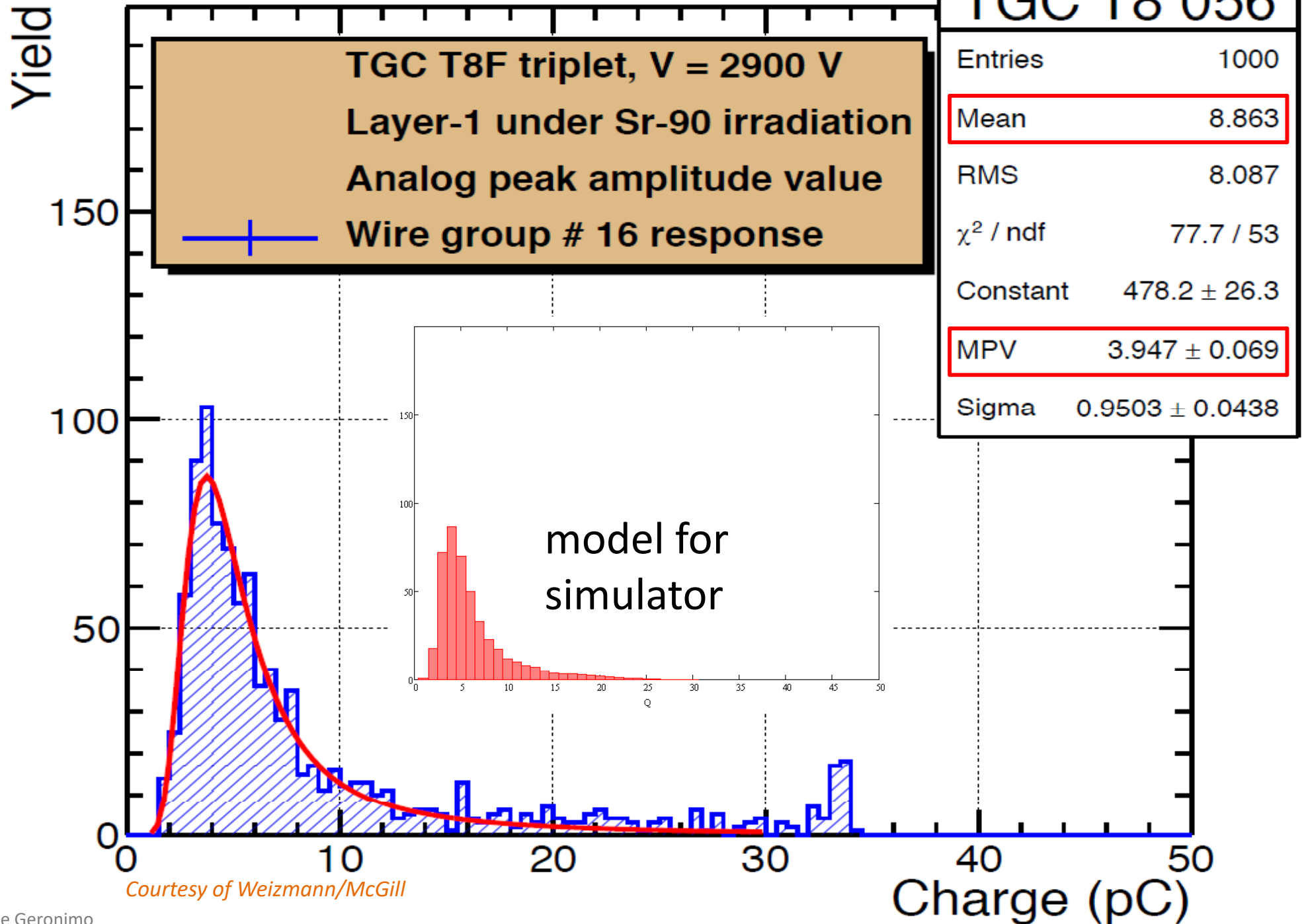
- **Issue** - Given a “good” (in SFM mode) channel, dead time occurs with actual charge distribution
- **Origin** - Non-linearity of active reset combined with charge distribution
- **Workaround** - External bias resistor (same as before)
- **Fix** - Increase value of bias current in SFM mode (same as before)

Pad Simulation 4.5pC @ 1MHz - No Resistor

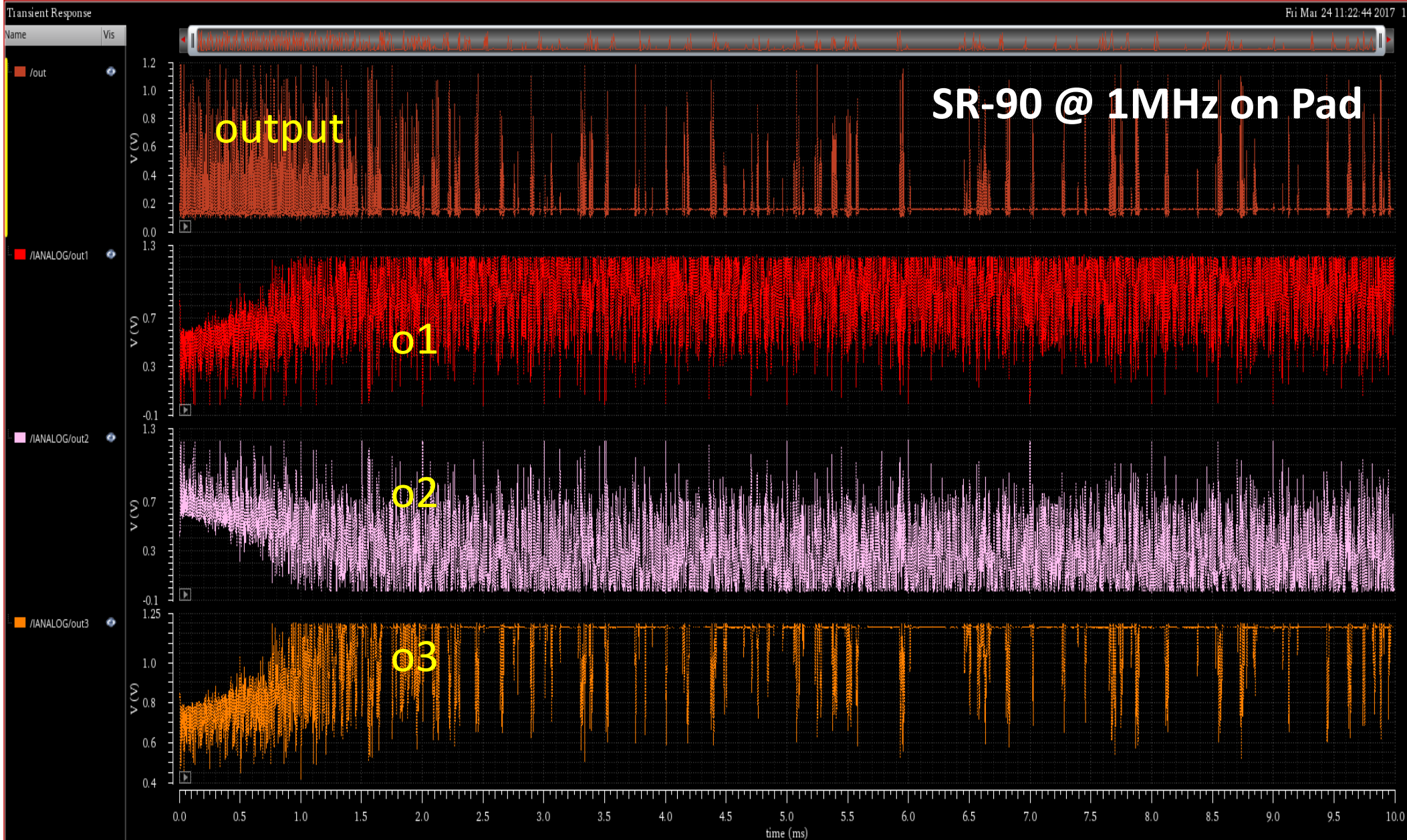


3pC were specified

Strontium-90 Charge Distribution

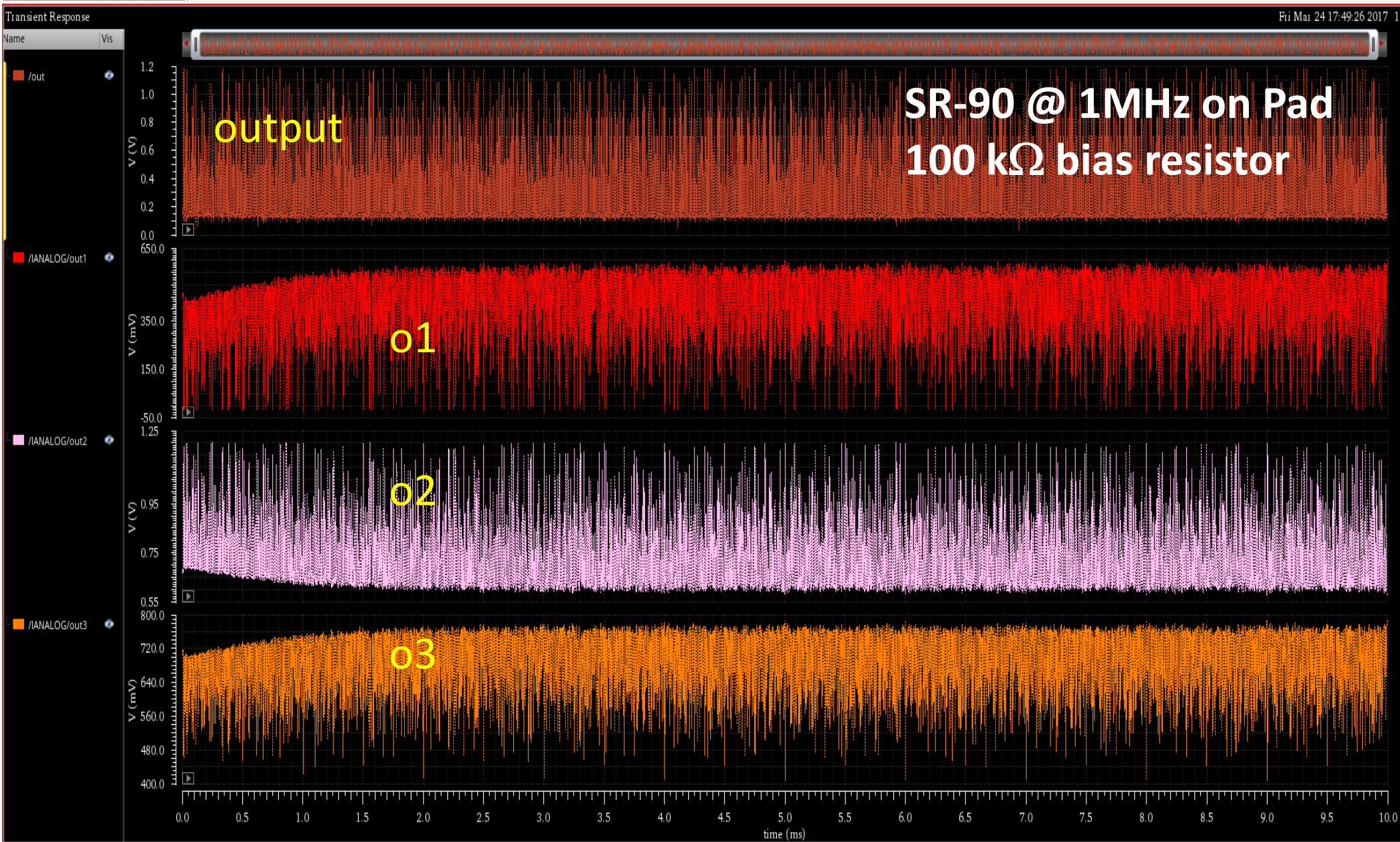


Pad Simulation SR-90 @ 1MHz



Stage 3 fails due to non-linearity of active reset (no SFM)

Pad Simulation SR-90 @ 1MHz - 100kΩ Resistor



$R_{\text{bias}} \approx 100\text{k}\Omega$ adjusts operating points and compensates for I_{aver}

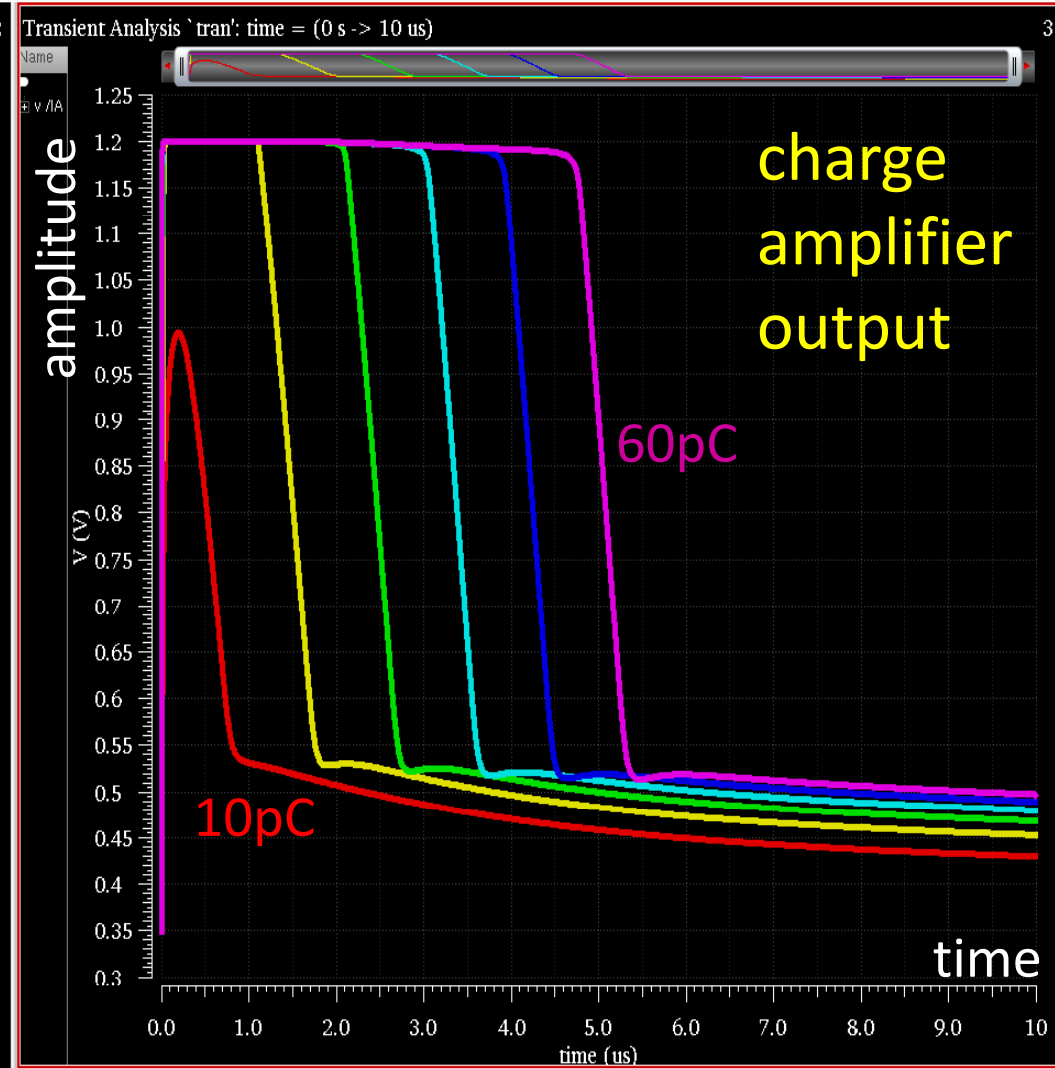
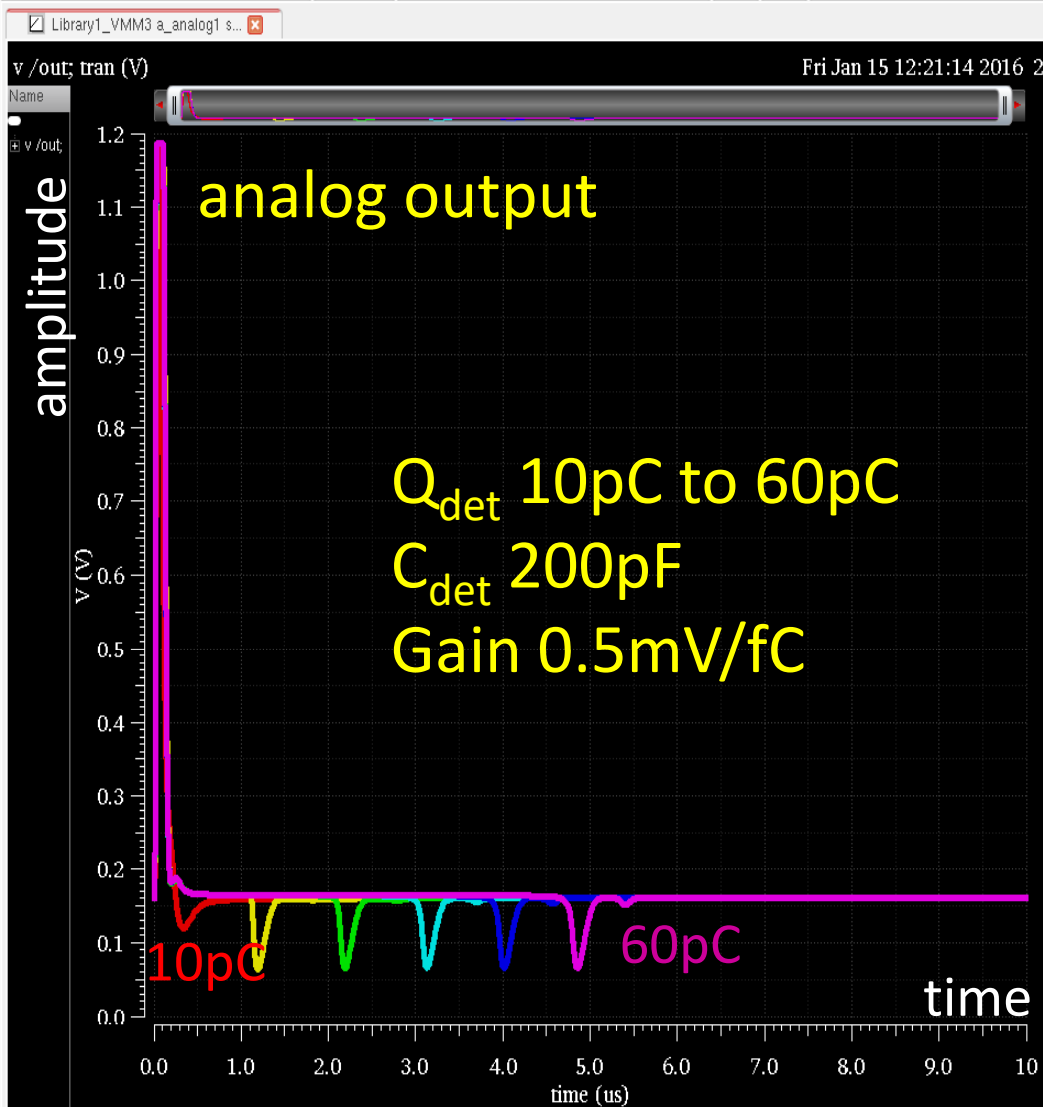
Choice Criteria for Bias Resistor

- When in SFM mode, VMM3 is able to sink or source DC currents up to $10\ \mu\text{A}$, but conservatively $5\ \mu\text{A}$ must be assumed
- As a rule of thumb, the current provided by the bias resistor must have same polarity of the charge with values on the order of the worst-case $\langle Q \rangle \times \text{Rate}$ product, and not exceed $5\ \mu\text{A}$
- Worst-case $\langle Q \rangle \times \text{Rate}$ products higher than $5\ \mu\text{A}$ must be handled with the attenuation network (π -network) as discussed later, to limit the effective average current within $5\ \mu\text{A}$
- Note1: the DC voltage of the VMM3 inputs is on the order of 300mV. In positive mode, the resistor should be placed between VDDP and input. In negative mode between input and AGND. Both VDDP and AGND nodes are available at the protection diodes.
- Note 2: $100\ \text{k}\Omega$ noise contribution $\approx 880\ \text{e}^- \text{ rms}$ ($\approx 0.13\ \text{fC}$)

Summary of SREC Issue

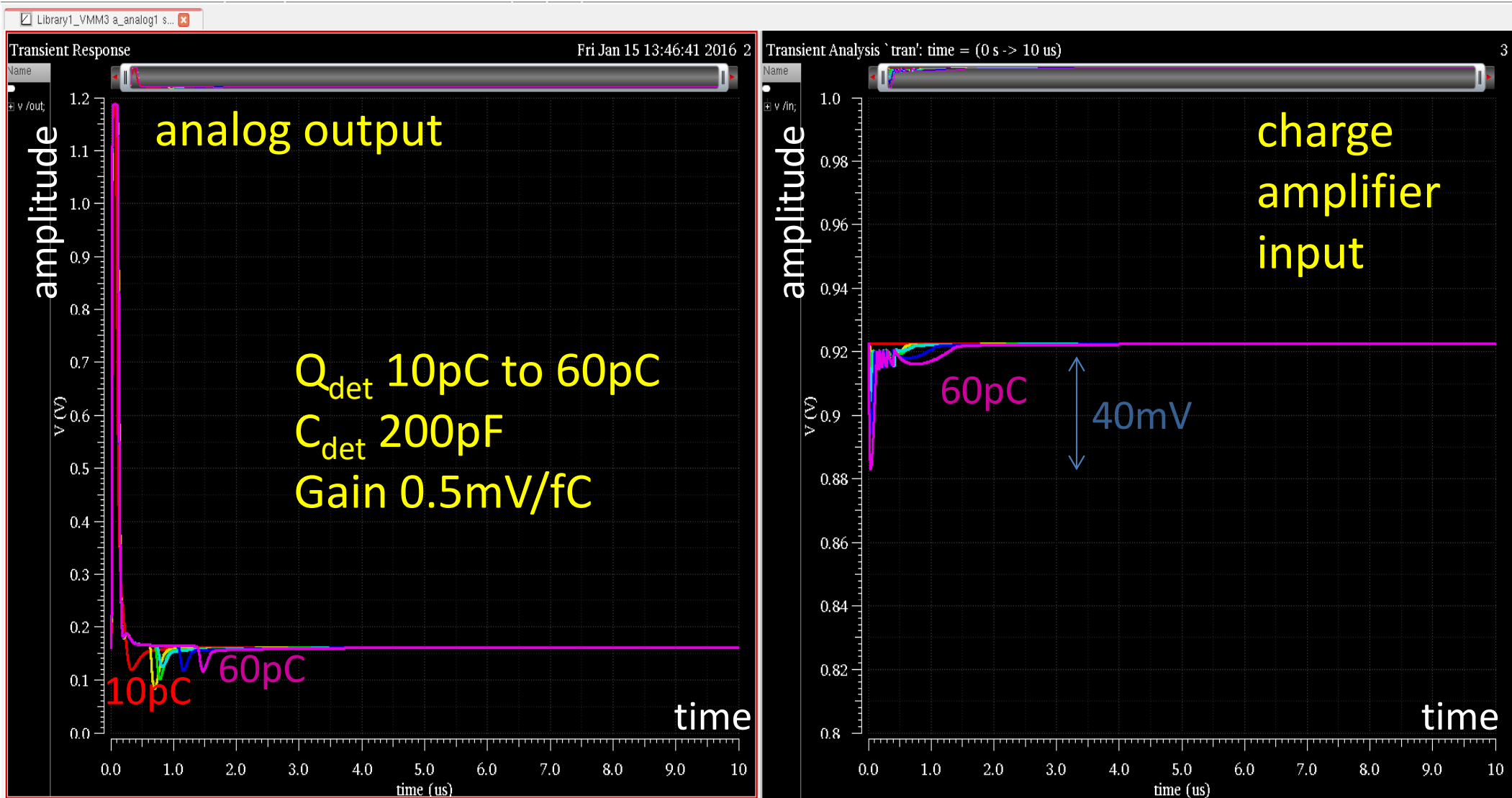
- **Issue** - The fast-recovery circuit, engaged at very-high-charge, may cause multiple threshold crossings
- **Origin** - Parasitics
- **Workaround** - Disable SREC or reduce number of very-high-charge events
- **Fix** - To be investigated (ASIC, package, PCB)

Response Without SREC



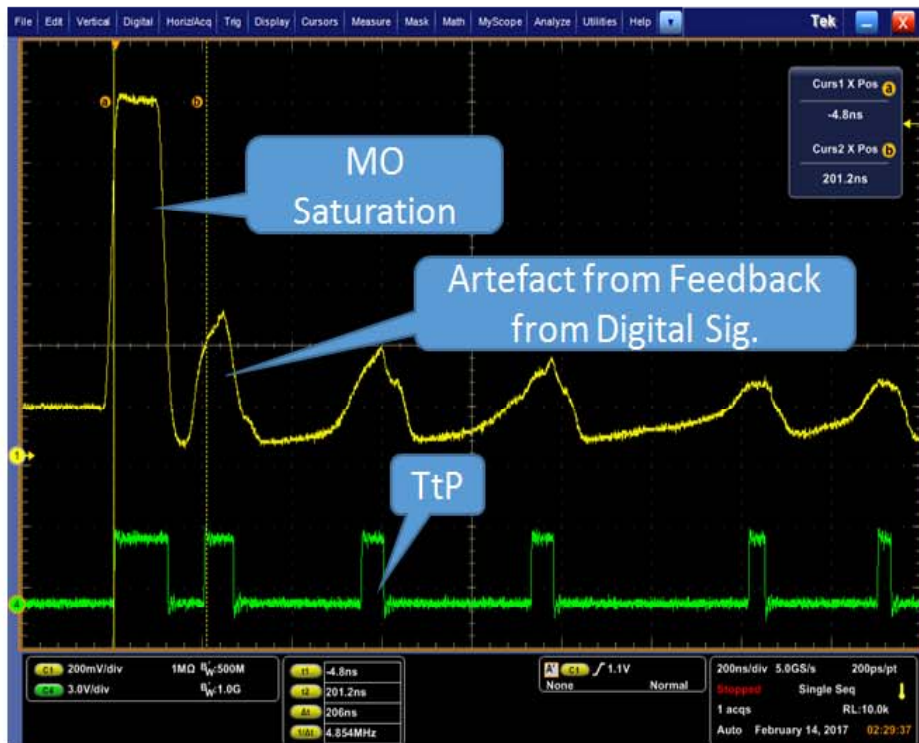
- Saturation of the charge amplifier extends to $2\mu\text{s}$ at 20pC and $6\mu\text{s}$ at 60pC
- Similar behavior is obtained for positive charges

Response with SREC

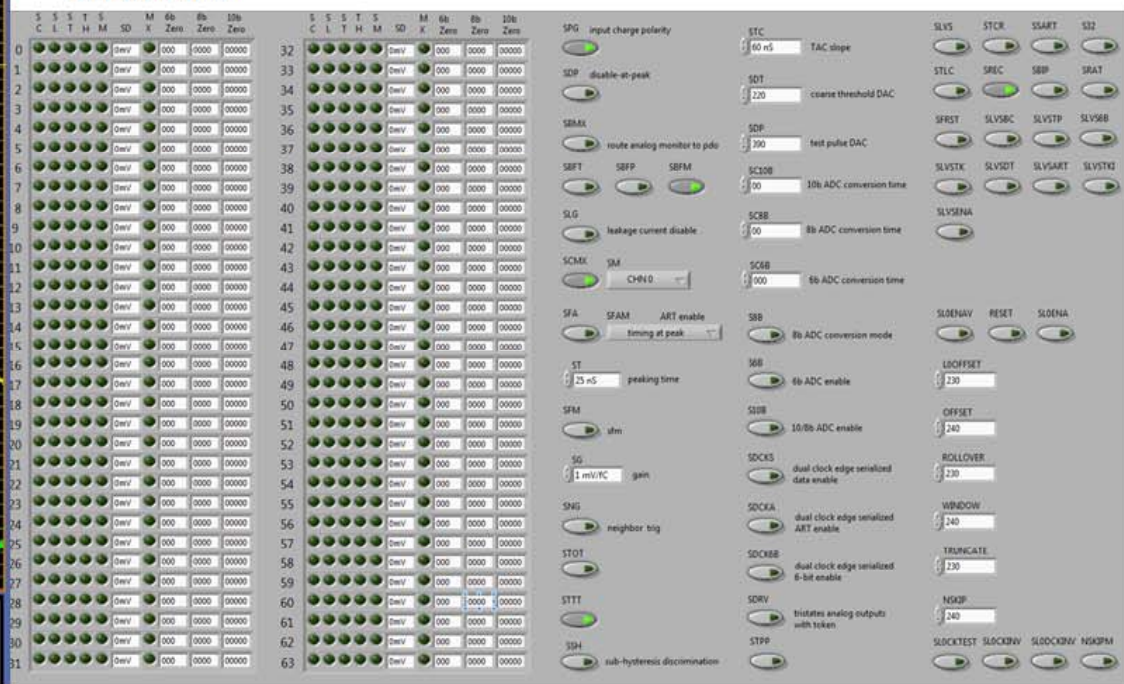


- With the fast recovery circuit enabled, the saturation of the charge amplifier is reduced to $1.2\mu\text{s}$ at 20pC and $2\mu\text{s}$ at 60pC
- Similar behavior is obtained for positive charges

Measurement with SREC



Channel 0



Recovery from Saturation Response 205 ns.

Low Discrimination Level 220 .

3/24/2017

N.Lupu, A.Vdovin, R.Abramov Technion, Haifa

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Courtesy of Technion (N.Lupu)

- Effect first reported by Technion (pulser), much smaller at Weizmann
- Due to external parasitics, needs investigation (PCB), risk of cross-talk

This may require disabling SREC and/or attenuating

Original Specs

3

Wire Signals

1. The VMM should recover from wire signals of $\langle Q_w \rangle = 6 \text{ pC}$ within 200 ns.
2. The linearity is not a critical factor here; however it is desirable for the linearity up to 2 pC to be known in order to apply offline corrections.

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Pad Signals

1. In ADC mode, the VMM should recover from pad signals of $\langle Q_p \rangle = \langle Q_w \rangle / 2 = 3 \text{ pC}$ within 250 ns.
2. The linearity is not a critical factor here; however it is desirable for the linearity up to 2 pC to be known in order to apply offline corrections.
3. In direct-timing-only mode (Time-over-Threshold and 6-bit ADC):
 - a. if the pulse charge is less than 6pC, the dead time shall be 60 ns after the trailing edge of the ToT pulse or 60ns after the readout of the last bit.
 - b. if the pulse charge is more than 6pC, the dead time shall not exceed $\sim 1 \mu\text{s}$ from the peak.

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Strip Signals

1. The VMM should recover from strip signals of $\langle Q_s \rangle = \langle Q_w \rangle / 6 = 1 \text{ pC}$ within 200 ns. The factor of 6 comes from the assumption that the signal will be distributed over three strips on average.
2. Linearity within $\pm 2\%$ up to 2 pC is required.

7

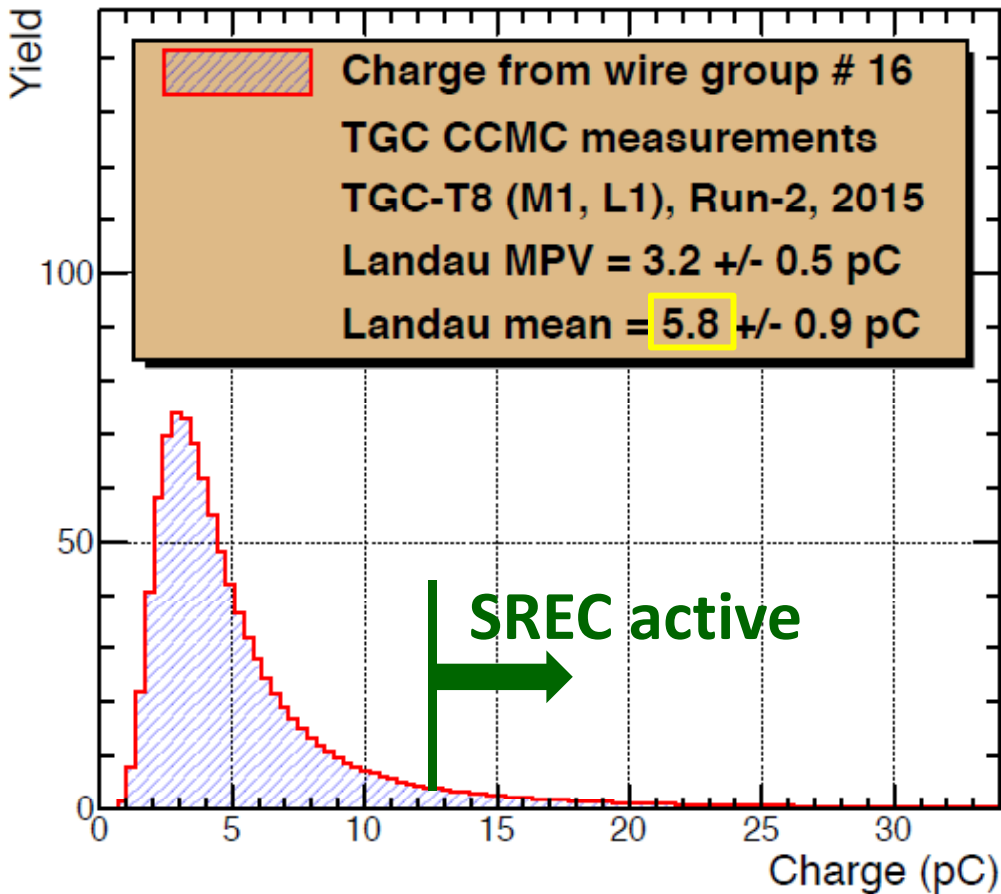
Rate per VMM

1. The expected/estimated maximum rate at luminosity of 7×10^{34} is 0.8 MHz per VMM channel for pads and 0.9 MHz per VMM channel for strips. An average strip multiplicity of 4.7 is assumed in this, including from neighbour-on mode. A value of 4.7 is on the considered to be on the high side, compared to data from the FNAL 2014 test beam which indicate an average of 4.2. The difference between the 2 numbers is kept as safety margin.

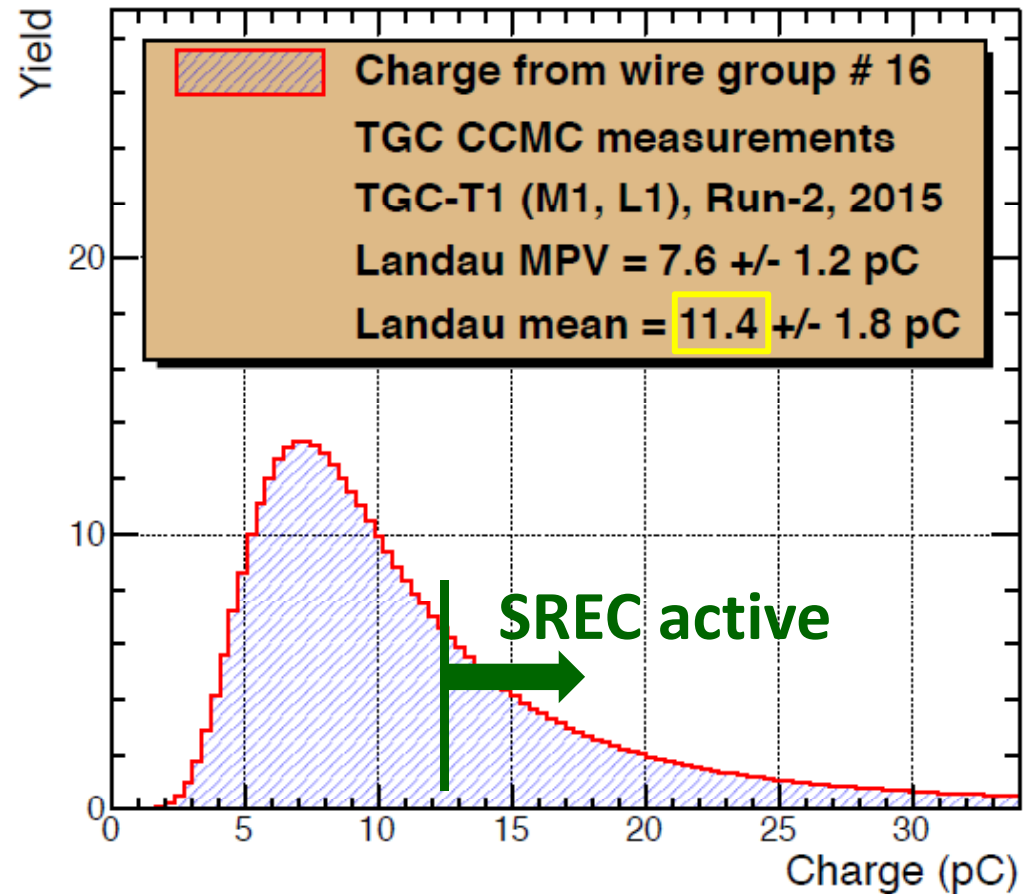
Example of simulation from Weizmann

- preliminary -

Analog response in the pit



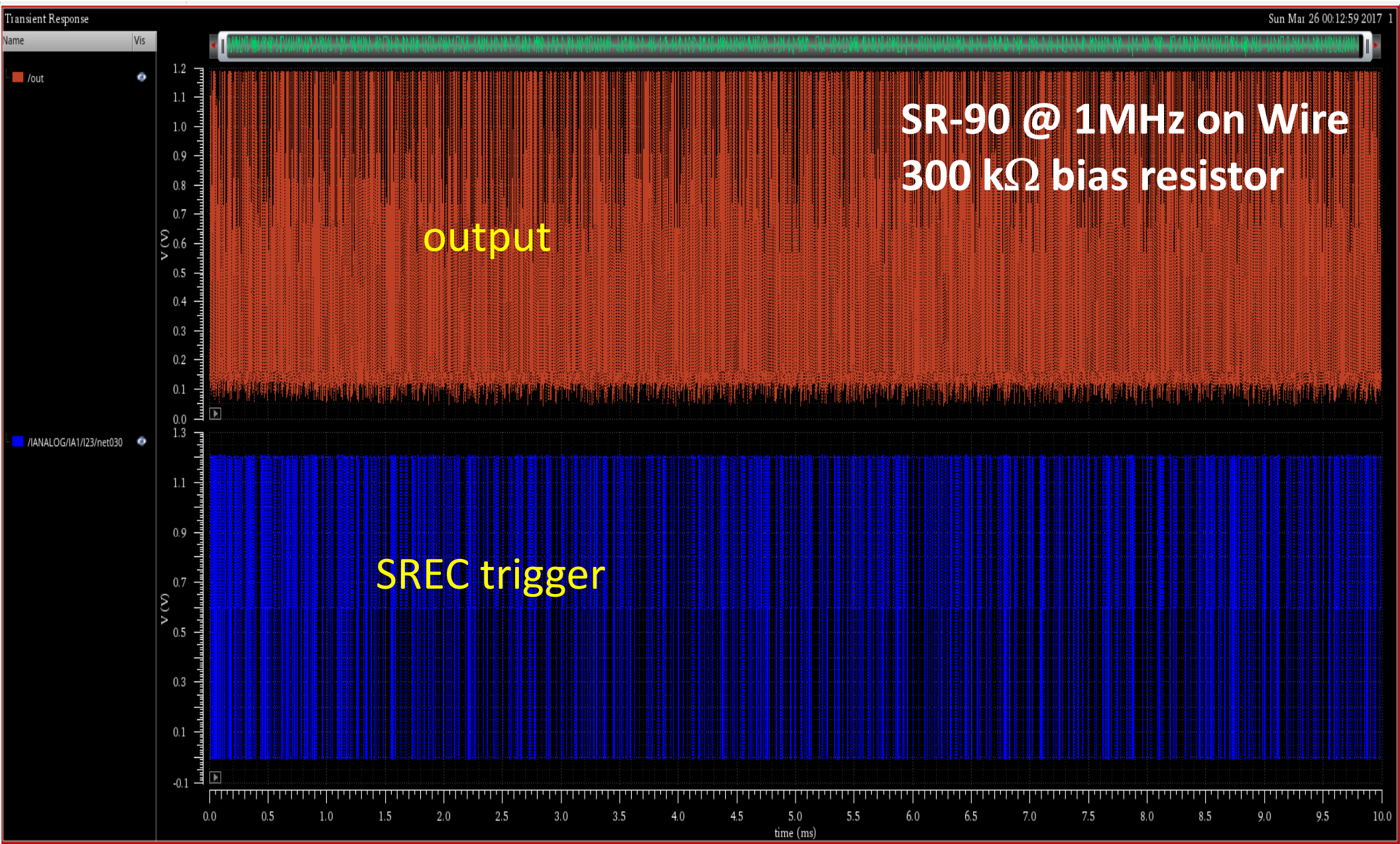
Analog response in the pit



Courtesy of Weizmann

Charges up to ~12 pC, Rates up to ~1.5 MHz (~18 μ A)

Wire Simulation SR-90 @ 1MHz - 300kΩ Resistor



Are Bias Resistors Enough?

- Input **bias currents (resistors) can reduce the dead time to very few % at most**, verified with average rates in excess of 1 MHz and average charges in excess of 15 pC.
- However, **the VMM3 internal nodes are still subject to excessive excursions**. Additionally, parasitic effects associated with high charge and fast-recovery circuit can cause **multiple triggers and cross-talk**, and it should be kept to a minimum.
- Critical: **Wires may exceed 10 μ A and can't afford frequent loss of virtual ground**.

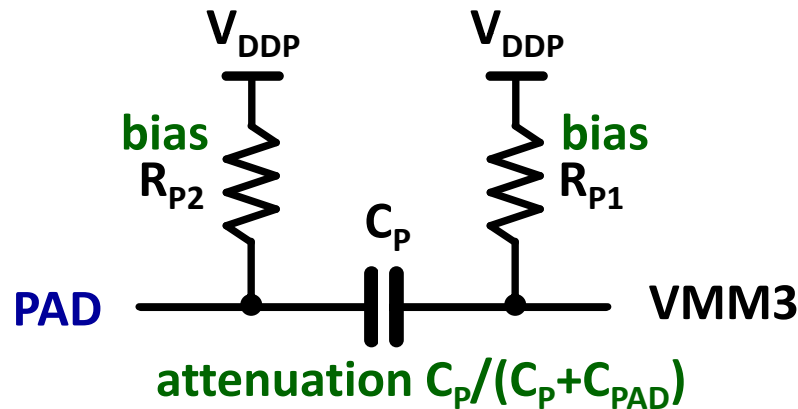


Capacitive Attenuation Networks (π -Networks)

The π -networks are designed to keep VMM3 in a safe linear region for most of the measurement, and to **minimize the engagement of the fast recovery circuit**.

- **Minimum size for integration in FEB** near the ESD protection circuit.
- **Increased protection** and **lifetime** of the front-end.
- **Very modest impact on S/N ratio**, increase in ENC **within 1fC**.
- **VMM gain can be increased** as needed.
- **Attenuation values** will come from **simulations and measurements** done in close collaboration with Weizmann and Technion.

Attenuation Networks (π -Networks)

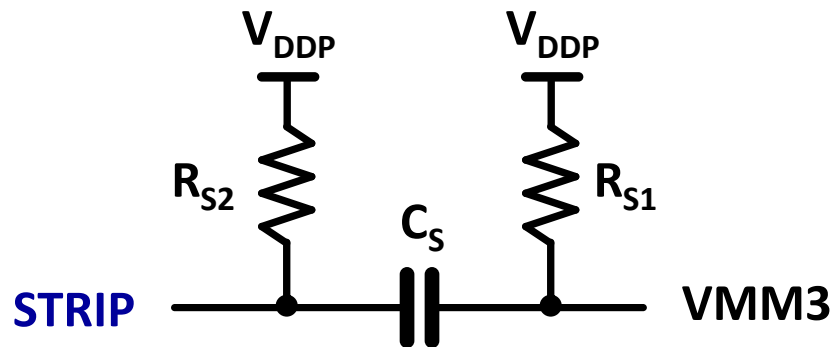


$$R_{p1} \approx 300 \text{ k}\Omega, R_{p2} \approx 300 \text{ k}\Omega$$

$$C_p \approx C_{PAD} / 2 \text{ or } 100 \text{ pF } 10\text{V}$$

Attenuation 1/3, can be adjusted

No attenuation \rightarrow only $R_{p1} = 100 \text{ k}\Omega$



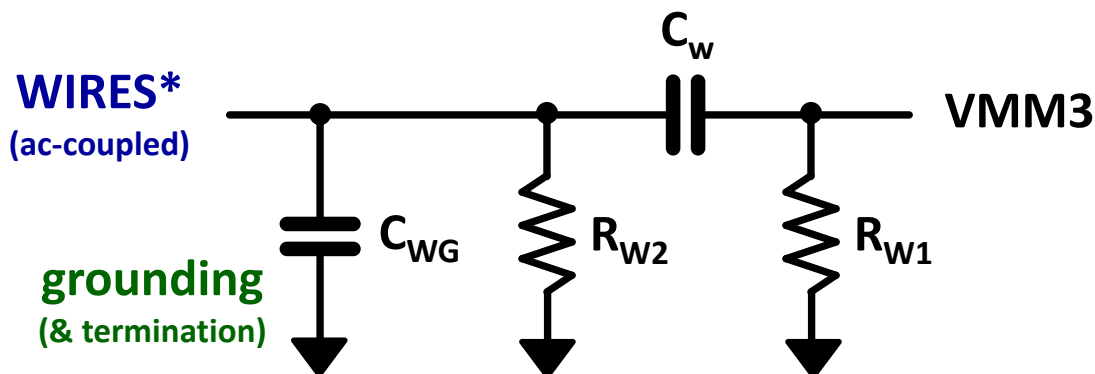
$$R_{s1} \approx 300 \text{ k}\Omega, R_{s2} \approx 300 \text{ k}\Omega$$

$$C_s > 100 \text{ pF } 10\text{V}$$

Small attenuation, or none

Beware of inter-strip coupling

No attenuation \rightarrow only $R_{s1} = 100 \text{ k}\Omega$



$$R_{w1} \approx 1 \text{ M}\Omega, R_{w2} \approx 300 \text{ k}\Omega$$

$$C_{wg} \approx 1 \text{ nF } 10\text{V}, C_w \approx 200 \text{ pF } 10\text{V}$$

Attenuation 1/6, can be adjusted

C_{wg} keeps wire impedance low

Controlled termination possible

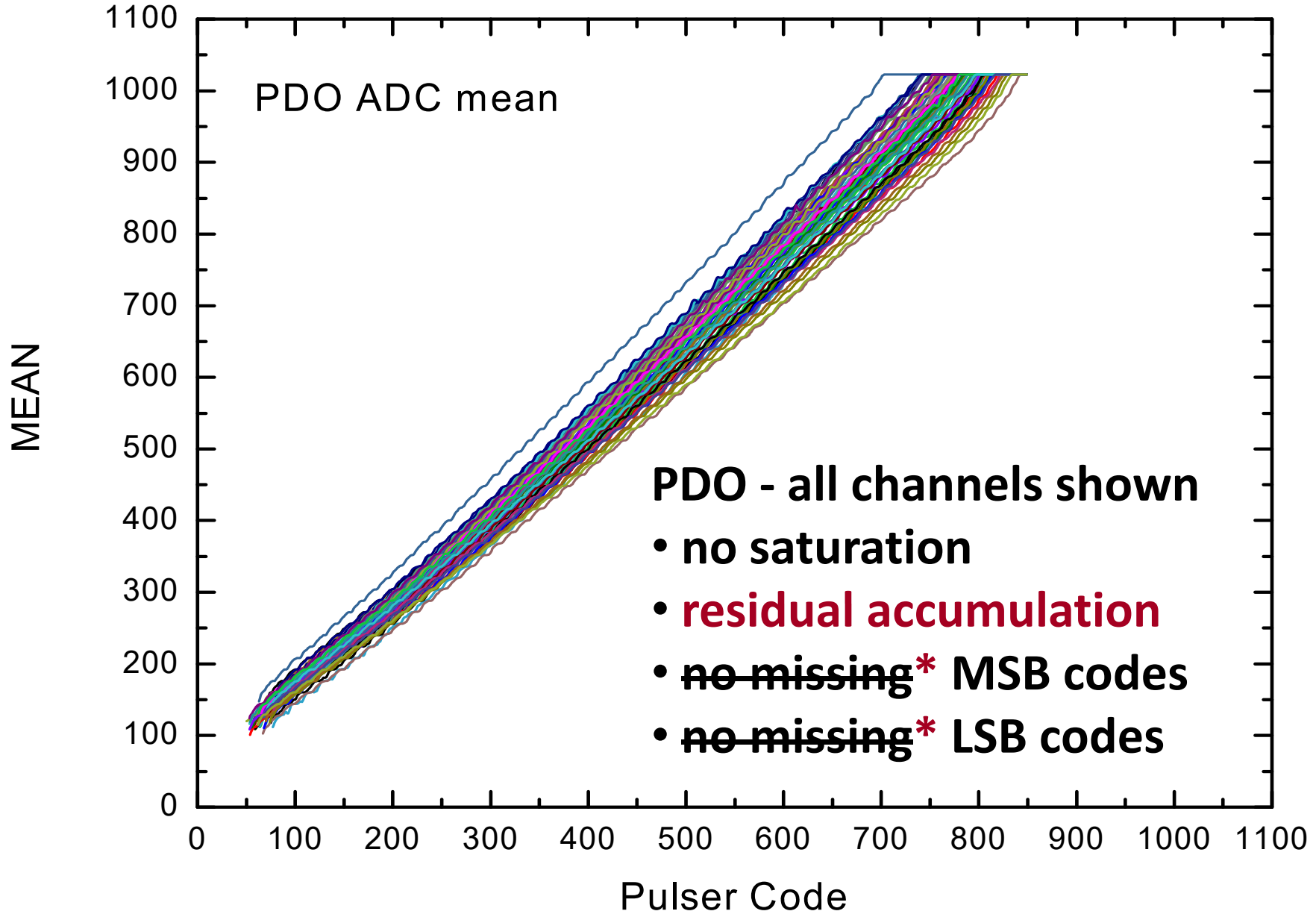
No attenuation \rightarrow only $R_{w1} = 300 \text{ k}\Omega$

* Alternative CR from Nachman (no C_{wg}) being investigated

Summary of ADC Accumulation Issue 2 (yield)

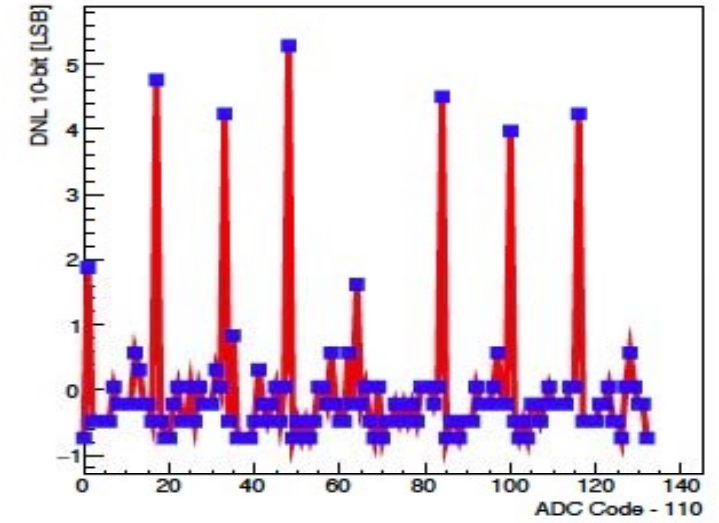
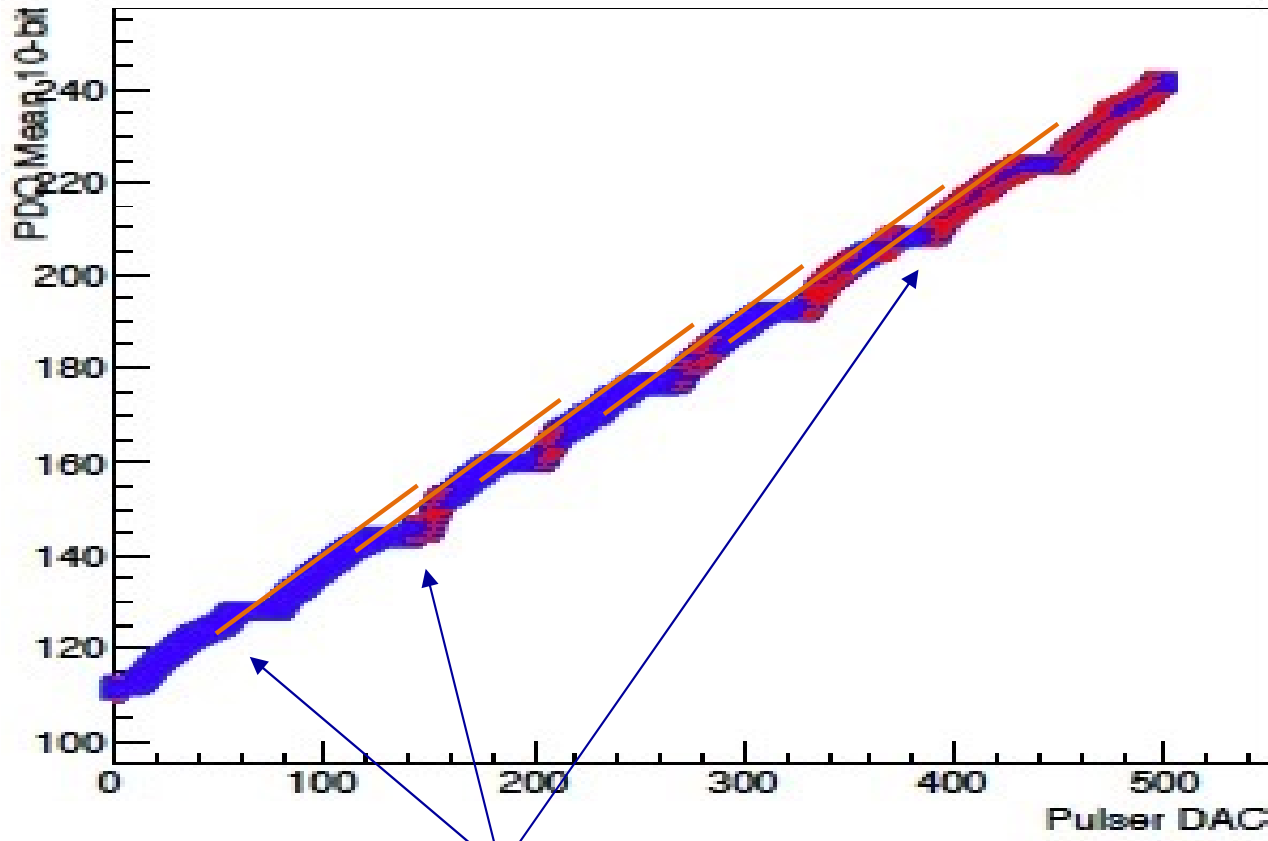
- **Issue** - Both 10-bit ADC (charge) and 8-bit ADC (timing) still present occasional (preliminary ~5%) missing MSB and LSB codes
- **Origin** - Residual mismatch between MSB decision p-MOSFETs
- **Workaround** - None
- **Fix** - TBD, simulations queued

ADC Results in VMM3

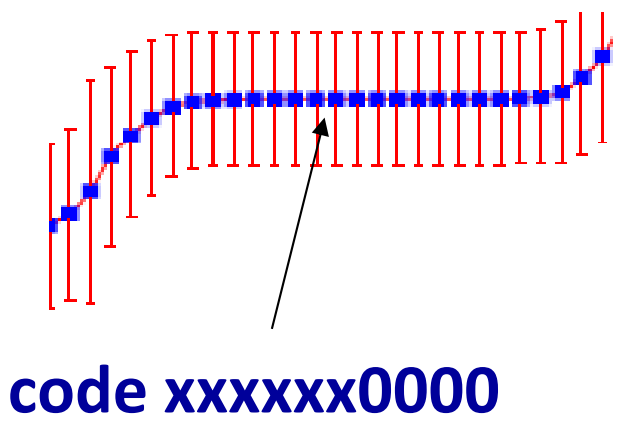


*** occasional missing of MSB and LSB codes still present**

Detail of Residual Accumulation



V. Polychronakos

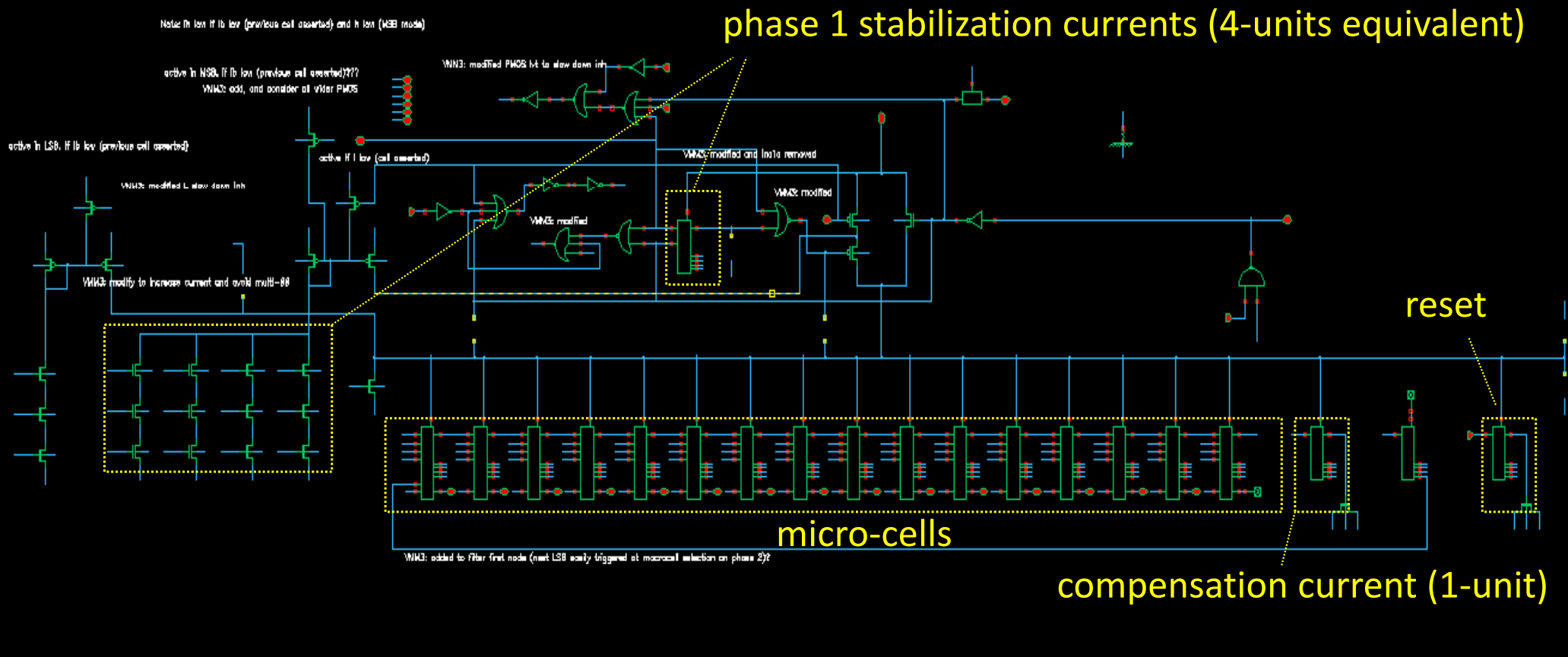


In phase 2: added parasitic current of ~4 micro-cells → **bin ~5 times larger** → **larger xxxxxx0000 code**

code xxxxxx0000

Probable Origin of Residual Accumulation

Macro-Cell Schematic



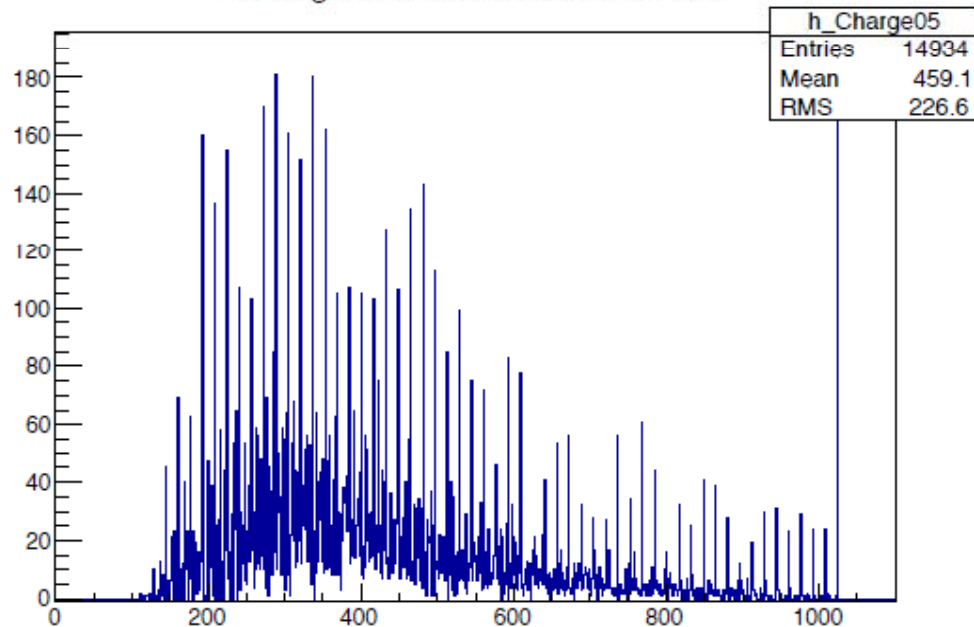
One of the phase 1 stabilization currents remains enabled during phase 2, resulting in the larger code xxxxxx0000

Missing MSB Yield Issue

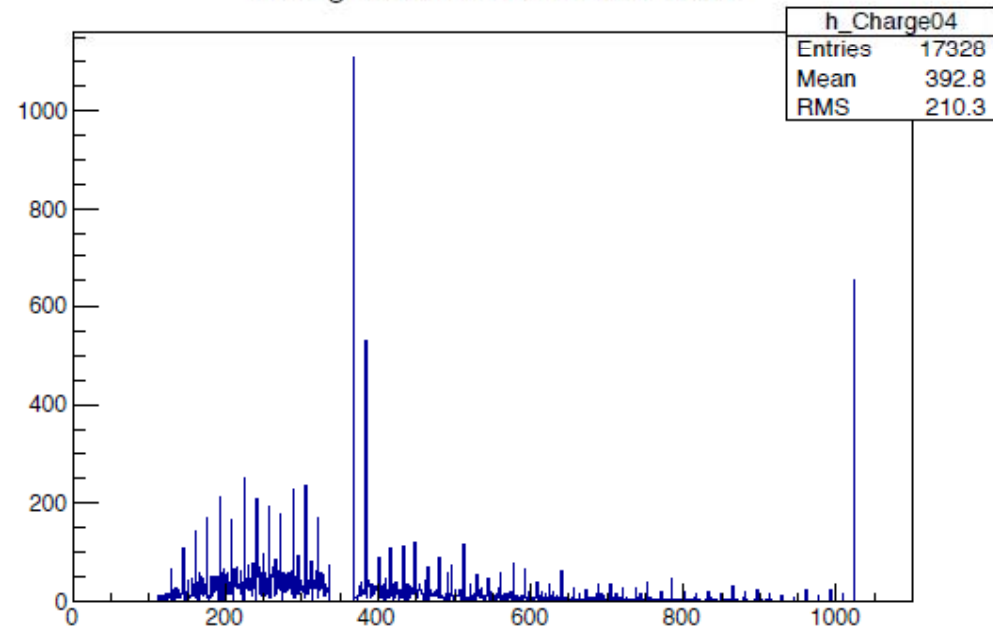
- Data taken with an MDT chamber shows that for some channels there is accumulation different than what was observed before.
- Gap in the distribution shows some macrocells-microcells completely missing while other channels show continuous spectrum.

~ 5% of the channels (preliminary)

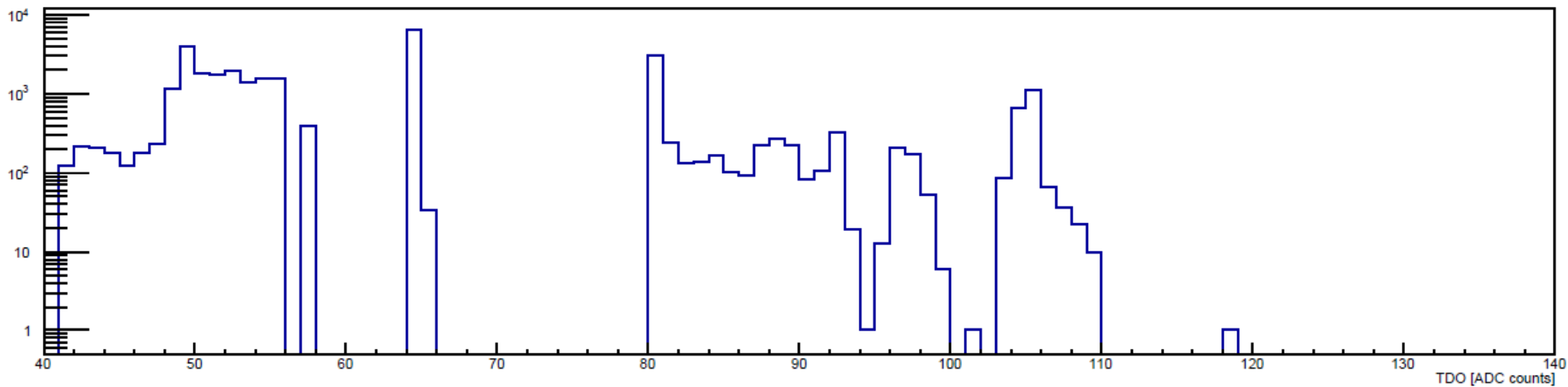
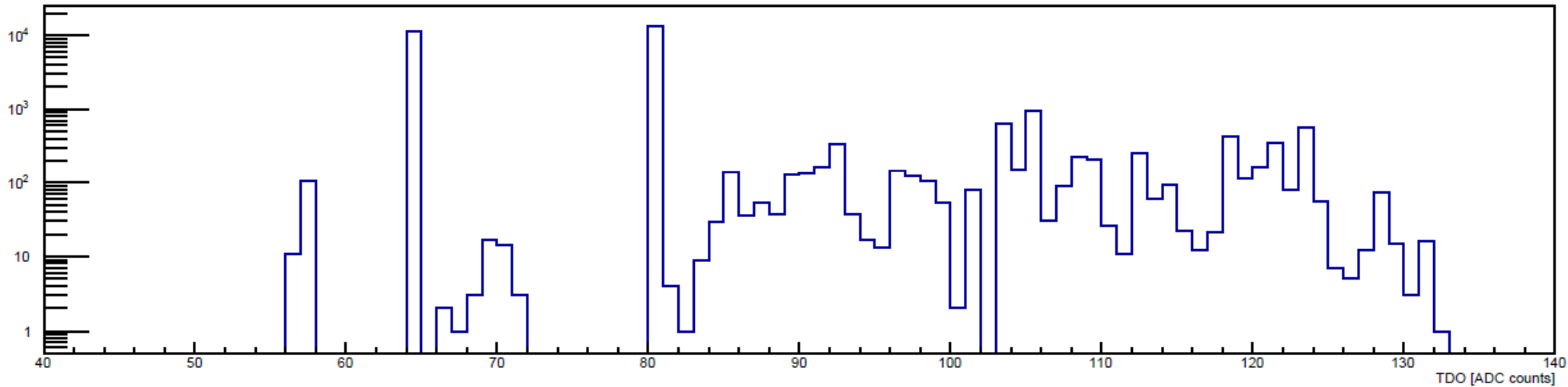
Charge of Chamber0 Channel5



Charge of Chamber0 Channel4



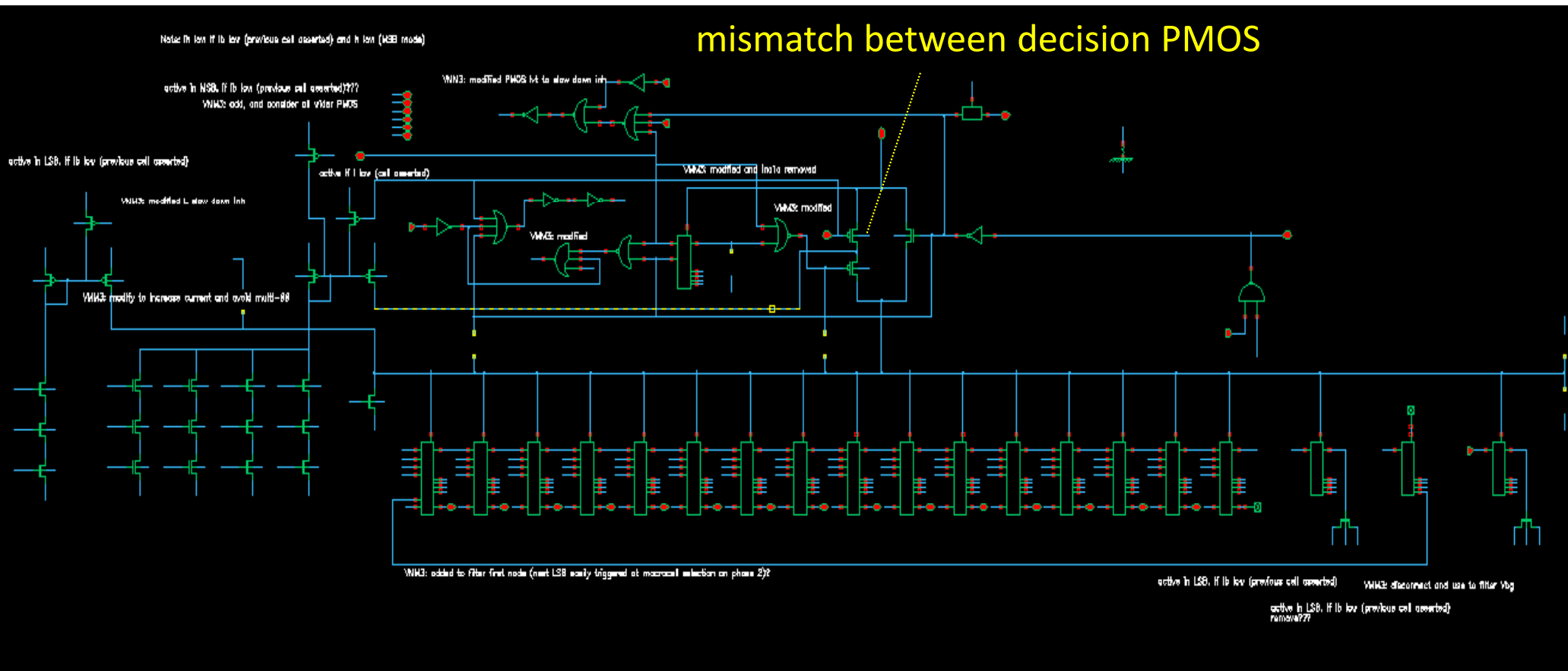
Missing MSB Yield Issue



**ADC offset does not shift position of missing MSB
→ Mismatch between MSB decision PMOS**

Probable Origin of Missing MSB

Macro-Cell Schematic



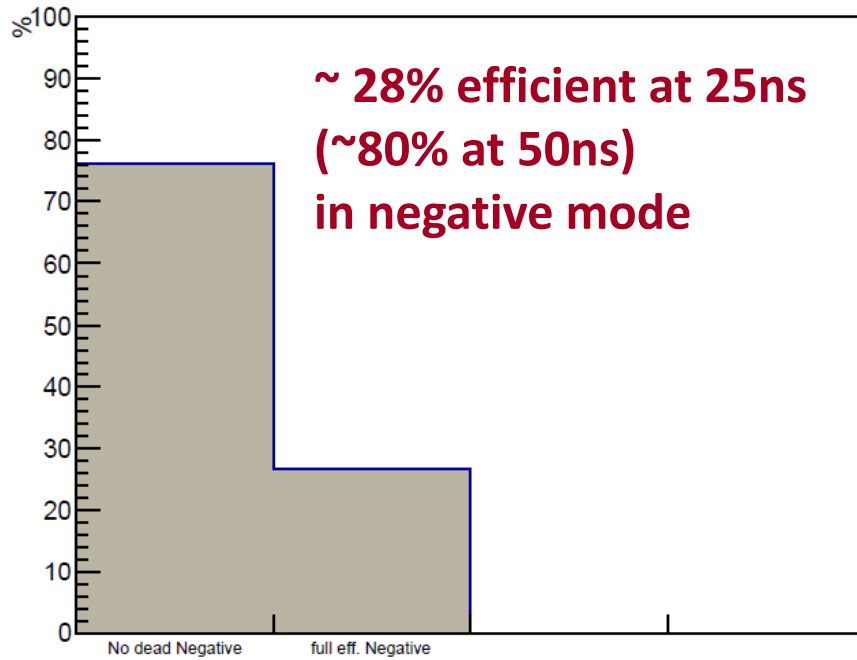
The decision PMOS is engaged only during the MSB phase. Excessive mismatch can cause selection of more than one Macro-Cell ahead.

Summary of High Baseline Issue 2 (yield)

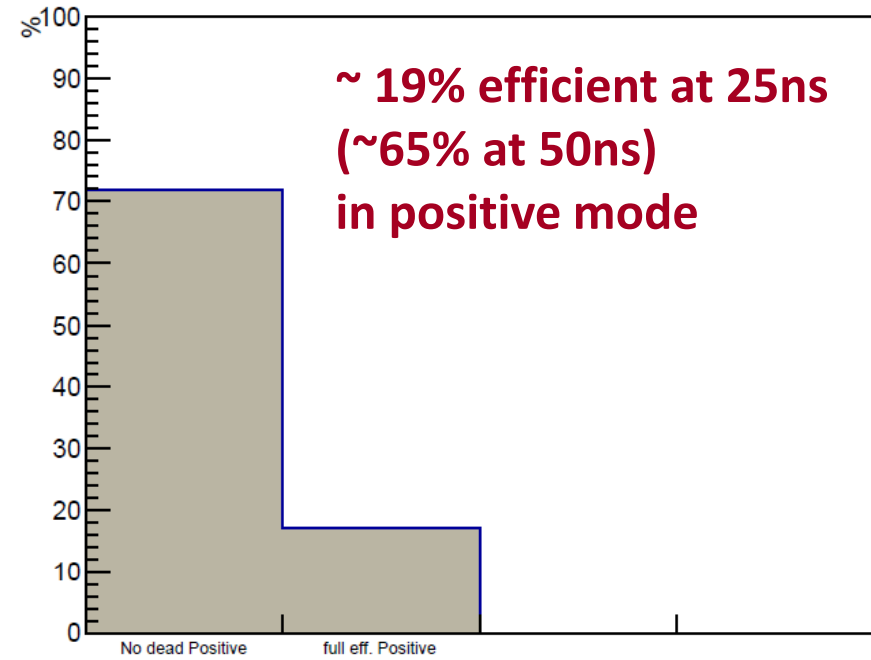
- **Yield Issue** - A large amount of samples exhibit small response and high analog baseline ($>200\text{mV}$, compared to the nominal $\sim 160\text{mV}$) in the central channels and no response when operating at the minimum peaking time 25ns
- **Origin** - Limited drive capability in second stage of shaper, combined with ground voltage drop
- **Possible workaround** - Operate sTGC at 50ns
- **Fix** - Increase driver size

Measured Statistics on High Baseline Issue 2

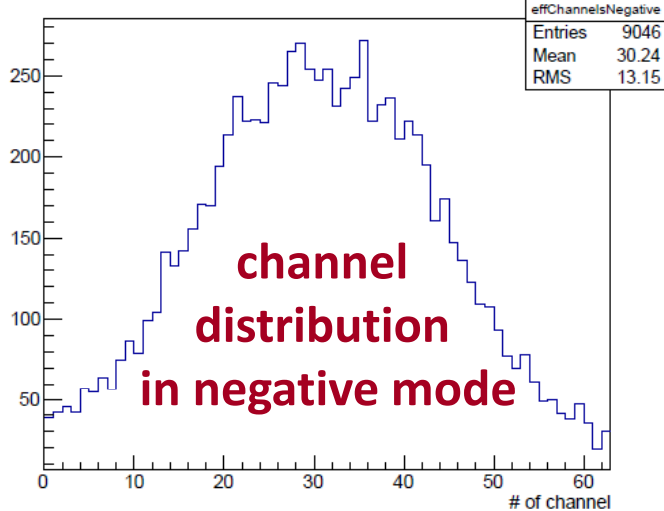
Statistics Negative



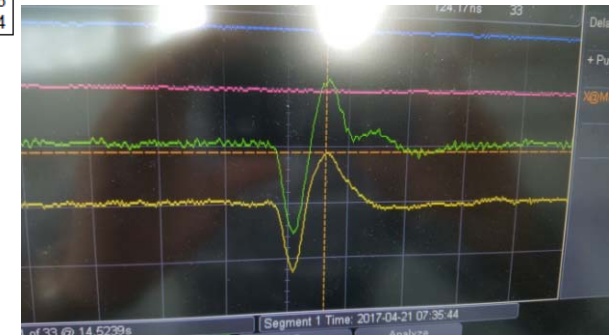
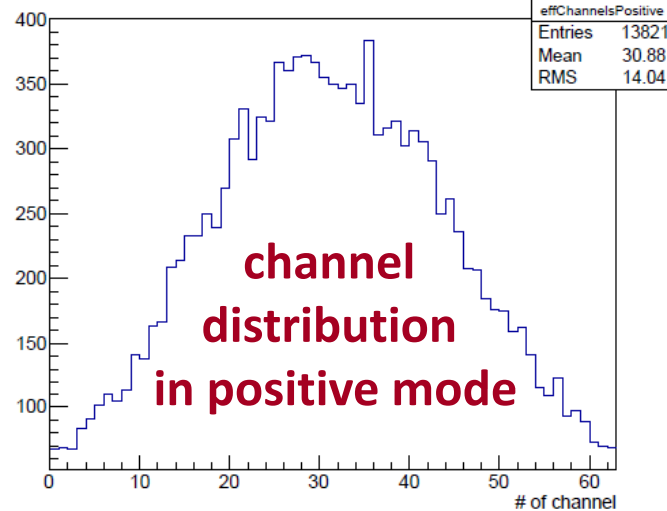
Statistics Positive



Non Efficient Channels Negative

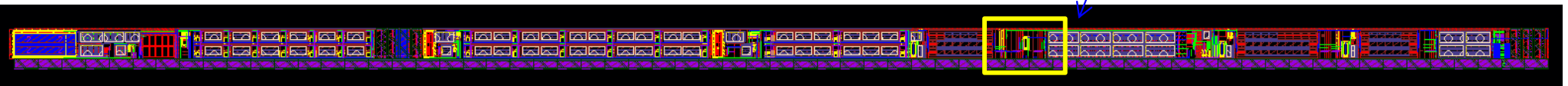
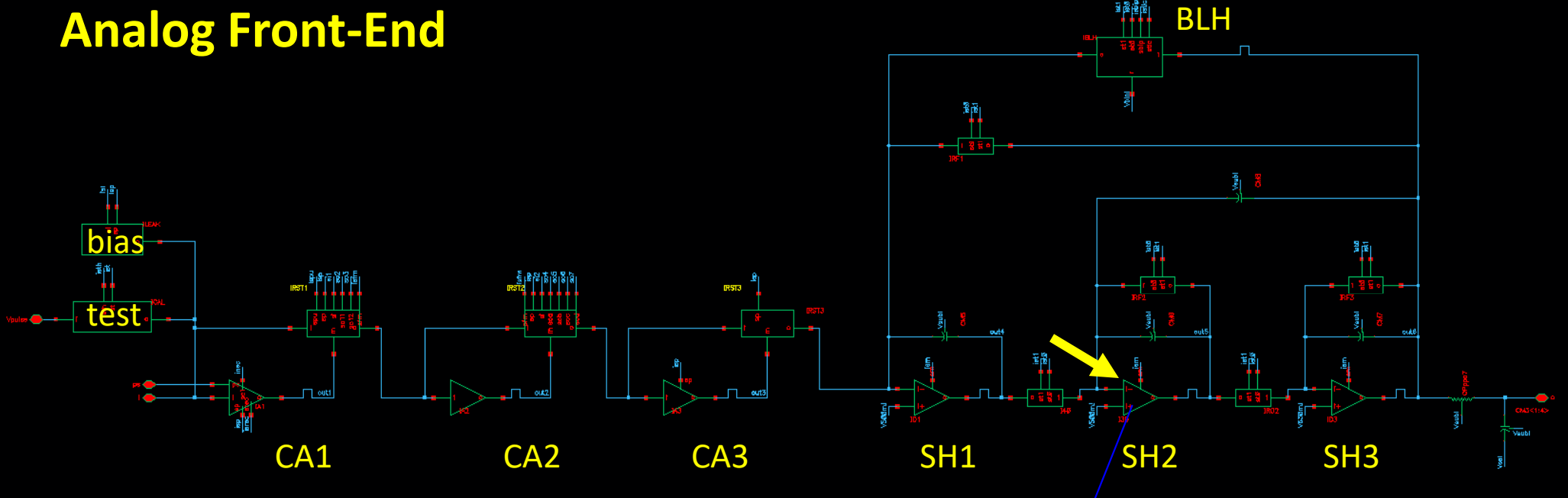


Non Efficient Channels Positive



Shaper Amplifier

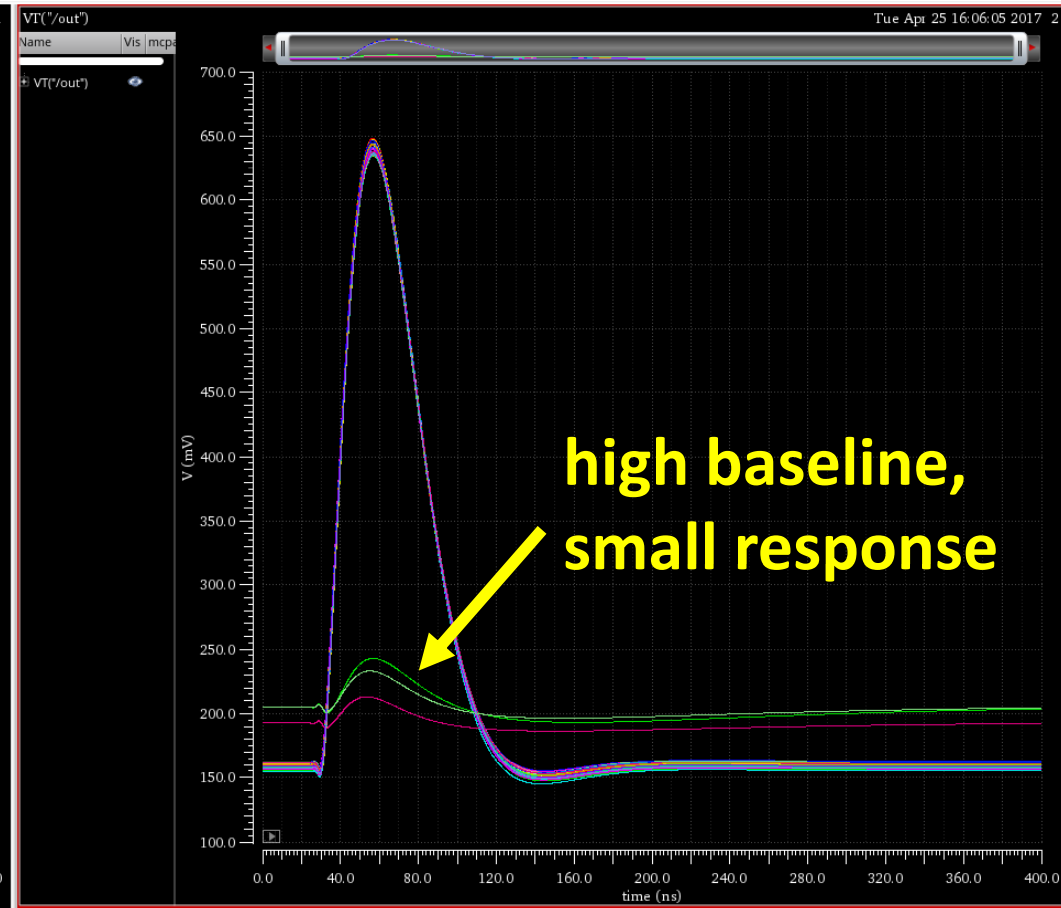
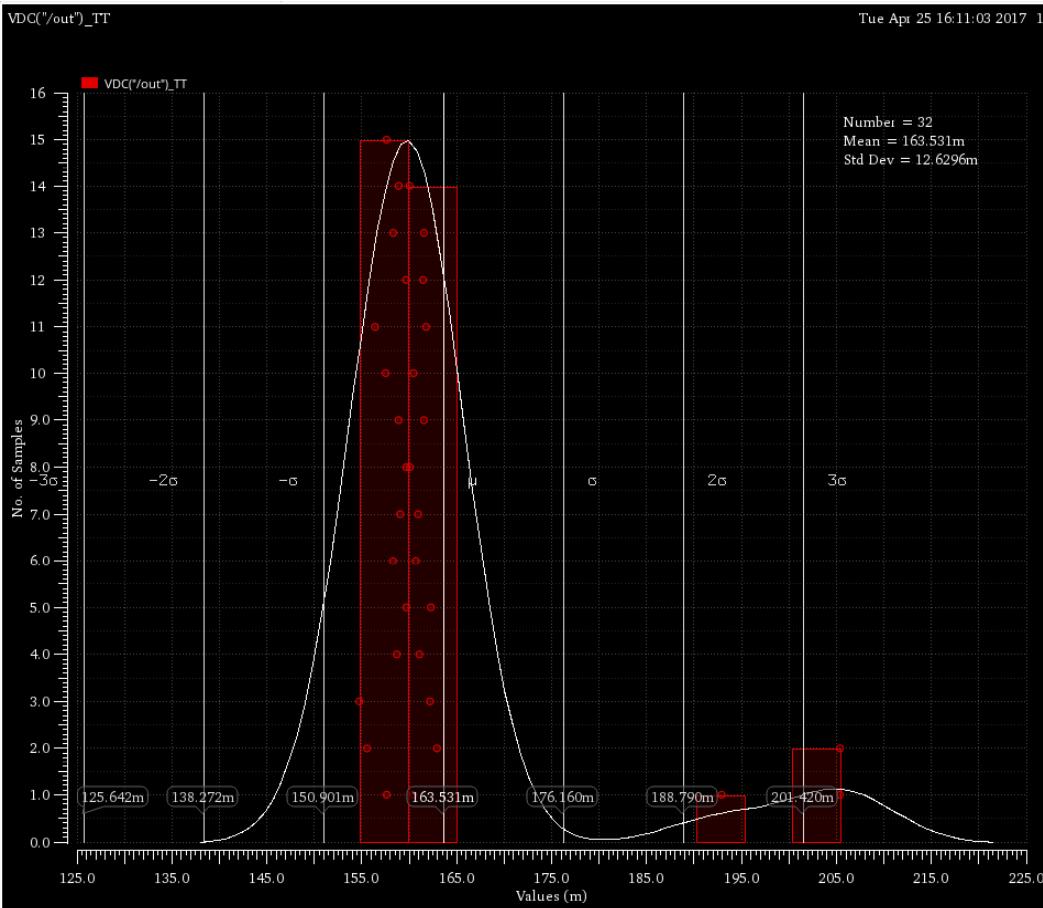
Analog Front-End



~ 4mm

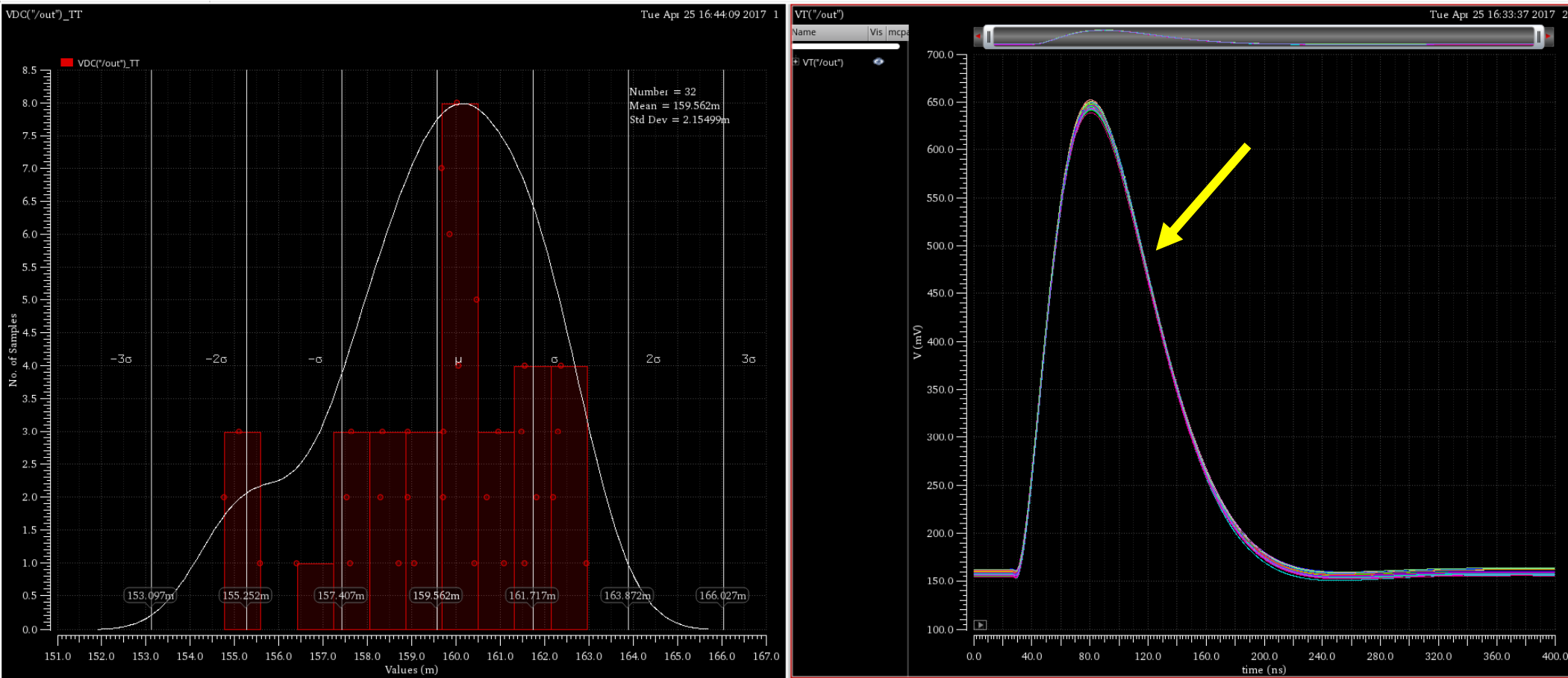
- Shaper amplifier is composed of three voltage amplifiers with programmable passive feedback in DDF configuration to realize one real pole and two complex conjugate poles.
- Issue is in the output stage of second amplifier, combined with voltage drop of ground at center chip

Monte Carlo at 25ns



- Monte Carlo TT simulation with 8mV ground voltage drop at 25ns. Second amplifier output stage doesn't have enough current to bring internal nodes to the correct operating point.

Monte Carlo at 50ns



- Monte Carlo TT simulation with 8mV ground voltage drop at 50ns. Larger feedback resistor allow amplifier to bring internal nodes to the correct operating point.

VMM3 Issues

Issue	Circuit	Notes
Need start-up sequence	channel logic	workaround
Handle sTGC charge & rate	analog front-end	workaround
Locking in ToT	channel logic	workaround
ENA acquisition reset	control logic	workaround
Trimming range extension	channel trimmer amplifier	3/4 of targeted
High baseline	shaper	workaround - yield 25ns*
ADC accumulation	ADCs	improvements - yield MSB*

*new

Conclusions

- VMM3 is the first full prototype front-end ASIC for the ATLAS Muon upgrade
- **Seven** issues have been found:

Issue	Circuit	Notes
Need start-up sequence	channel logic	workaround
Handle sTGC charge & rate	analog front-end	workaround
Locking in ToT	channel logic	workaround
ENA acquisition reset	control logic	workaround
Trimming range extension	channel trimmer amplifier	3/4 of targeted
High baseline	shaper	workaround - yield 25ns*
ADC accumulation	ADCs	improvements - yield MSB*

- Most issues have workaround or may be acceptable
- Two may severely impact the **yield**

Design Time Required for Fixes (VMM3a)

Fix		Complexity	Risk	Confidence	Time (hrs)
ADC	linearity	medium	low	moderate	~ 80
	yield	medium	low	moderate	~ 120
Reset		low	low	high	~ 30
SFM		low	low	high	~ 30
Baseline	stlc	very low	very low	high	~ 20
	yield	very low	very low	high	~ 40
Trim DAC		very low	negligible	very high	~ 15
Startup		very low	negligible	very high	~ 15
DRC, LVS					~ 20

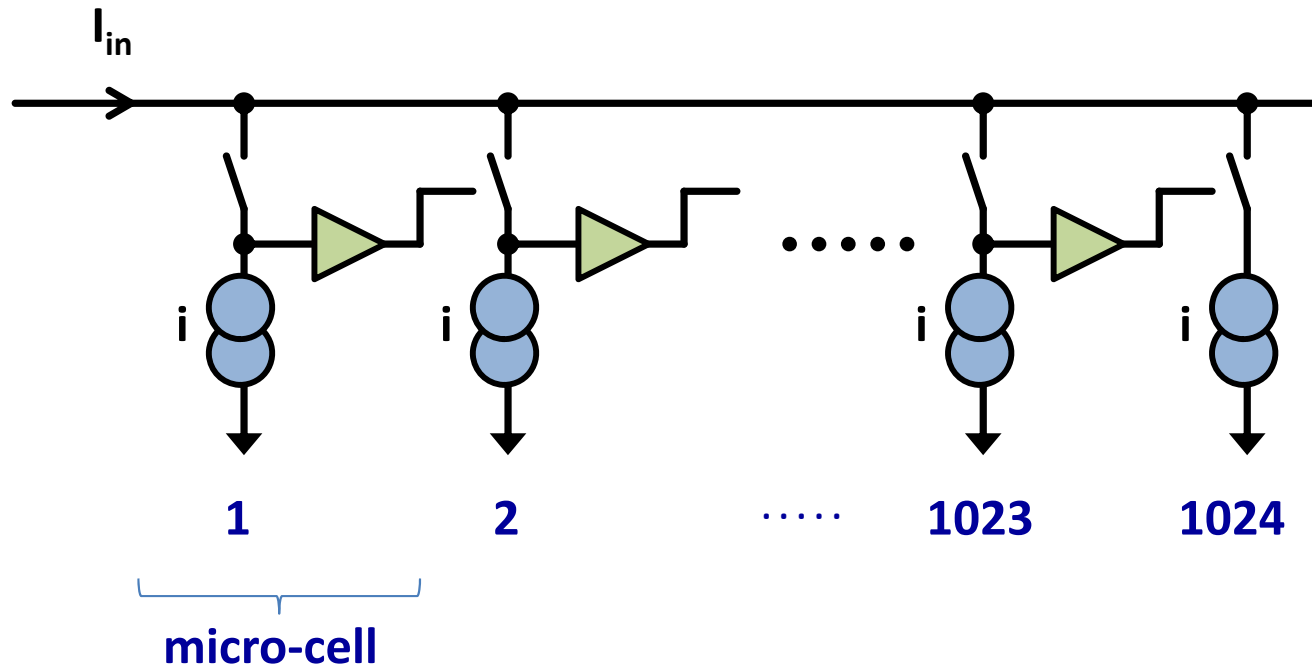
If going directly for production, please allow margins for extra checks

Backup Slides

Summary of ADC Accumulation Issue

- **Issue** - Both 10-bit ADC (charge) and 8-bit ADC (timing) exhibit residual accumulations at the MSB transitions; effective resolution reduced by ~3 bits and ~2 bits respectively
- **Probable origin** - Parasitic current from the MSB phase
- **Workaround** - None
- **Fix** - TBD, simulations queued

ADC: CMD Architecture



1024 micro-cells

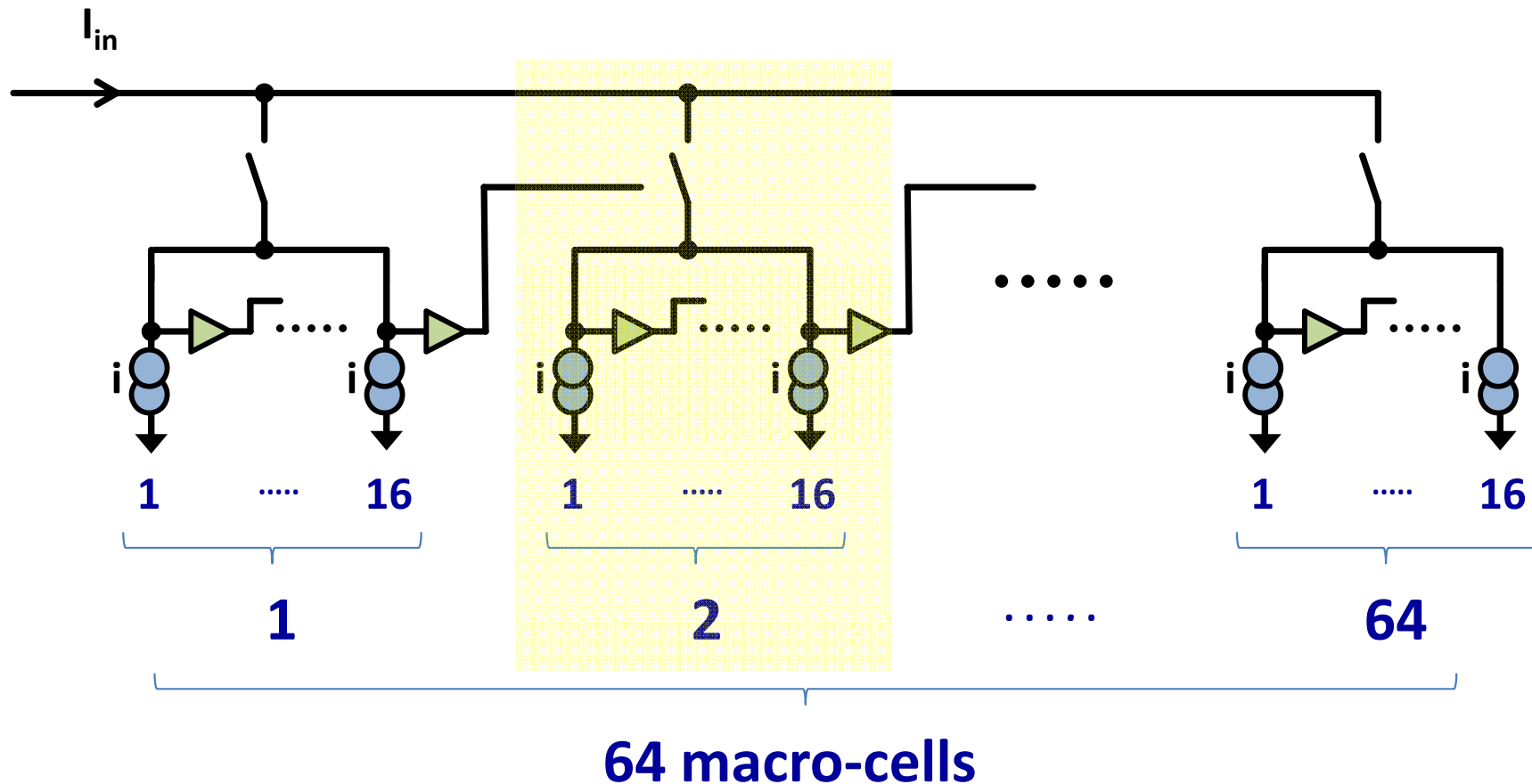
Current-Mode Domino

- no clock required
- early conversion start
- proven in single phase
- **two-phase concept**

Two-Phase ADC Architecture

phase 1: macro-cell selection

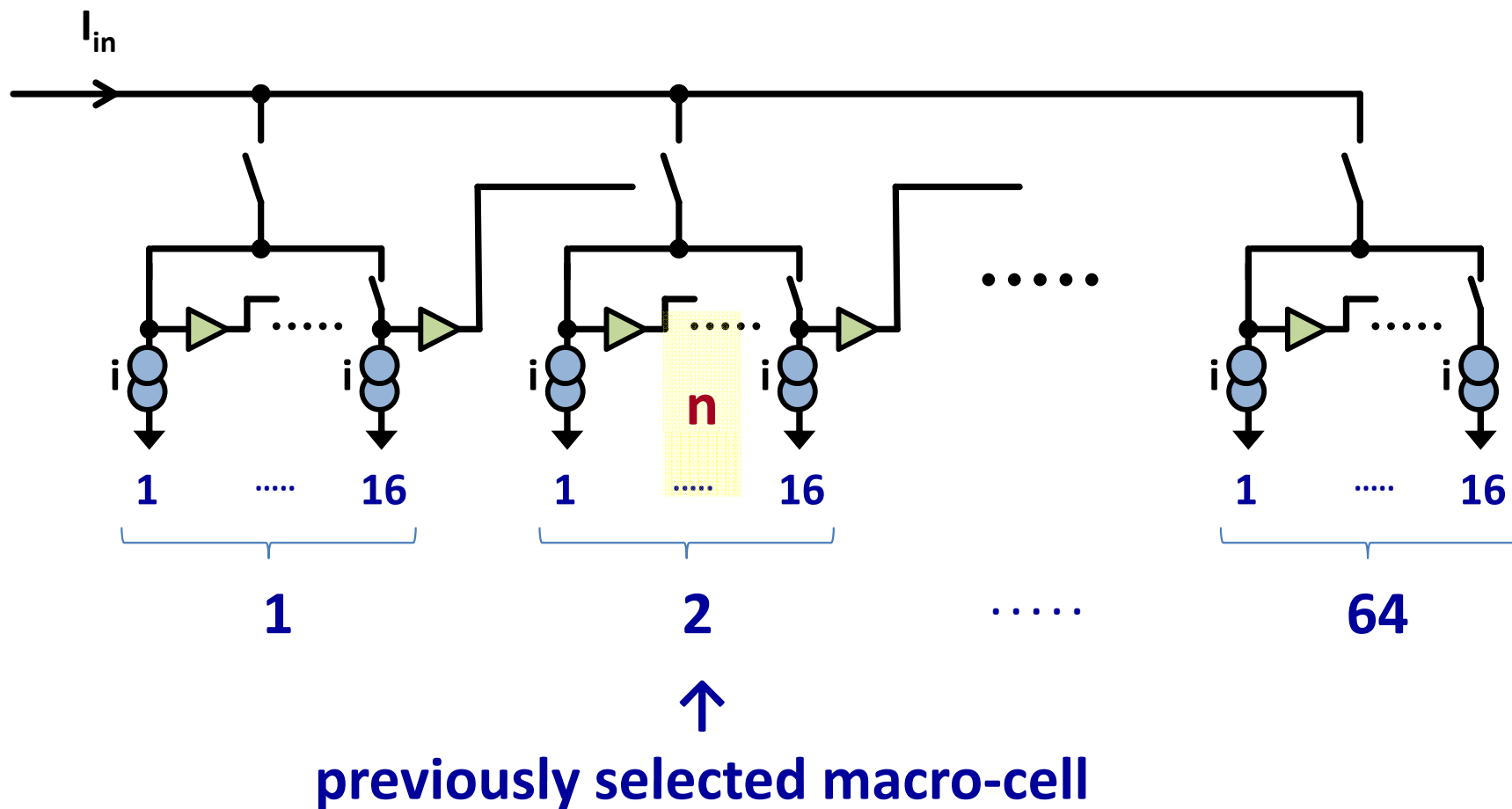
micro-cells are shorted together in groups of 16



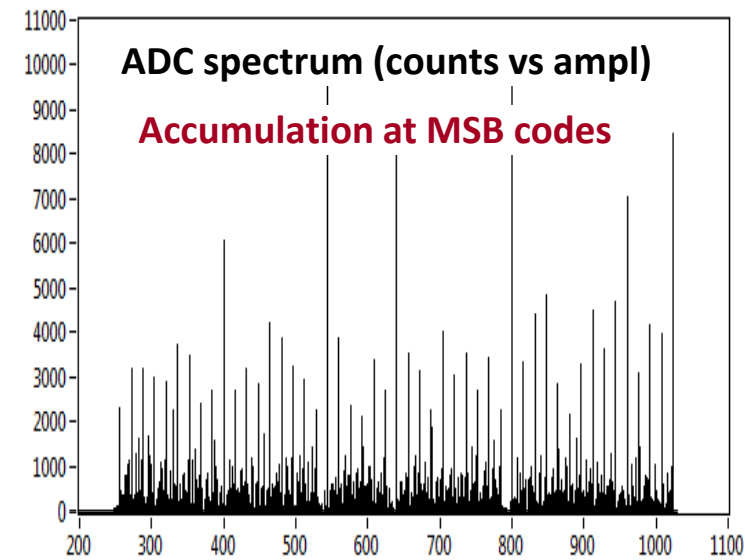
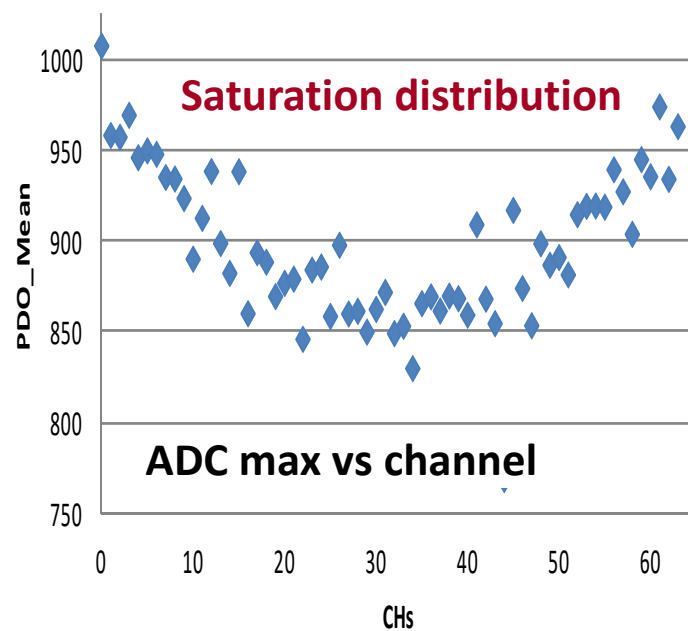
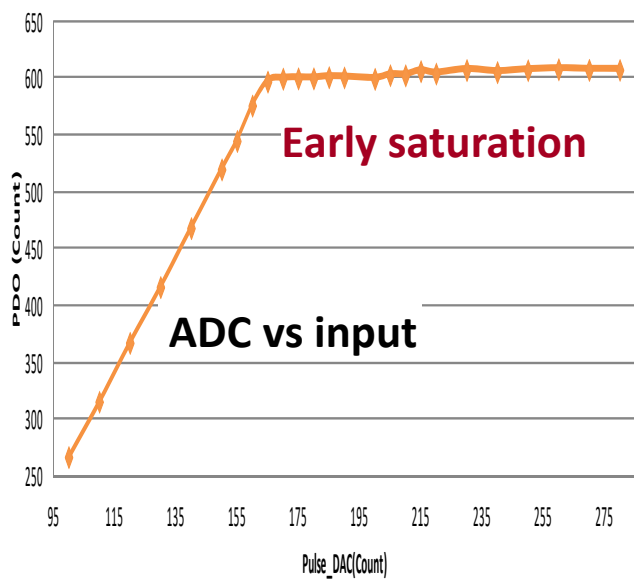
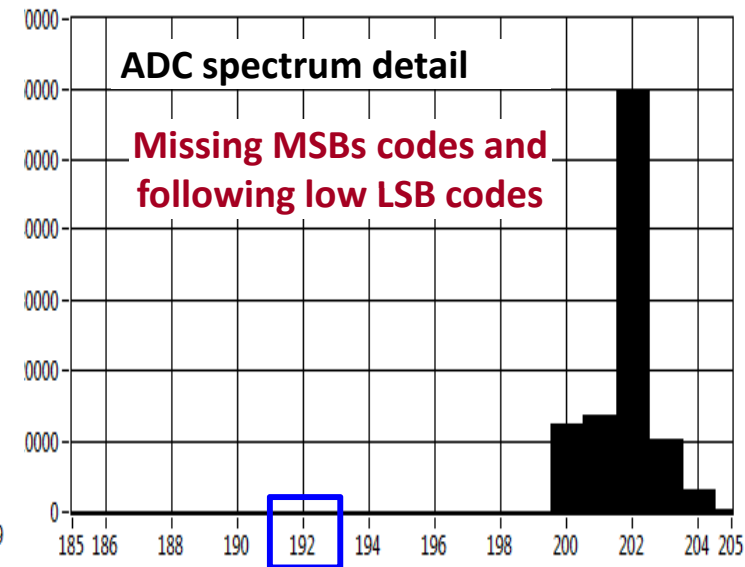
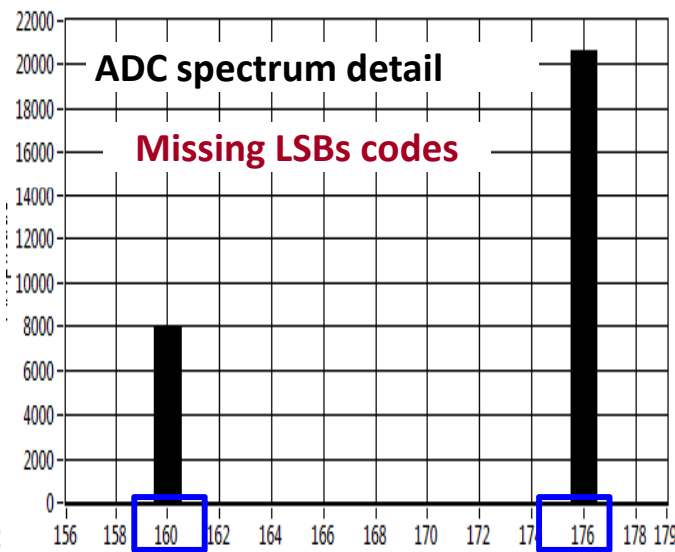
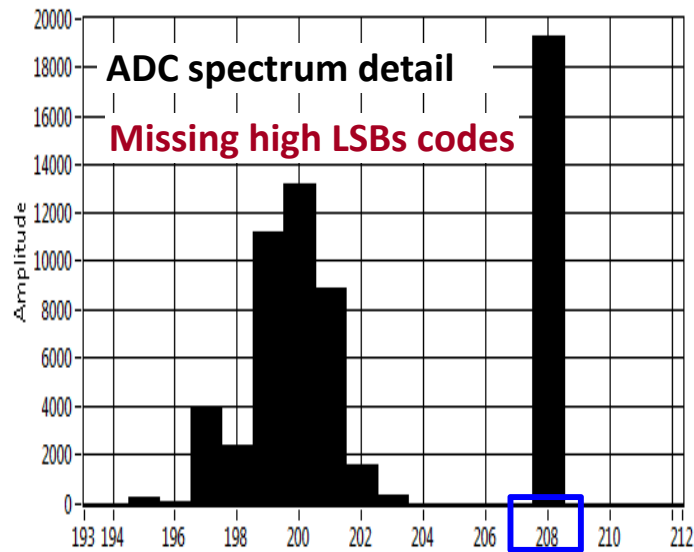
Two-Phase ADC Architecture

phase 2: micro-cell selection

micro-cells are separated individually

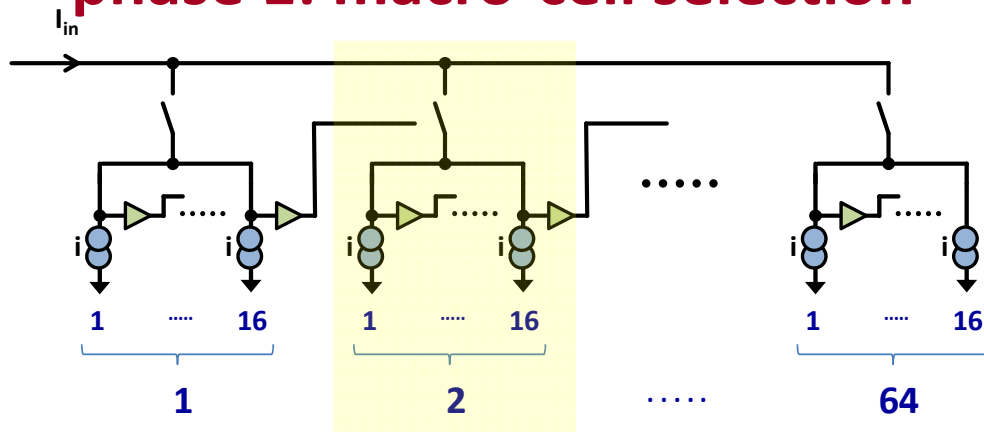


Relevant Issues in VMM2



Major Issue in VMM2 Architecture

phase 1: macro-cell selection

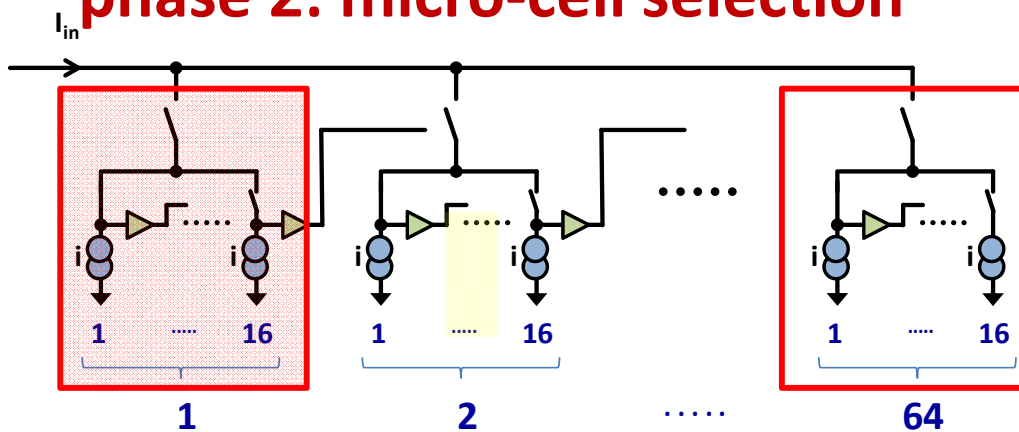


If wrong macro-cell selected (from ringing, pickup, ...)

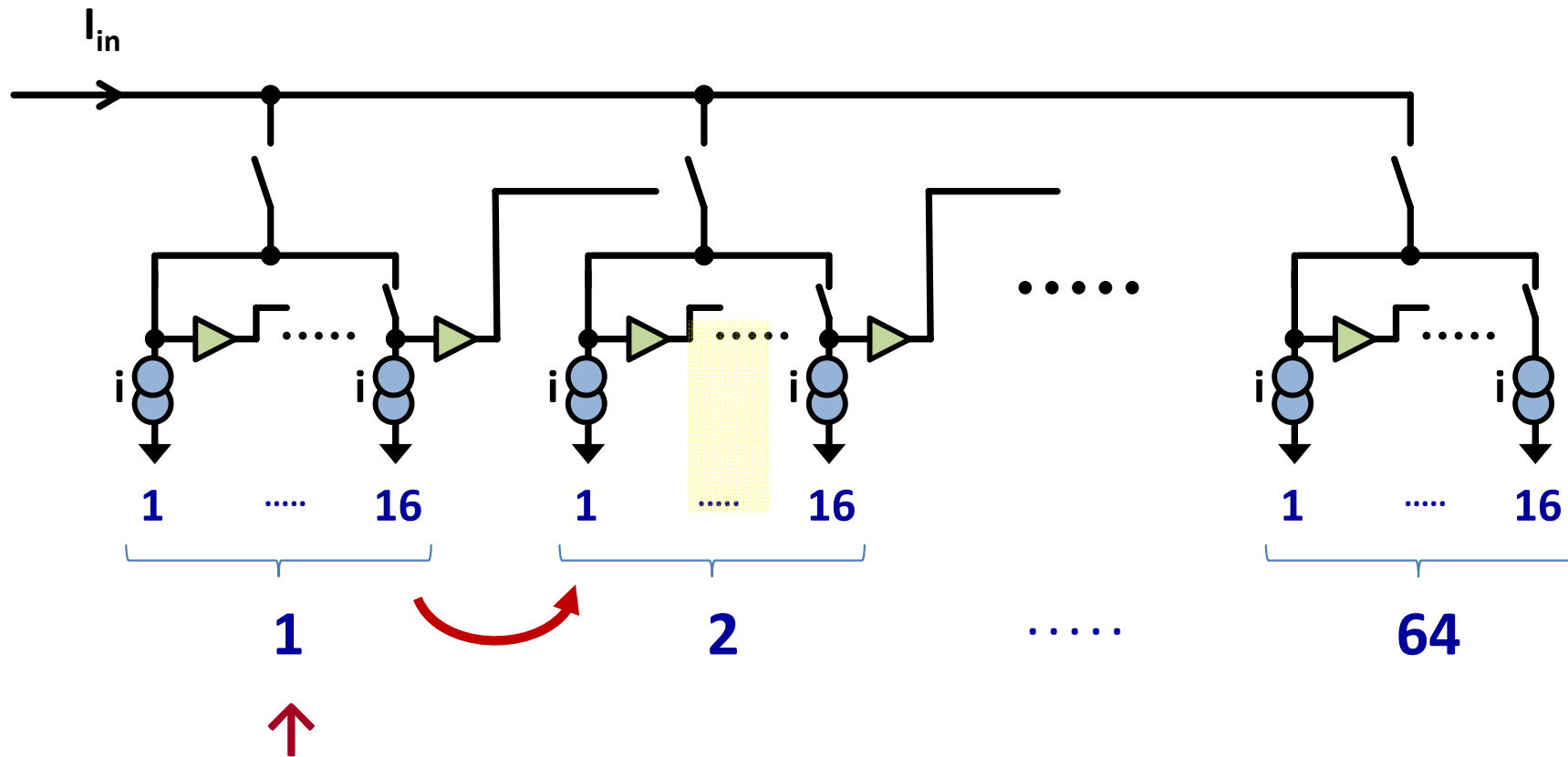


micro-cell selection fails

phase 2: micro-cell selection

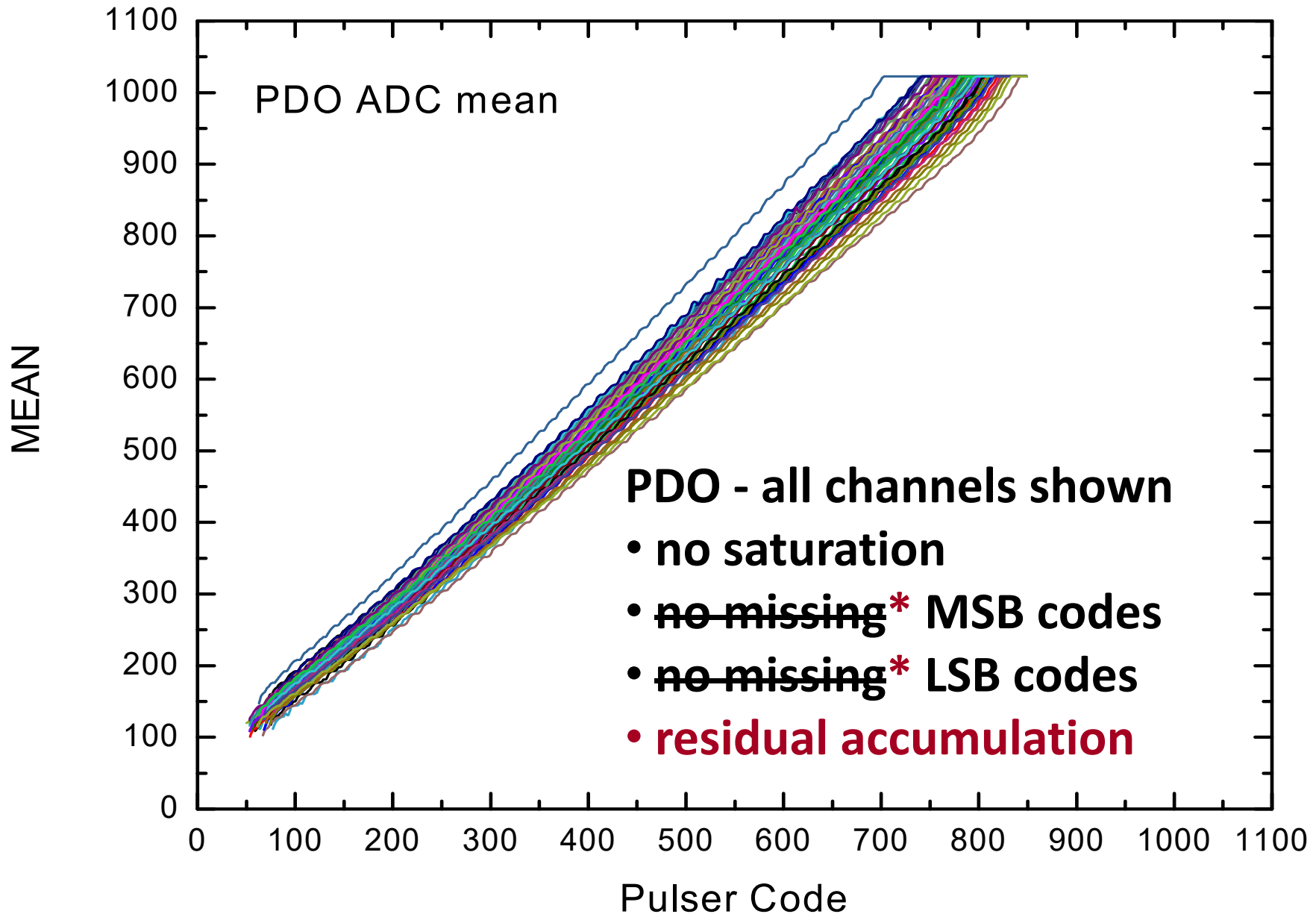


Pre-Cell Concept in VMM3



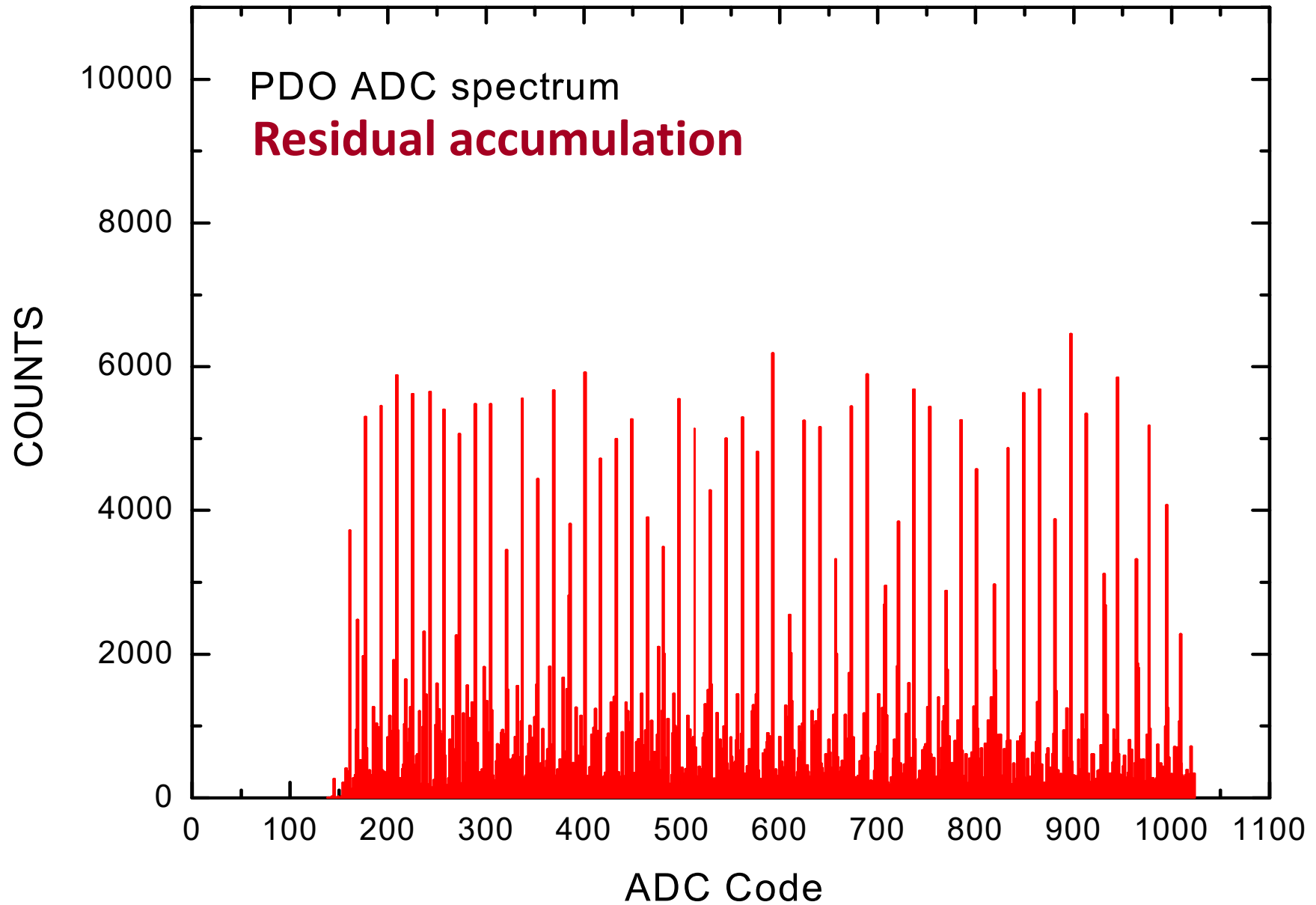
Phase 1: same - Phase 2: micro-cell selection starts from preceding macro-cell, able to transition to the next macro-cell

ADC Results in VMM3



* occasional missing MSB and LSB codes still present

ADC Results in VMM3



Working with Reduced ADC Resolution

“... which results in **ENOB = 7.4 bits**” see **Vinnie’s backup slides**

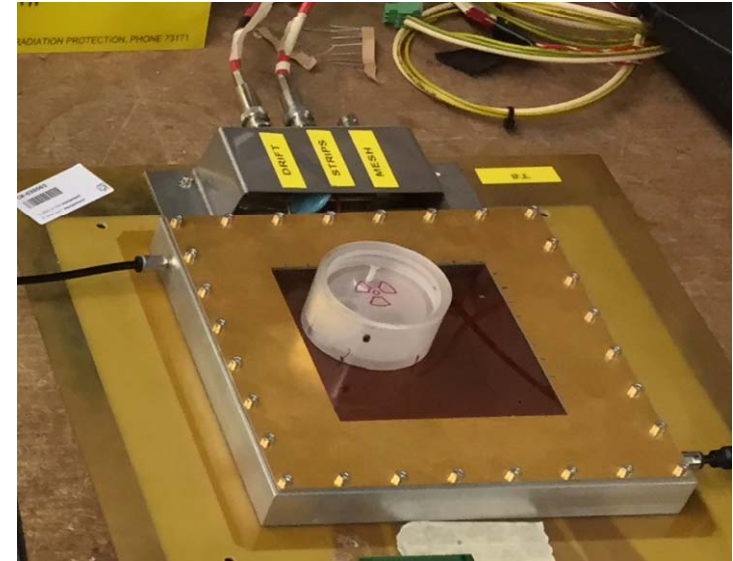
10-bit amplitude ADC with 7-bit effective resolution

$$\text{ADC noise at 6mV/fC: } \frac{1}{\frac{6 \cdot 10^{-3}}{2^{10-7} \cdot \sqrt{12}}} = 0.38 \text{ fC rms}$$

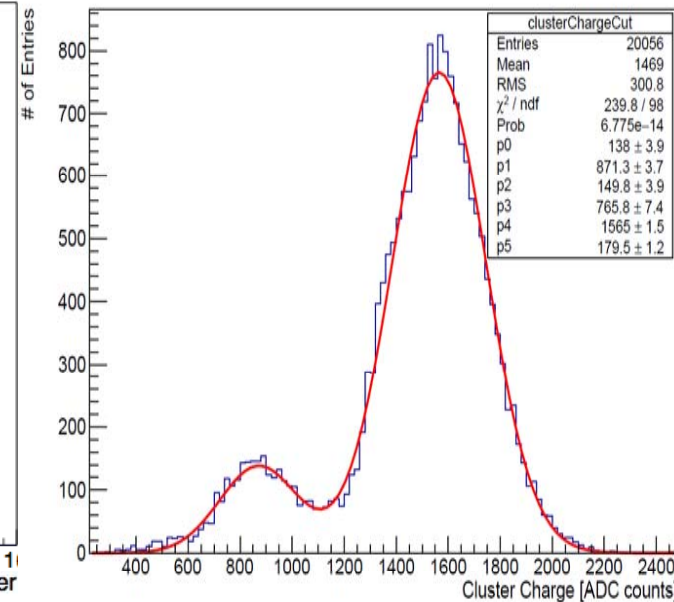
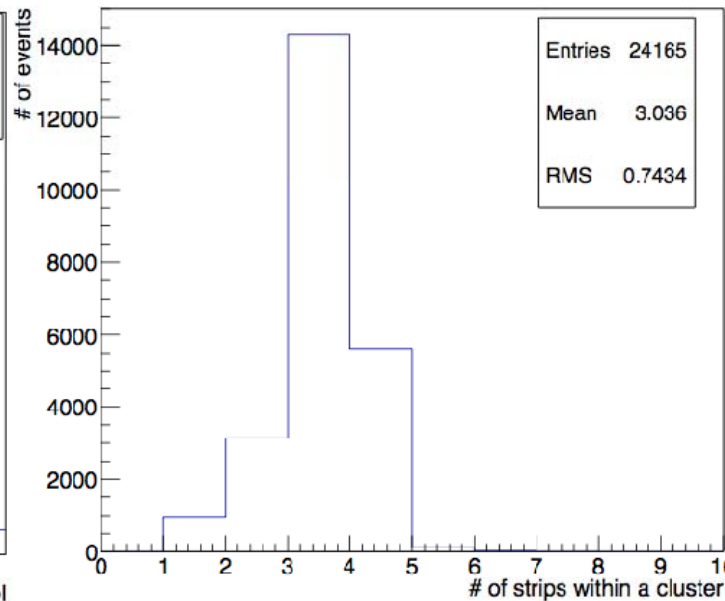
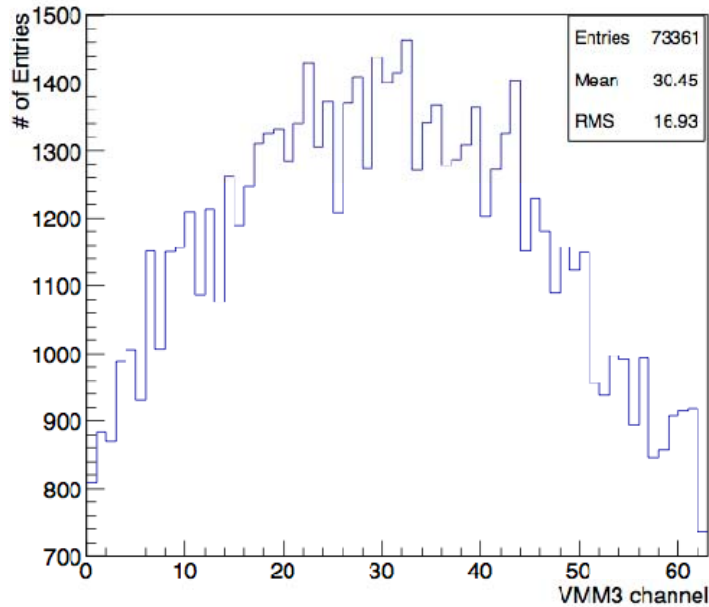
8-bit timing ADC with 6-bit effective resolution

$$\text{ADC noise at 60ns TAC: } \frac{1}{\frac{6 \cdot 10^{-3}}{2^{10-7} \cdot \sqrt{12}}} = 270 \text{ ps rms}$$

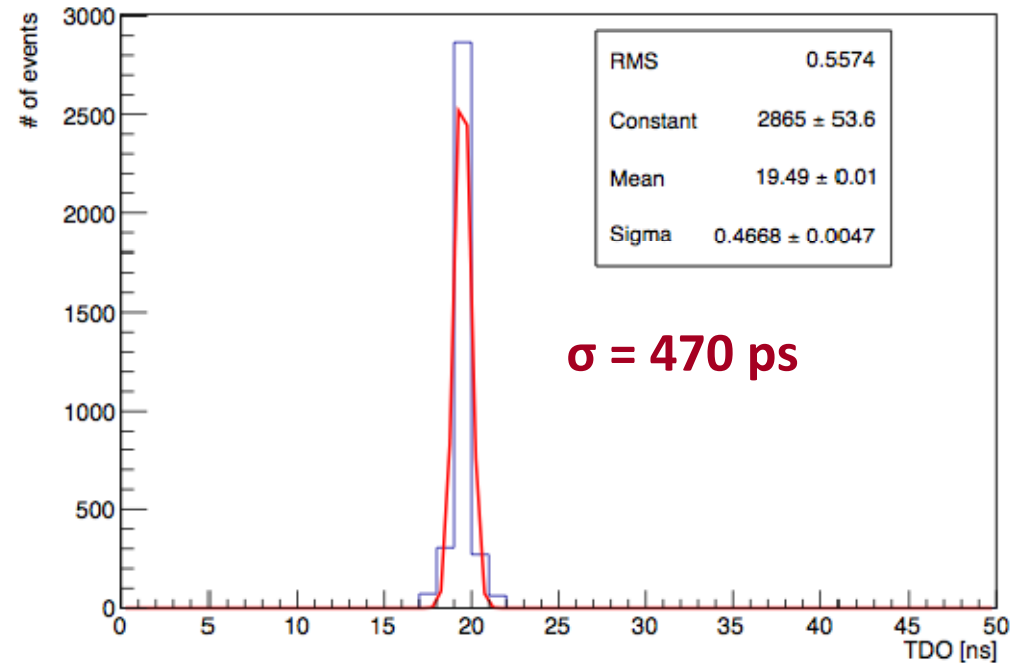
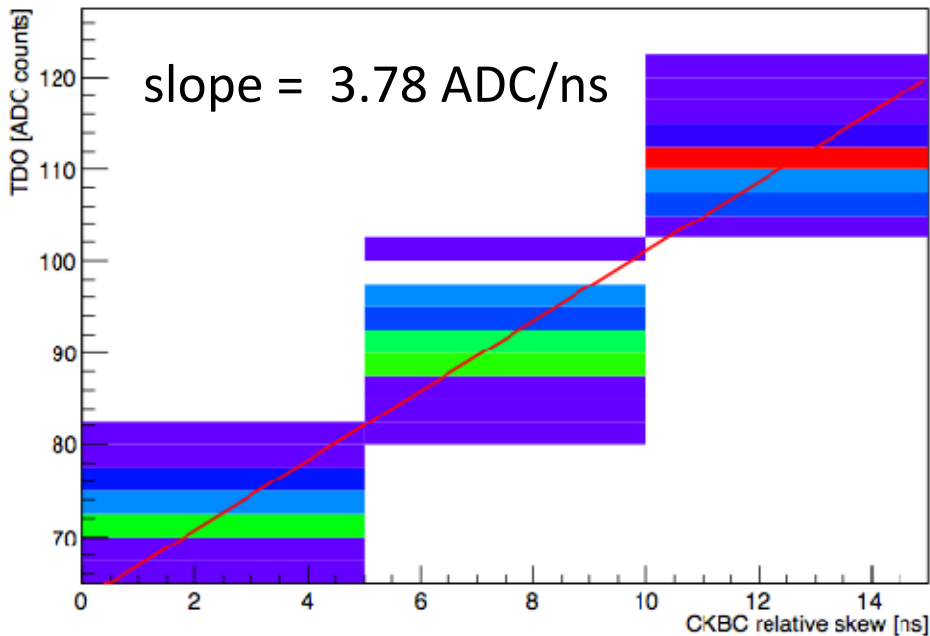
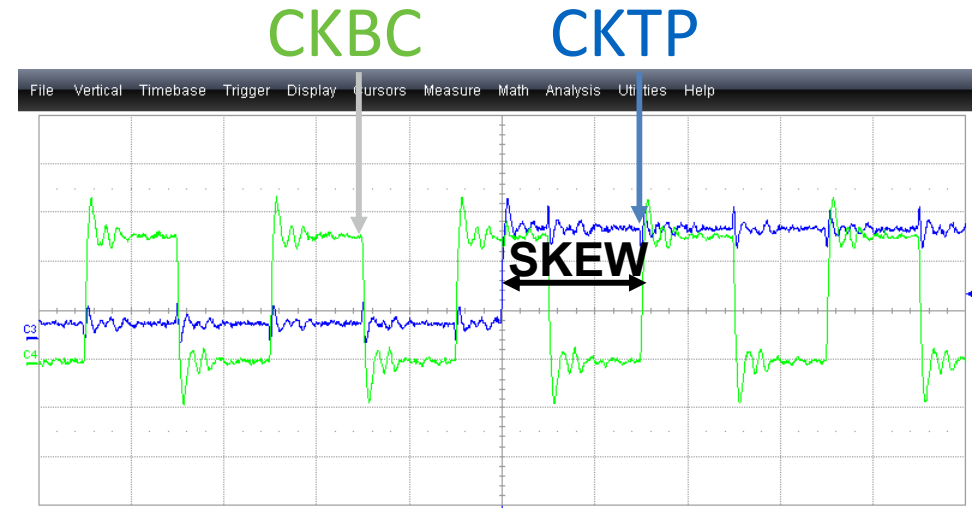
- Micromegas Test chamber with Ar+7%CO₂
- One mini1 (socket based) and packaged VMM3
- Strip voltage at 510V, Drift Voltage at 300V
- VMM3 at 50 ns integration time, 6mV/fC gain
- Random trigger at 1kHz rate
- Hit map complete, no dead channel or inefficient ones
- Simple clustering done, distribution shows a mean value of 3 strips
- Energy resolution at a good level **~27% FWHM**, good Ar escape separation and relative height



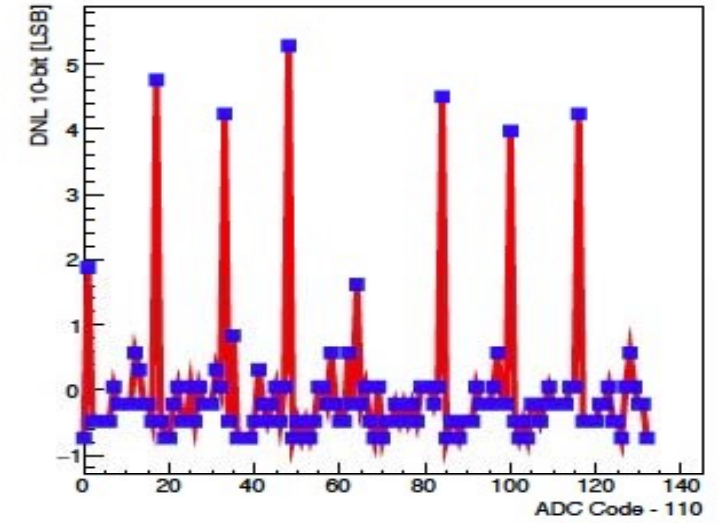
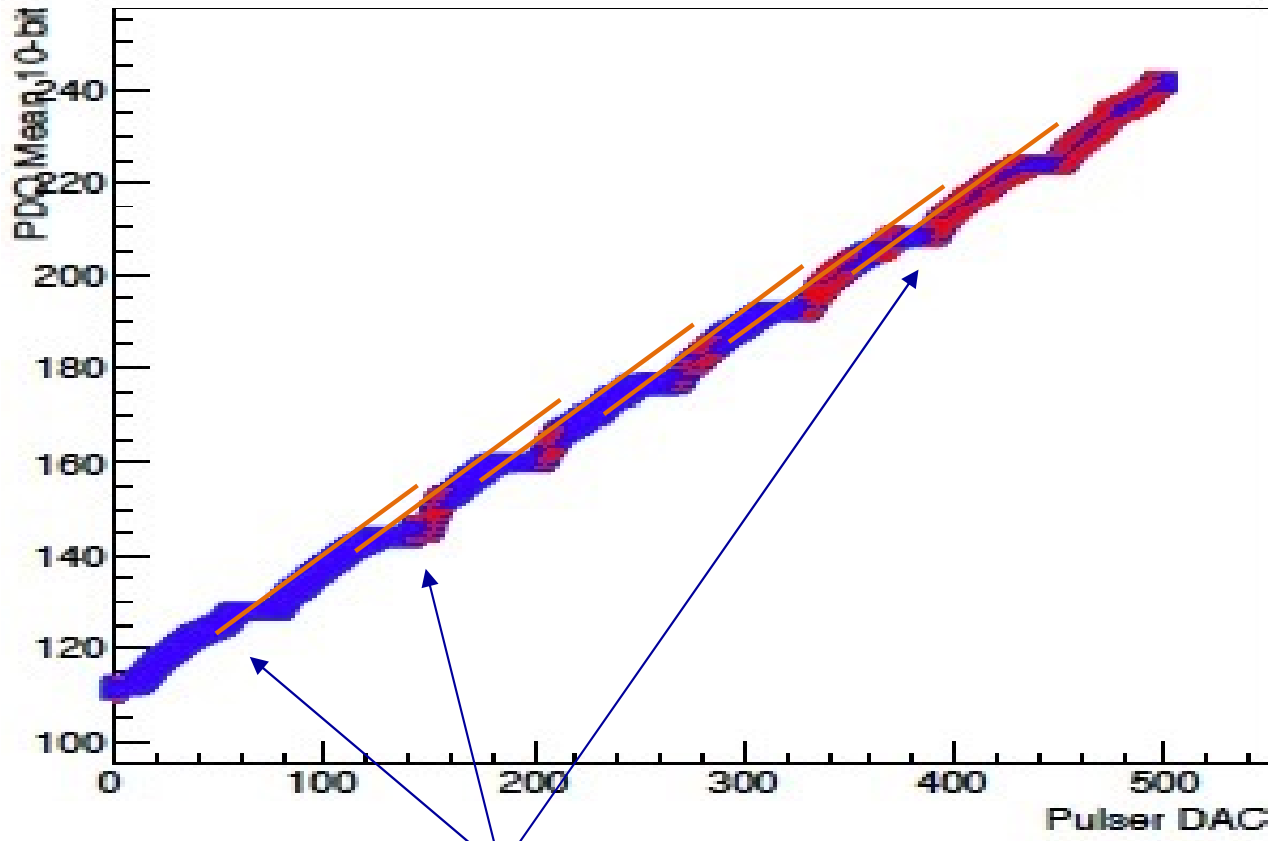
Cluster Charge (cut on size)



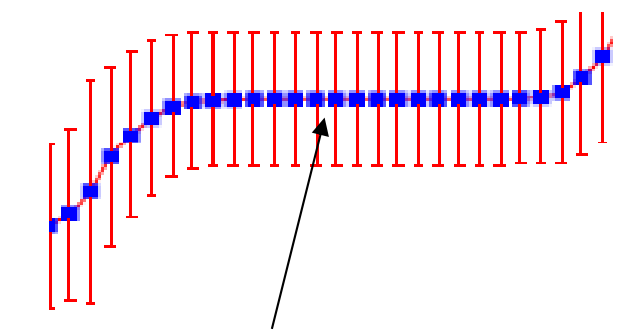
- As known each channel in VMM has a Time to Amplitude Converter which provides timing information (8-bit).
- Calibration involves the TAC calibration for precise timing measurements
- The way it is done on VMM3 is to skew the CKBC with respect to CKTP and measure the TDO.
- Steps of 5 ns used.
- Linear fit on the resulting histogram provides a calibration constant.



Detail of Residual Issue



V. Polychronakos

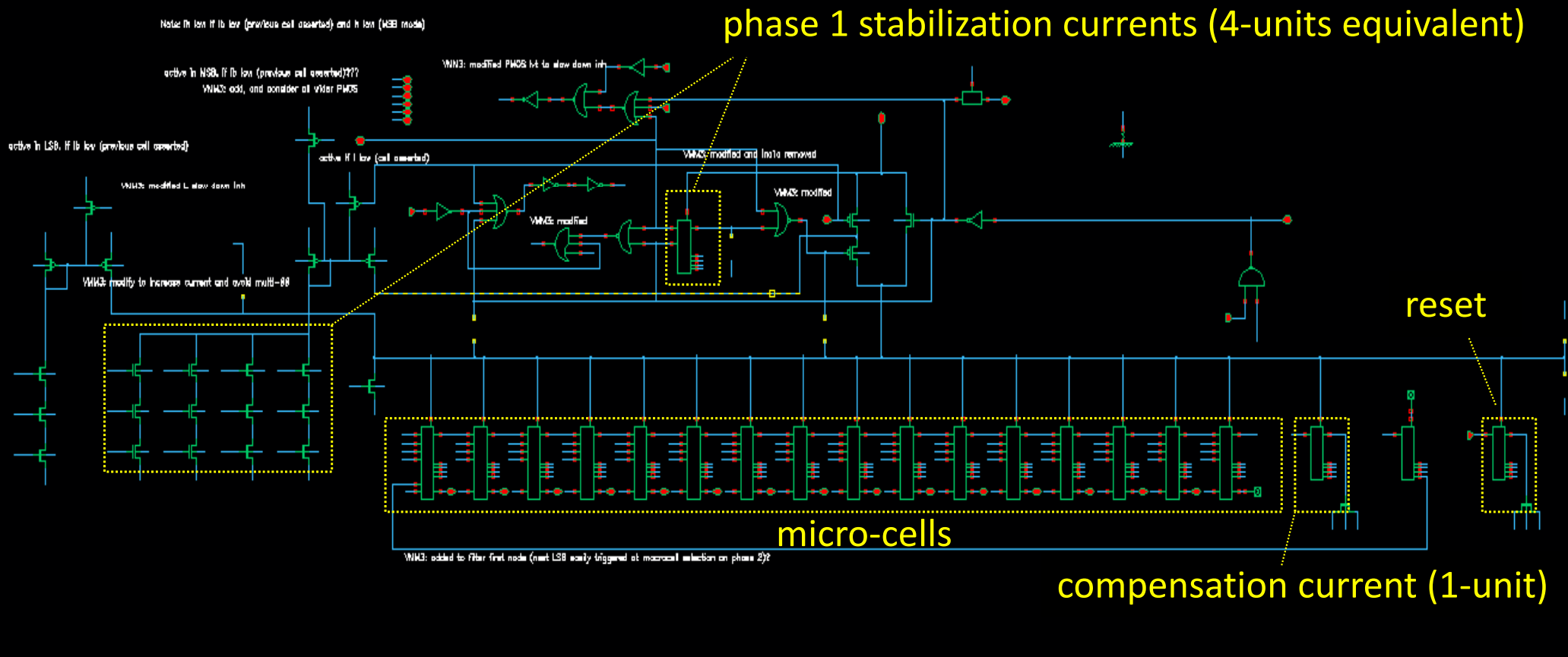


code xxxxxx0000

In phase 2: added parasitic current of ~4 micro-cells → **bin ~5 times larger** → **larger xxxxxx0000 code**

Probable Origin of Residual Issue

Macro-Cell Schematic

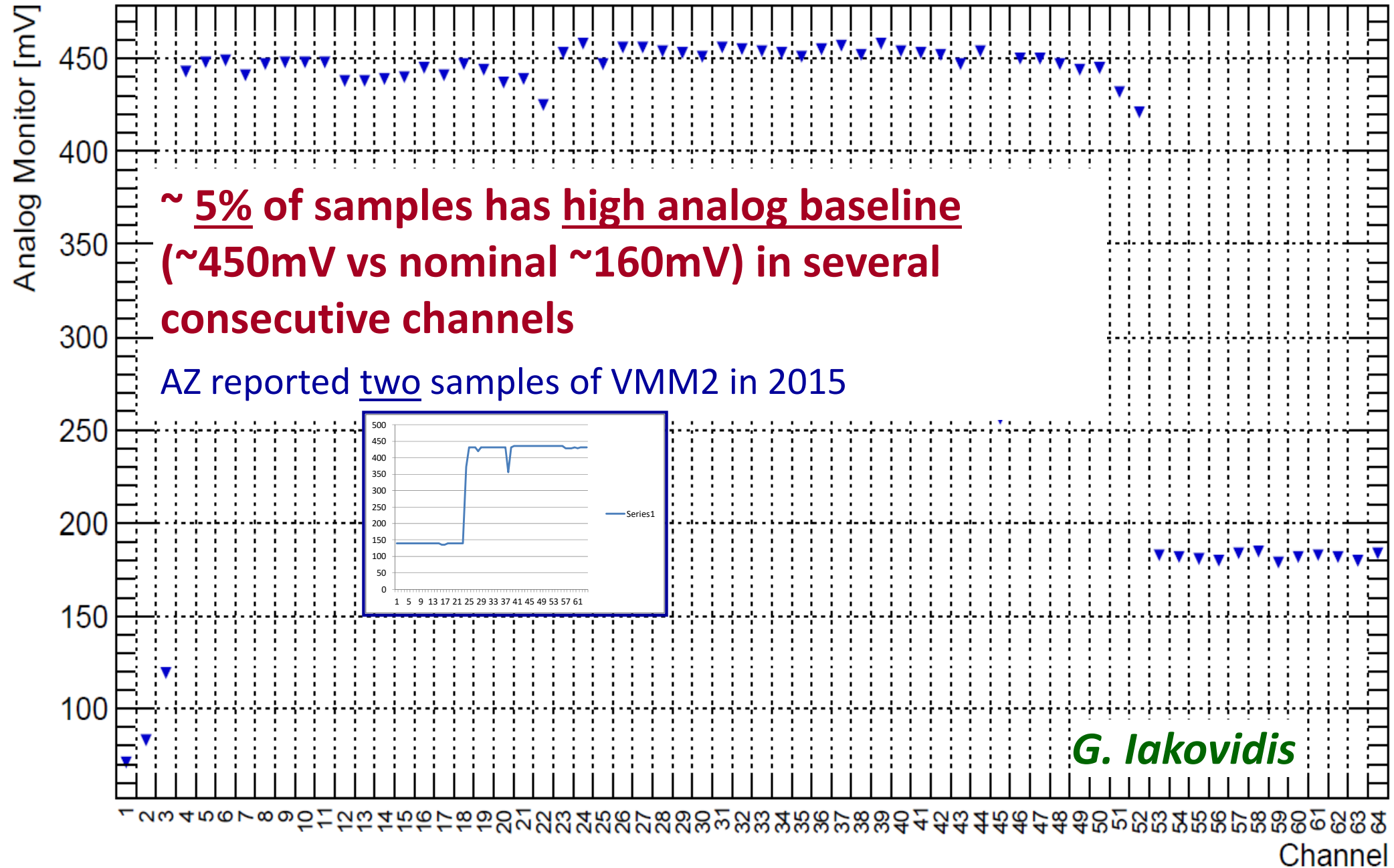


One of the phase 1 stabilization currents remains enabled during phase 2, resulting in the larger code xxxxxx0000 - to be simulated

Summary of High Baseline Issue

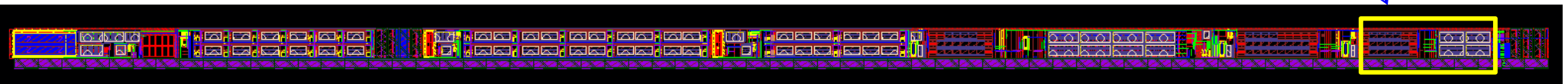
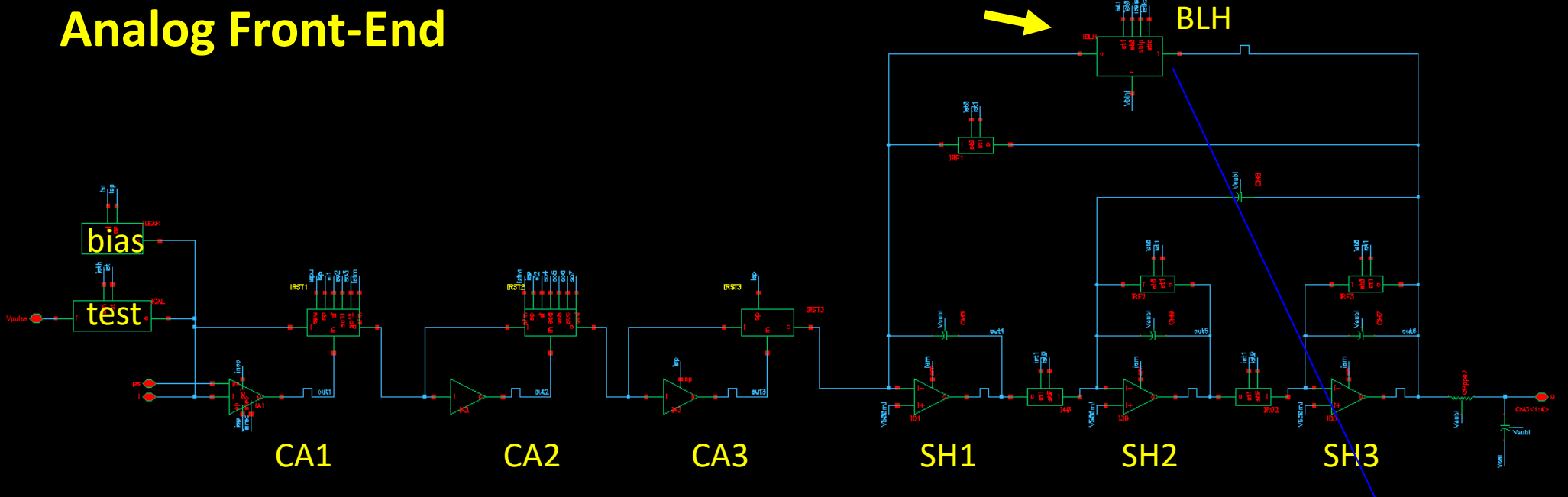
- **Issue** - About 5% of tested samples exhibit a high analog baseline ($>400\text{mV}$, compared to the nominal $\sim 160\text{mV}$) in several consecutive channels
- **Origin** - Disengagement of low-pass filter in stabilizer, simulations in progress
- **Workaround** - The baseline is correct when tail cancellation modes are enabled (STLC or SBIP)
- **Fix** - TBD, simulations queued

Measured High Baseline



Baseline Stabilizer

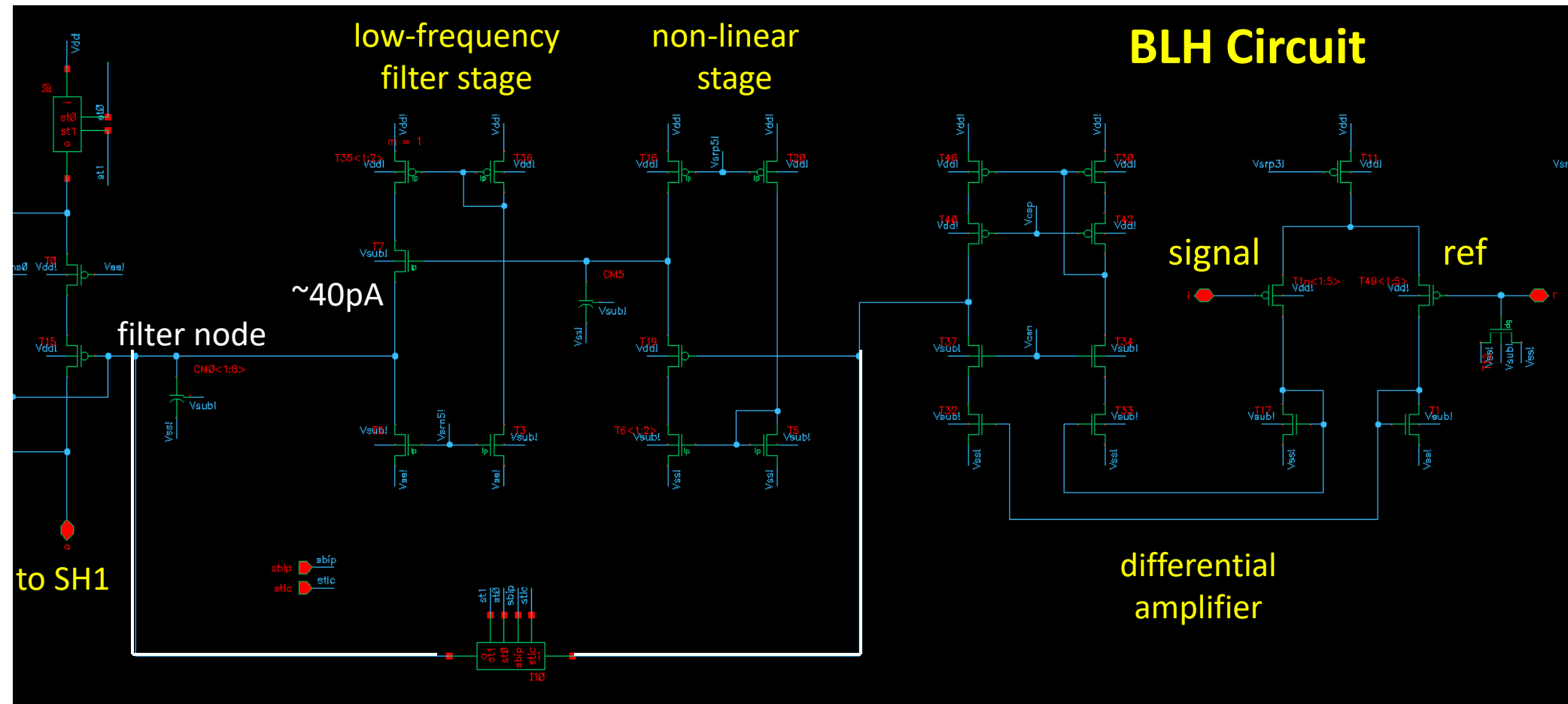
Analog Front-End



~ 4mm

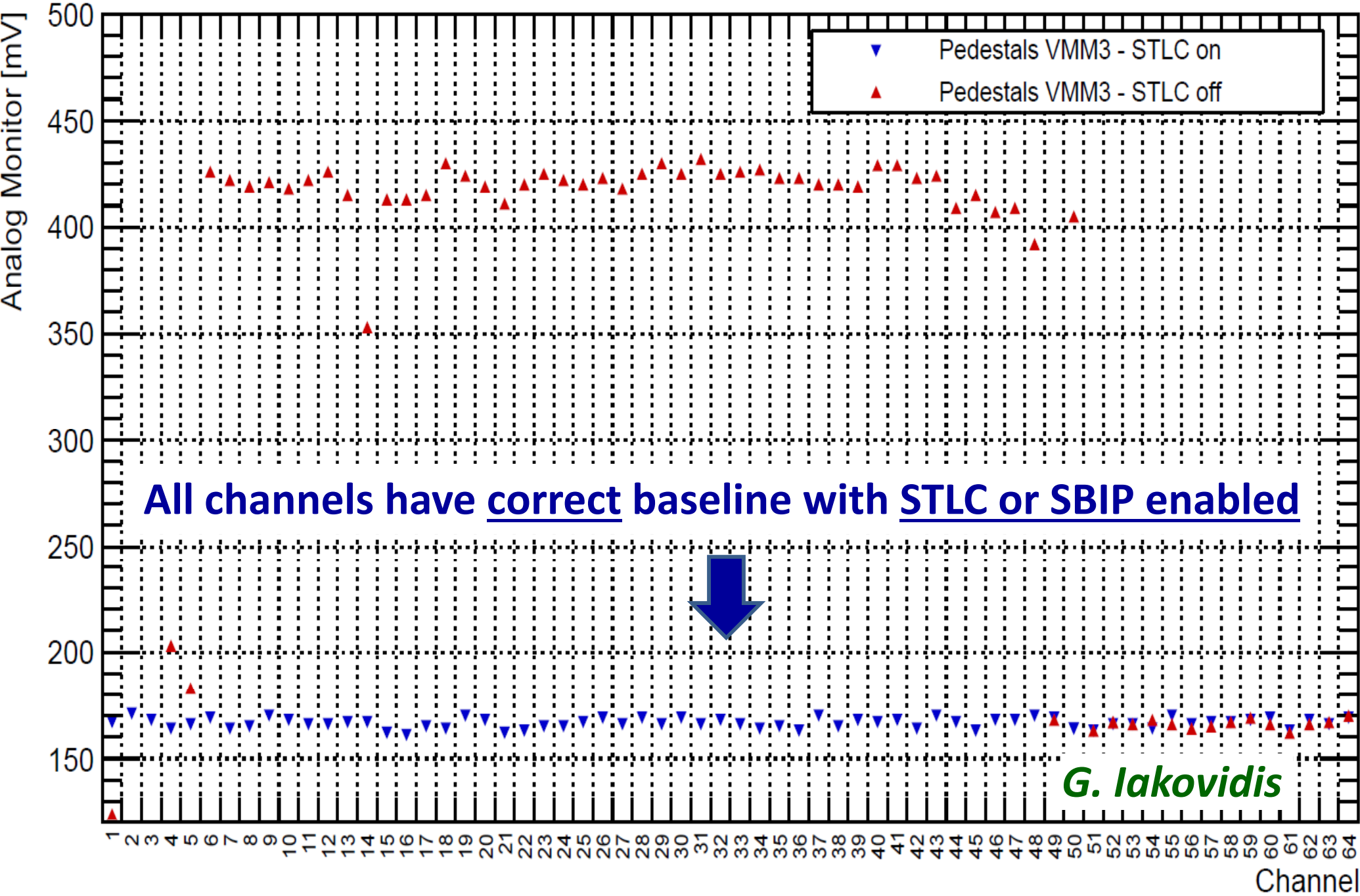
- Feedback around shaper (BLH) provides stable output baseline by using a precision 160mV reference.
- Composed of a differential amplifier, a non-linear stage, and a very-low-frequency filter which operates with very low current

Bypass for Tail Suppression



- $\sim 450\text{mV}$ baseline \rightarrow filter node shifted to 1.2V supply, no more control from BLH.
- VMM3 implements programmable bypass for mild and strong tail cancellation (bits STLC and SBIP)

Measured Baseline with STLC or SBIP



All channels have correct baseline with STLC or SBIP enabled



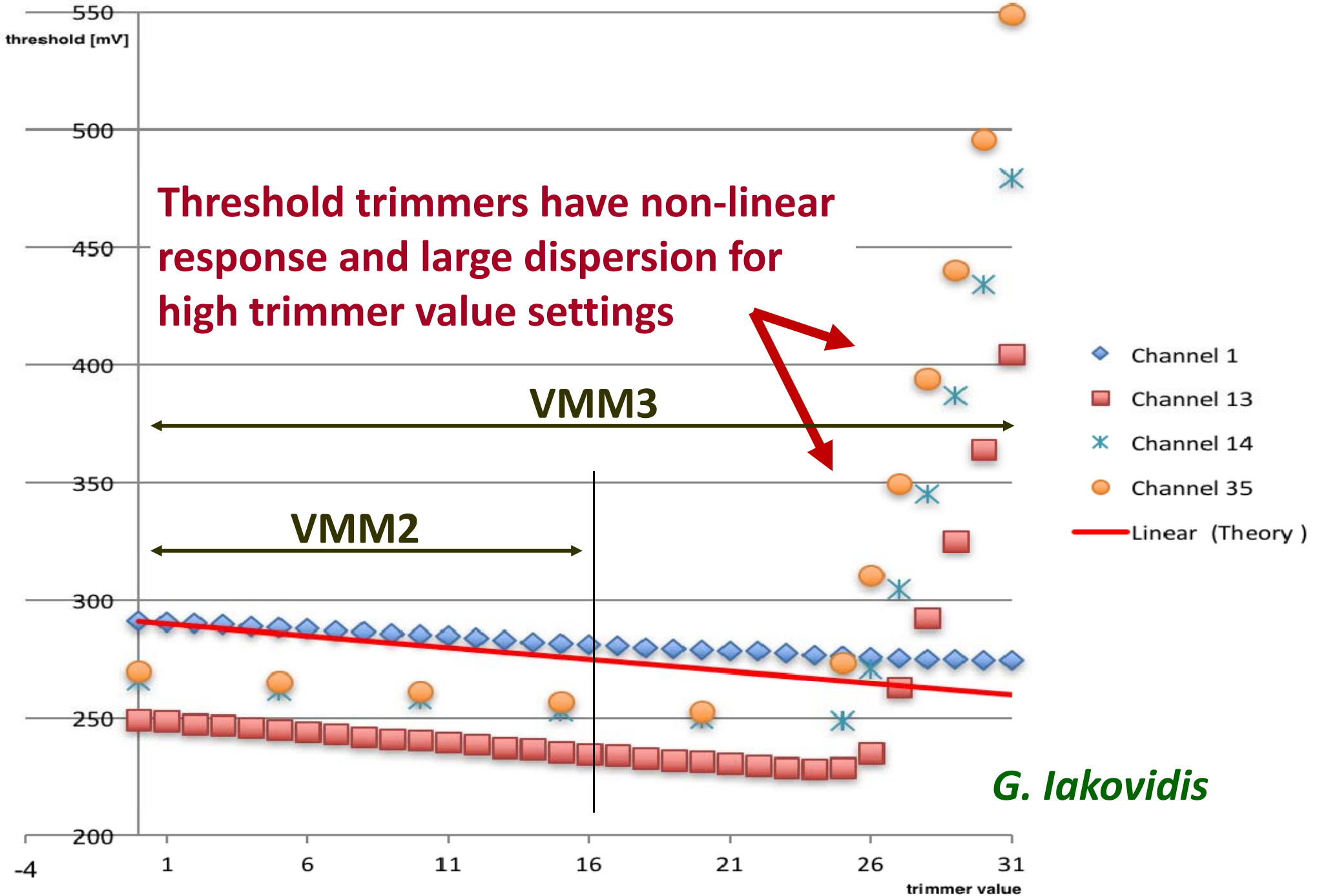
G. Iakovidis

Summary of Threshold Trimming Issue

- **Issue** - Trimming voltage exhibits saturation and return back; effective range is $\sim x1.5$ instead of planned $x2$
- **Origin** - Limited drive capability of trimming amplifier
- **Workaround** - None
- **Fix** - Increase driver size

Threshold Trimming Issue

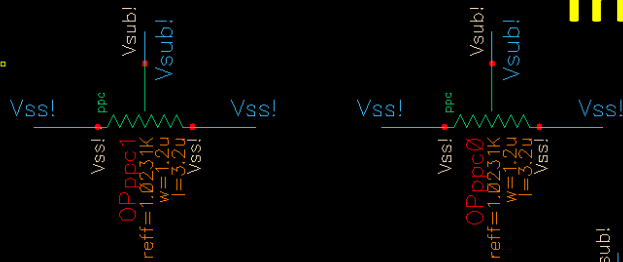
Threshold trimmers have non-linear response and large dispersion for high trimmer value settings



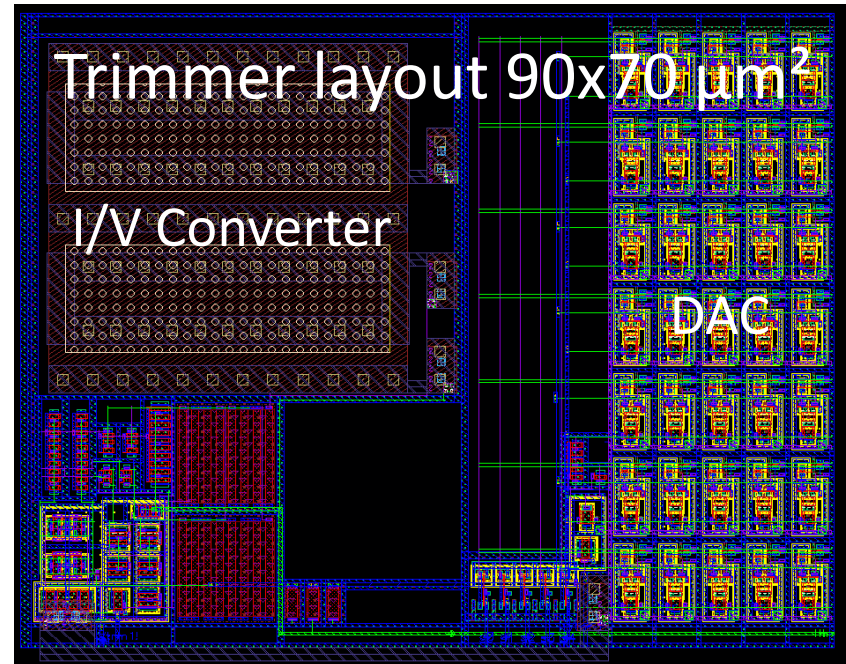
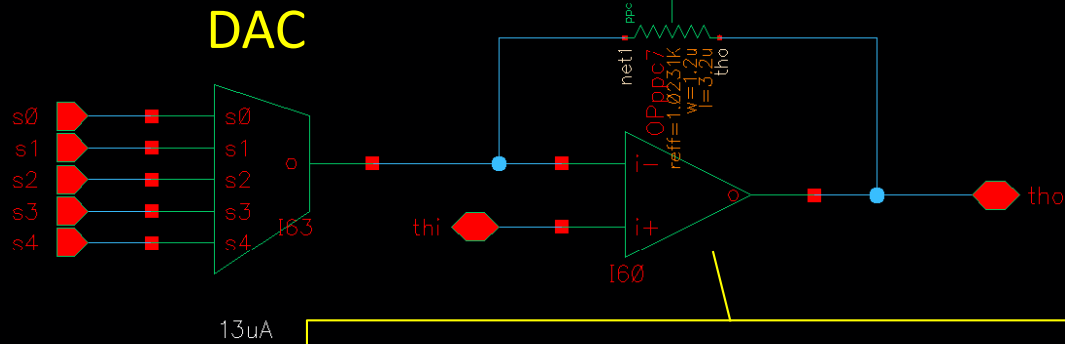
G. Iakovidis

Threshold Trimming Issue Circuit Detail

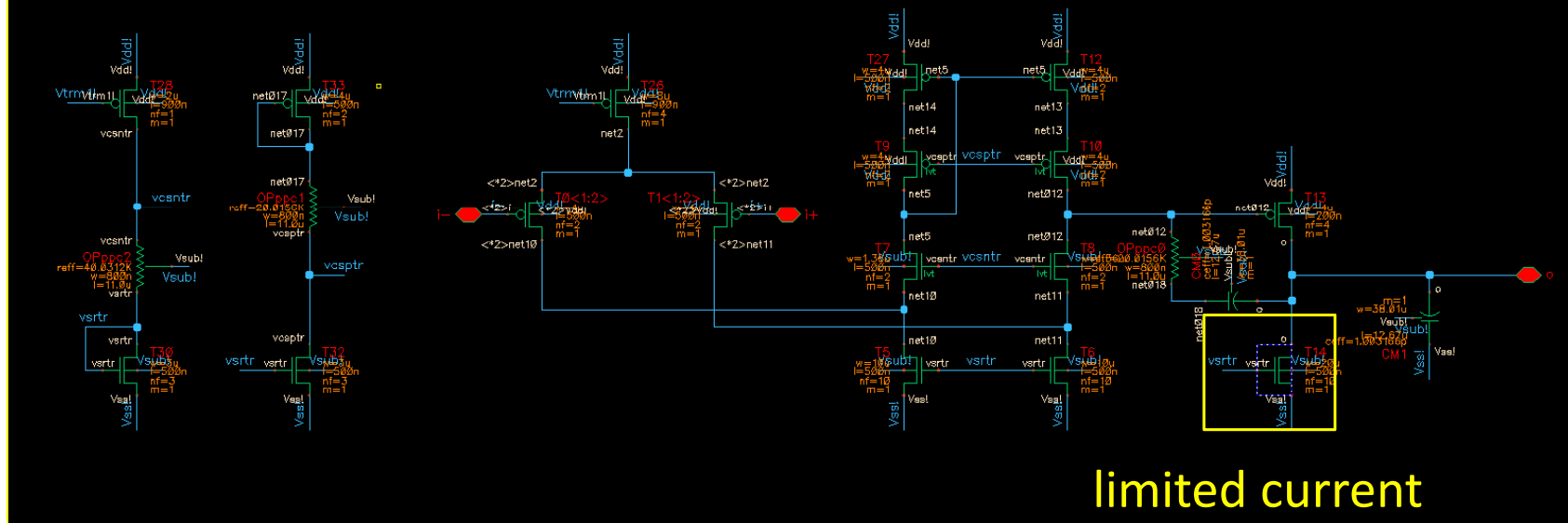
Trimmer Circuit



I/V Converter

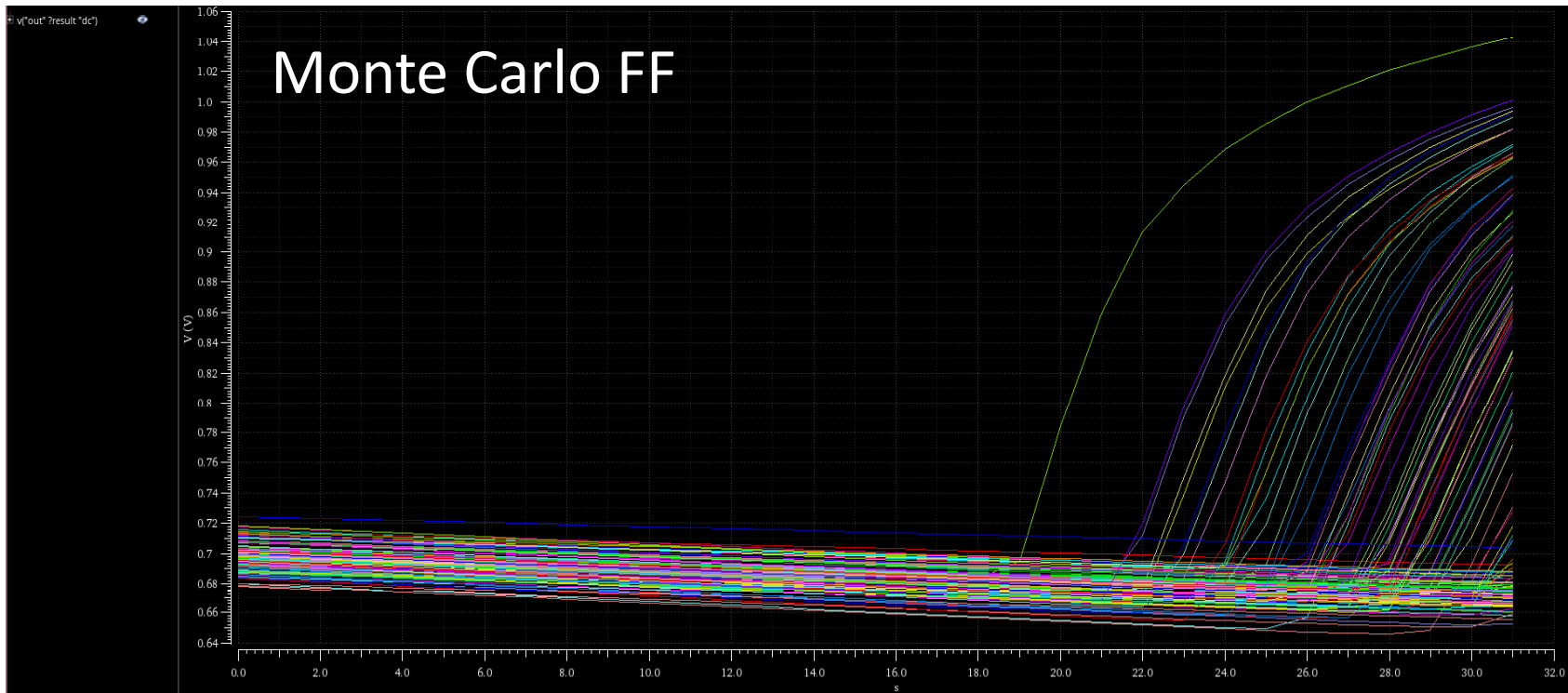
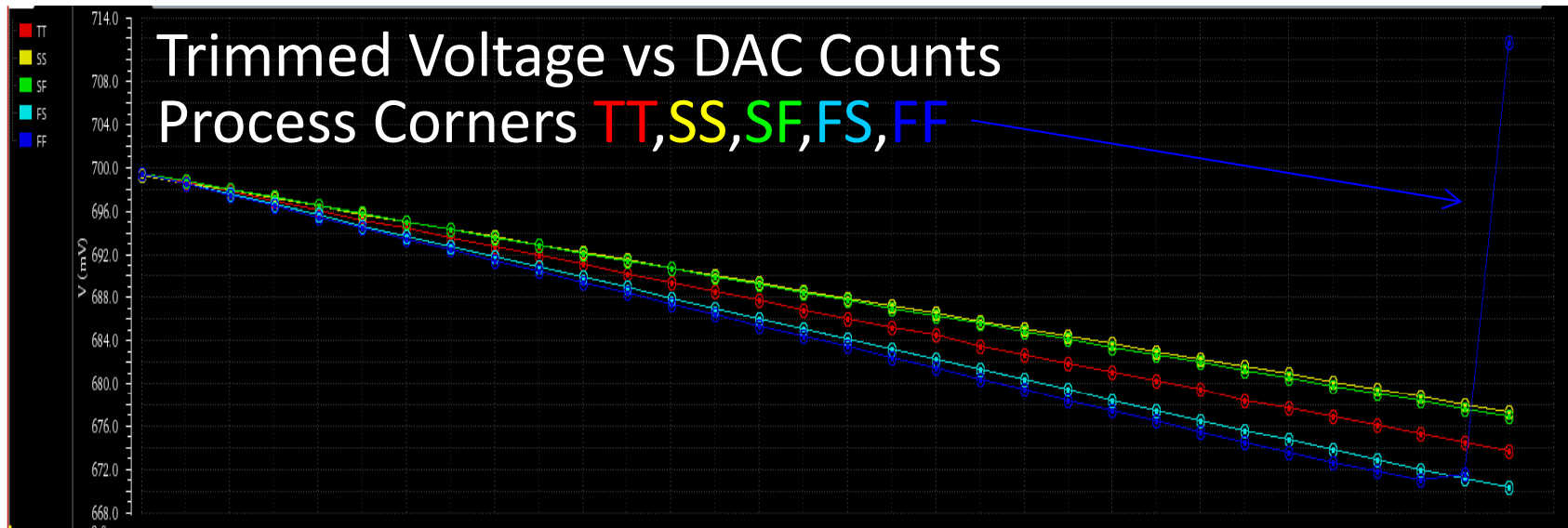


Trimmer Amplifier

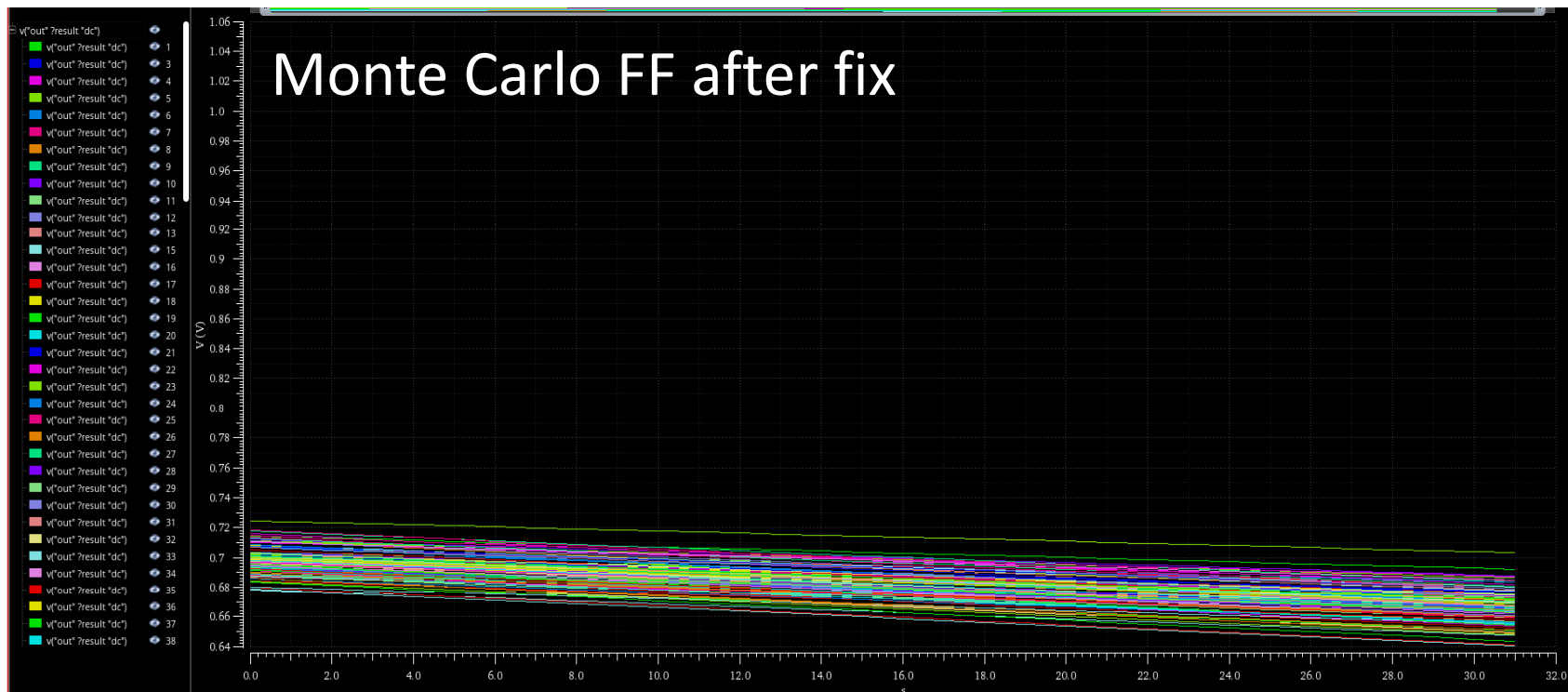
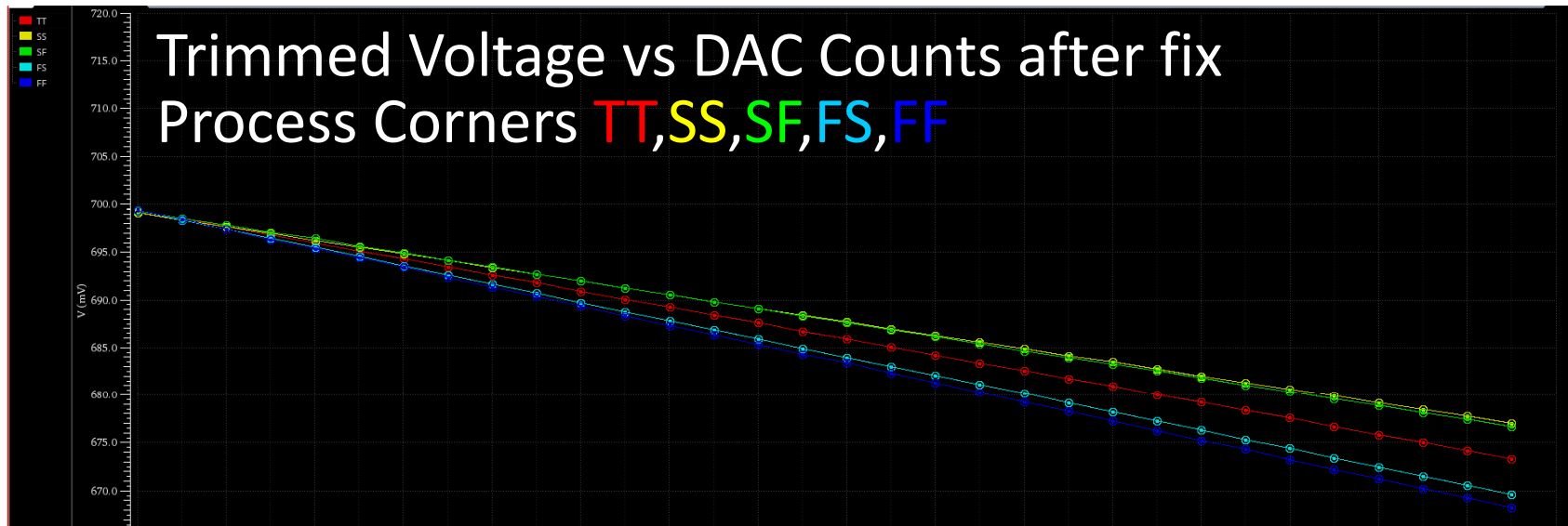


limited current

Threshold Trimming Issue Simulation



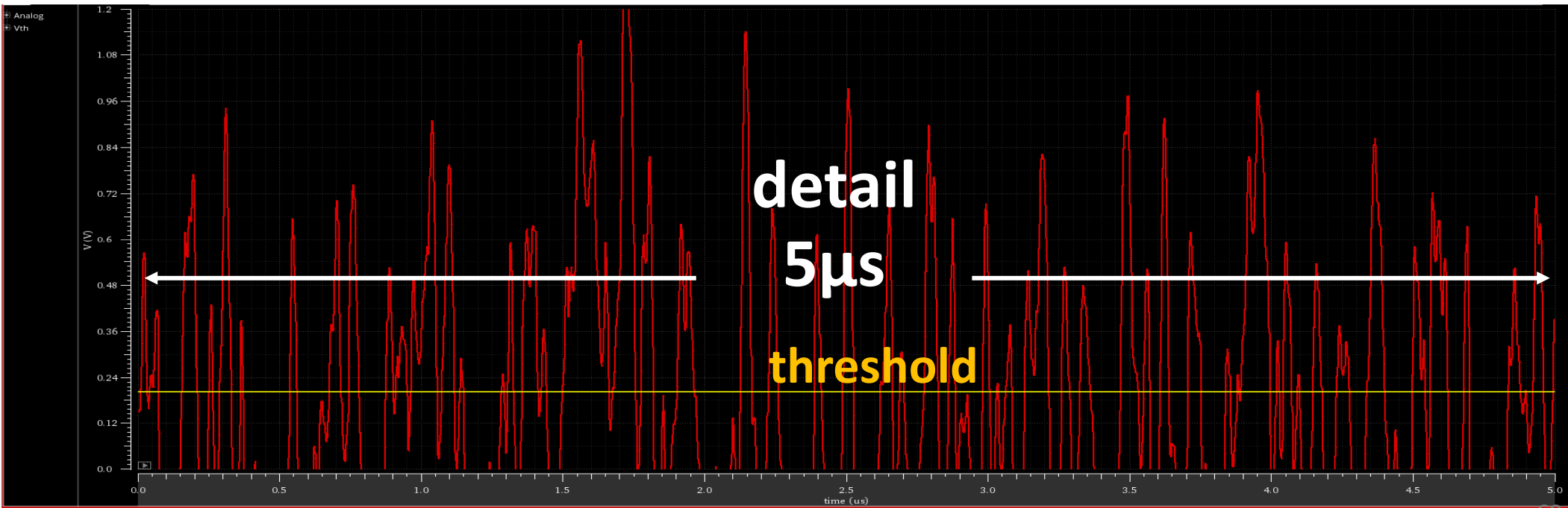
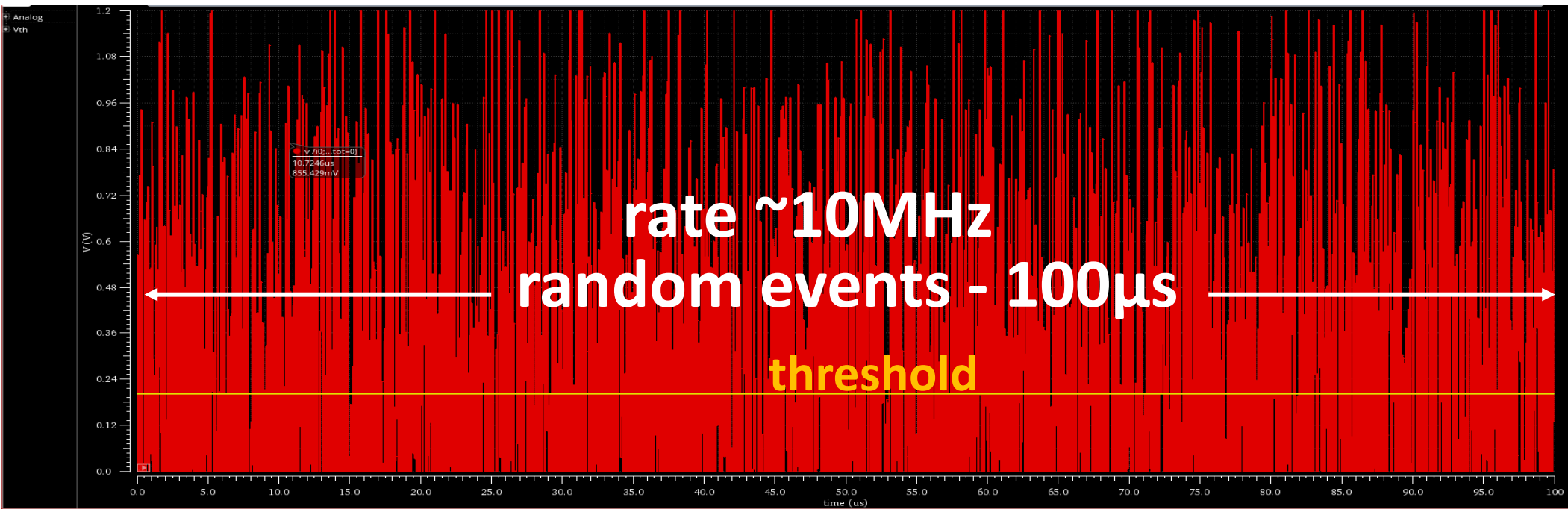
Threshold Trimming Simulation after Fix



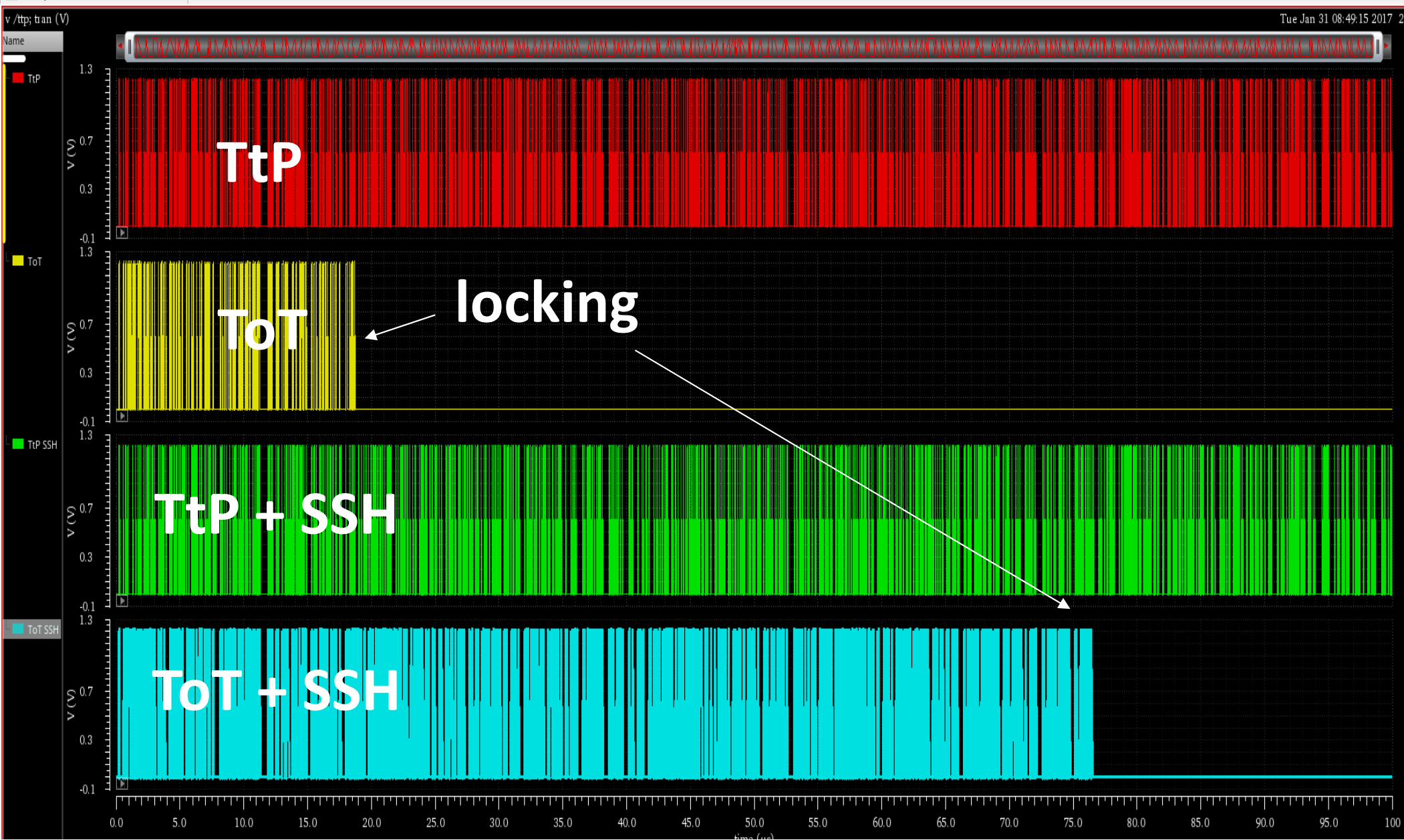
Summary of Locking Issue

- **Issue** - In time-over-threshold (ToT) the channel locks after few events; unlocking requires acquisition-reset
- **Origin** - Conflict between reset signals in discrimination logic; may also result in **occasional single event miss at high rate for some settings**
- **Workaround** - No locking occurs when operating in threshold-to-peak (TtP)
- **Fix** - Small logic fix

Simulated Random High-Rate Input

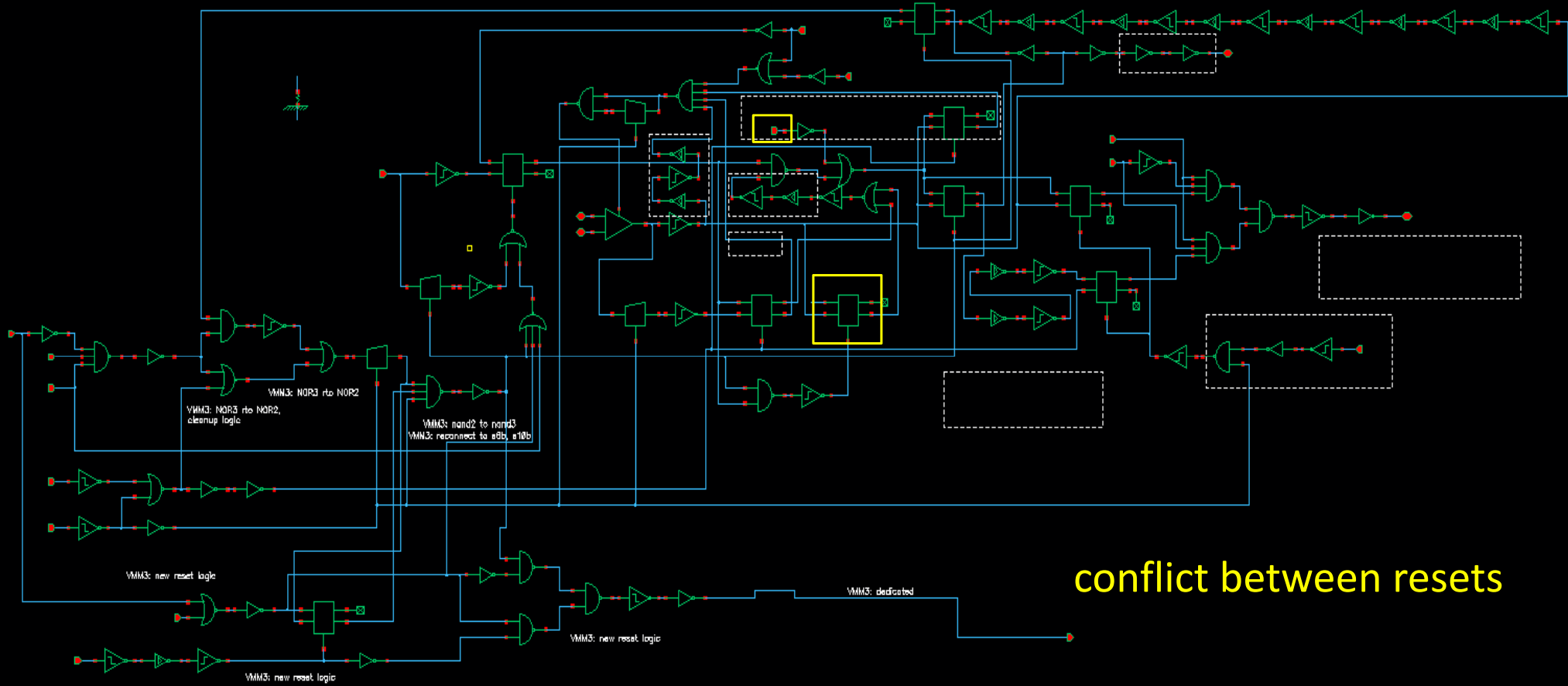


Locking Simulation at Random High Rate

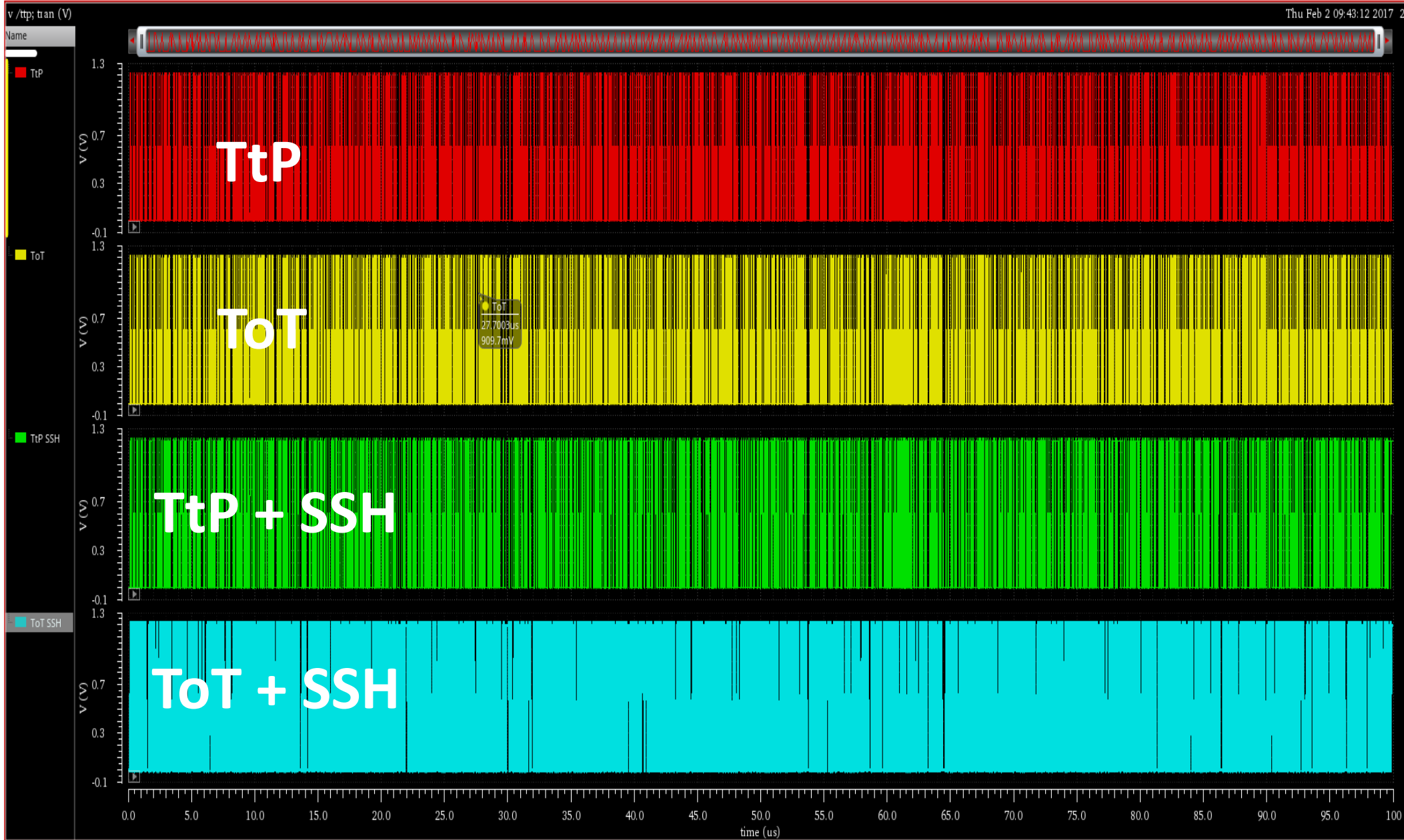


Locking Origin - Circuit Detail

Discriminator Logic



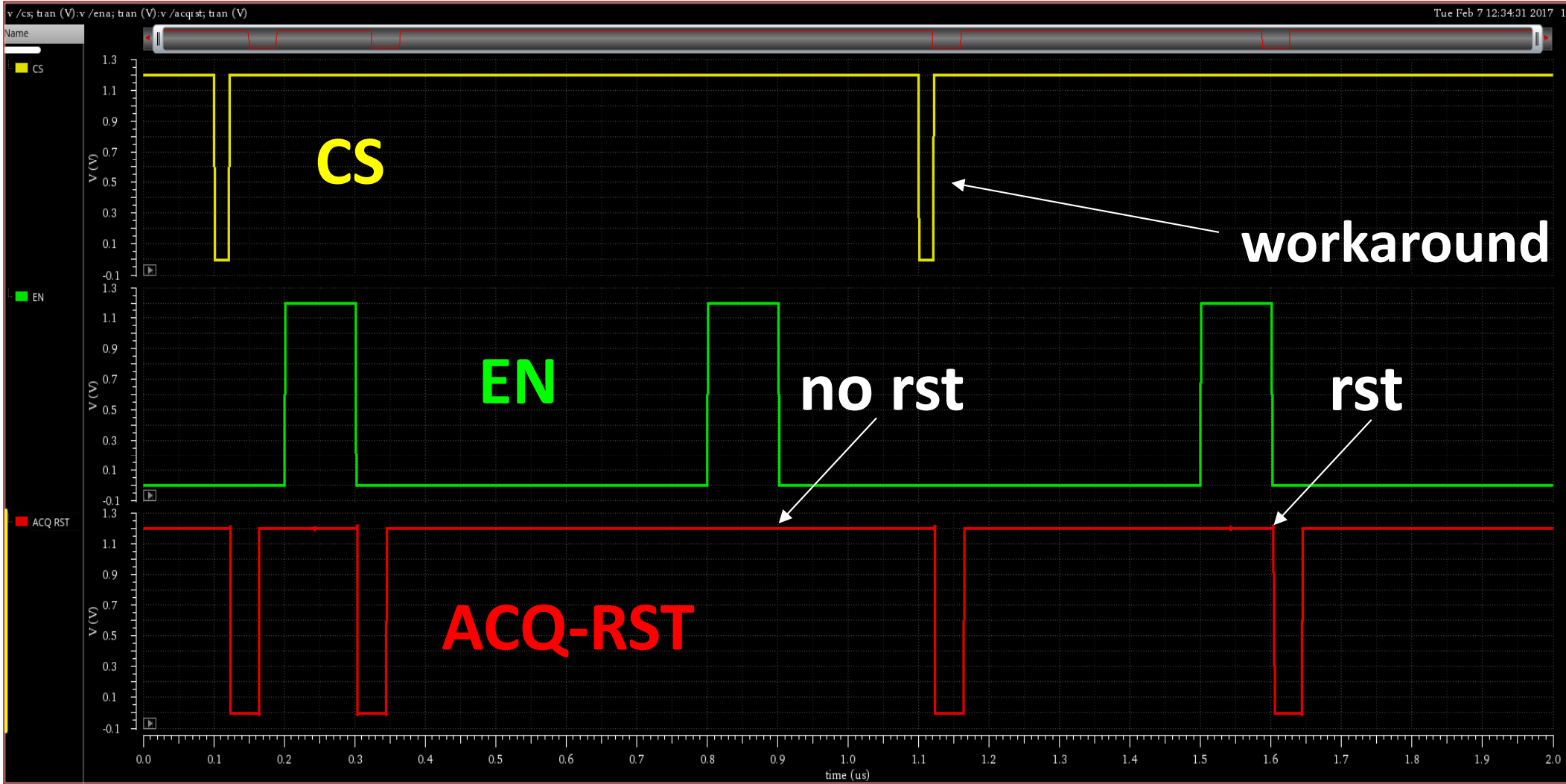
Simulation after Fix



Summary of Acquisition-Reset Issue

- **Issue** - Acquisition-reset with Enable (EN) works only for one cycle
- **Origin** - Wrong reset logic on dedicated register
- **Workaround** - Acquisition-reset with Chip-Select (CS) pulse at the end of each cycle
- **Fix** - Small logic fix

Acquisition Reset - Simulation



- Acquisition-reset with EN only with first cycle
- CS can be used as workaround

Acquisition Reset - Circuit Detail

